יראיזי, ביויוושי, אואא אווי, ולאיזי, לב鼎好!

SPRS094C - APRIL 1999 - REVISED OCTOBER 1999

- High-Performance Static CMOS Technology
 - 33-ns Instruction Cycle Time (30 MHz)
 - 30 MIPS Performance
 - Low-Power 3.3-V Design
- Based on T320C2xx DSP CPU Core
 - Code-Compatible With 'F243/'F241/'C242
 - Instruction Set and Module Compatible With 'F240/'C240
 - Source-Code-Compatible With TMS320C1x/2x
- Flash (LF) and ROM (LC) Device Options
 - 'LF240x[†]: 'LF2407, 'LF2406, 'LF2402
 - 'LC240x[†]: 'LC2406, 'LC2404, 'LC2402
- On-Chip Memory
 - Up to 32K Words x 16 Bits of Flash EEPROM (4 Sectors) or ROM
 - Up to 2.5K Words x 16 Bits of Data/Program RAM
 - 544 Words of Dual-Access (DARAM)
 - 2K Words of Single-Access (SARAM)
- Boot ROM ('LF240x Devices)
 - SCI/SPI Flash Bootloader
- Two Event-Manager (EV) Modules (A and B) EVA and EVB Each Include:
 - Two 16-Bit General-Purpose Timers
 - Eight 16-Bit Pulse-Width Modulation (PWM) Channels Which Enable:
 - Three-Phase Inverter Control
 - Centered or Edge Alignment of PWM Channels
 - Emergency PWM Channel Shutdown With External PDPINT Pin
 - Programmable Deadband Prevents Shoot-Through Faults
 - Three Capture Units For Time-Stamping of External Events
 - On-Chip Position Encoder Interface Circuitry
 - Synchronized Analog-to-Digital Conversion
 - Suitable for AC Induction, BLDC,
 Switched Reluctance, and Stepper Motor
 Control
 - Applicable for Multiple Motor and/or Converter Control

- External Memory Interface ('LF2407)
 - 192K Words x 16 Bits of Total Memory, 64K Program, 64K Data, 64K I/O
- Watchdog (WD) Timer Module
- 10-Bit Analog-to-Digital Converter (ADC)
 - 8 or 16 Multiplexed Input Channels
 - 500 ns Minimum Conversion Time
 - Selectable Twin 8-Input Sequencers
 Triggered by Two Event Managers
- Controller Area Network (CAN) 2.0B Module
- Serial Communications Interface (SCI)
- 16-Bit Serial Peripheral Interface (SPI)
 Module (Except 'x2402)
- Phase-Locked-Loop (PLL)-Based Clock Generation
- Up to 40 Individually Programmable, Multiplexed General-Purpose Input/Output (GPIO) Pins
- Five External Interrupts (Power Drive Protection, Reset, and Two Maskable Interrupts)
- Power Management:
 - Three Power-Down Modes
 - Ability to Power-Down Each Peripheral Independently
- Real-Time JTAG-Compliant Scan-Based Emulation, IEEE Standard 1149.1‡ (JTAG)
- Development Tools Include:
 - Texas Instruments (TI™) ANSI
 C Compiler, Assembler/Linker, and
 Code Composer™ Debugger
 - Evaluation Modules
 - Scan-Based Self-Emulation (XDS510™)
 - Numerous Third-Party Digital Motor Control Support
- Package Options
 - 144-Pin Thin Quad Flatpack (TQFP) PGE ('LF2407)
 - 100-Pin TQFP PZ ('LC2404, 'LC2406, 'LF2406)
 - 64-Pin PQFP PG ('LC2402 and 'LF2402)
- Extended Temperature Options (A and S)
 - A: 40°C to 85°C
 - S: -40°C to 125°C



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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† Throughout this data sheet, '240x is used as a generic name for the 'LF240x/'LC240x family of devices.

‡ IEEE Standard 1149.1–1990, IEEE Standard Test-Access Port



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description

The TMS320LF240x and TMS320LC240x devices, new members of the '24x family of digital signal processor (DSP) controllers, are part of the C2000 platform of fixed-point DSPs. The '240x devices offer the enhanced TMS320 architectural design of the 'C2xx core CPU for low-cost, low-power, high-performance processing capabilities. Several advanced peripherals, optimized for digital motor and motion control applications, have been integrated to provide a true single chip DSP controller. While code-compatible with the existing '24x DSP controller devices, the '240x offers increased processing performance (30 MIPS) and a higher level of peripheral integration. See the TMS320x240x device summary section for device-specific features.

The '240x family offers an array of memory sizes and different peripherals tailored to meet the specific price/performance points required by various applications. Flash-based devices of up to 32K words offer a reprogrammable solution useful for:

- Applications requiring field programmability upgrades
- Development and initial prototyping of applications that migrate to ROM-based devices

Flash devices and corresponding ROM devices are fully pin-to-pin compatible. Note that flash-based devices contain a 256-word boot ROM to facilitate in-circuit programming.

All '240x devices offer at least one event manager module which has been optimized for digital motor control and power conversion applications. Capabilities of this module include centered- and/or edge-aligned PWM generation, programmable deadband to prevent shoot-through faults, and synchronized analog-to-digital conversion. Devices with dual event managers enable multiple motor and/or converter control with a single '240x DSP controller.

The high performance, 10-bit analog-to-digital converter (ADC) has a minimum conversion time of 500 ns and offers up to 16 channels of analog input. The auto sequencing capability of the ADC allows a maximum of 16 conversions to take place in a single conversion session without any CPU overhead.

A serial communications interface (SCI) is integrated on all devices to provide asynchronous communication to other devices in the system. For systems requiring additional communication interfaces; the '2407, '2406, and '2404 offer a 16-bit synchronous serial peripheral interface (SPI). The '2407 and '2406 offer a controller area network (CAN) communications module that meets 2.0B specifications. To maximize device flexibility, functional pins are also configurable as general purpose inputs/outputs (GPIO).

To streamline development time, JTAG-compliant scan-based emulation has been integrated into all devices. This provides non-intrusive real-time capabilities required to debug digital control systems. A complete suite of code generation tools from C compilers to the industry-standard Code Composer debugger supports this family. Numerous third party developers not only offer device-level development tools, but also system-level design and development support.



TMS320x240x device summary

Note that throughout this data sheet, '240x is used as a generic name for the 'LF240x/'LC240x family of devices.

Table 1. Hardware Features of '240x Devices

FEATURE	'LF2407†	'LF2406	'LF2402	'LC2406	'LC2404	'LC2402	
'C2xx DSP Core	Yes	Yes	Yes	Yes	Yes	Yes	
Instruction Cycle		33 ns	33 ns				
MIPS (30 MHz)		30 MIPS	30 MIPS				
DAM (40 L):	DARAM	544	544	544	544	544	544
RAM (16-bit word)	SARAM	2K	2K	_	2K	1K	_
On-chip Flash (16-bit word) (4 sectors: 4K, 12K, 12K, 4K)	_	32K	32K	8K	_	_	_
On-chip ROM (16-bit word)		_	_	_	32K	16K	4K
Boot ROM (16-bit word)		256	256	256	_	_	_
External Memory Interface		Yes	_	_	_	_	_
Event Managers A and B (EVA and EVB)	EVA, EVB	EVA, EVB	EVA	EVA, EVB	EVA, EVB	EVA	
General-Purpose (GP) Ti	4	4	2	4	4	2	
Compare (CMP)/PWM		10/16	10/16	5/8	10/16	10/16	5/8
Capture (CAP)/QEP		6/4	6/4	3/2	6/4	6/4	3/2
Watchdog Timer		Yes	Yes	Yes	Yes	Yes	Yes
10-Bit ADC		Yes	Yes	Yes	Yes	Yes	Yes
Channels		16	16	8	16	16	8
Conversion Time (minimum	um)	500 ns	500 ns				
SPI		Yes	Yes	_	Yes	Yes	_
SCI		Yes	Yes	Yes	Yes	Yes	Yes
CAN		Yes	Yes	_	Yes	_	_
Digital I/O Pins (Shared)		41	41	21	41	41	21
External Interrupts		5	5	3	5	5	3
Supply Voltage		3.3 V	3.3 V				
Packaging		144 TQFP	100 TQFP	64 PQFP	100 TQFP	100 TQFP	64 PQFP

^{&#}x27;LF2407, the full-featured device of the 'LF240x family of DSP controllers, is useful for emulation and code development.



functional block diagram of the '2407 DSP controller

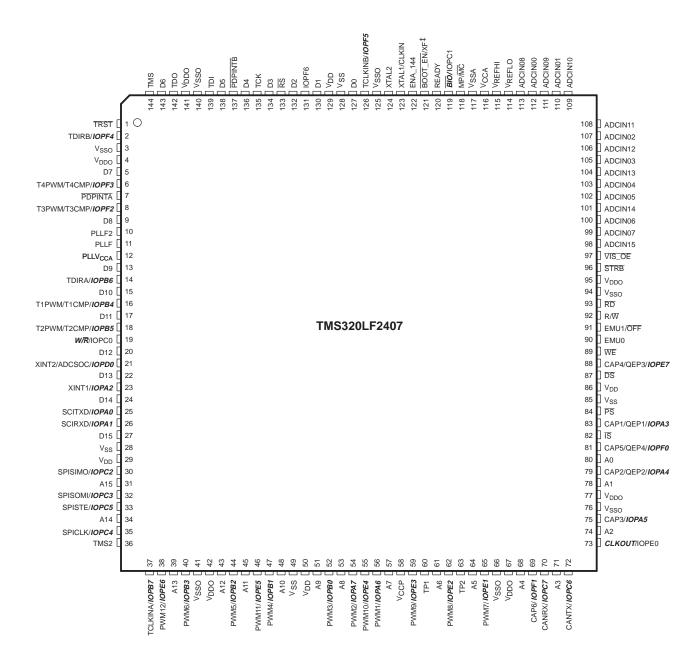
XINT1/IOPA2				PLLF
74114117101742				PLLVCCA
XINT2/ADCSOC/IOPD0	1	DARAM (B0)	PLL Clock	PLLF2
RS	1	256 Words	1 LE GIOGR	XTAL1/CLKIN
CLKOUT/IOPE0	1			XTAL2
TMS2	1			ADCIN00-ADCIN07
BIO/IOPC1	'C2xx	DARAM (B1)		ADCIN08-ADCIN15
MP/MC	DSP	256 Words		VCCA
BOOT_EN/XF	Core		10-Bit ADC (With Twin	VSSA
	1		Autosequencer)	VREFHI
		DARAM (B2)	/ tatedequericer)	VREFLO
		32 Words		XINT2/ADCSOC/IOPD0
				SCITXD/IOPA0
	4444		SCI	SCIRXD/IOPA1
V _{DD} (3.3 V)	CADA	M (OK)M-=-I-)		SPISIMO/IOPC2
VSS	SARA	M (2K Words)		SPISOMI/IOPC3
			SPI	SPICLK/IOPC4
				SPISTE/IOPC5
TP1				CANTX/IOPC6
TP2		lash/ROM	CAN	CANRX/IOPC7
V _{CCP} (5V)		2K Words: 12K/12K/4K)		V _{CCP} (5V)
	410	1210 1210 410)	WD	*CCP(0*)
				Port A(0-7) IOPA[0:7]
A0-A15				Port B(0-7) IOPB[0:7]
D0-D15			Digital I/O	Port C(0-7) IOPC[0:7]
PS, DS, IS			(Shared With Other Pins)	Port D(0) IOPD[0]
R/W				Port E(0-7) IOPE[0:7]
RD				Port F(0-6) IOPF[0:6]
READY				TRST
STRB	External	Memory Interface		TDO
WE				TDI
ENA_144			JTAG Port	TMS
				TCK
VIS_OE				EMU0
W/R / IOPC0				EMU1
PDPINTA				PDPINTB
CAP1/QEP1/IOPA3				CAP4/QEP3/IOPE7
CAP2/QEP2/IOPA4				CAP5/QEP4/IOPF0
CAP3/IOPA5				CAP6/IOPF1
PWM1/IOPA6		ot Managar A	Event Manager D	PWM7/IOPE1
PWM2/IOPA7	Ever	nt Manager A	Event Manager B	PWM8/IOPE2
PWM3/IOPB0	• 3×Ca	pture Input	3 × Capture Input	PWM9/IOPE3
PWM4/IOPB1		mpare/PWM	6 × Compare/PWM	PWM10/IOPE4
PWM5/IOPB2	Outpu		Output (DIAMA	PWM11/IOPE5
PWM6/IOPB3	● 2×GF	P Timers/PWM	• 2 × GP Timers/PWM	PWM12/IOPE6
T1PWM/T1CMP/IOPB4				T3PWM/T3CMP/IOPF2
T2PWM/T2CMP/IOPB5				T4PWM/T4CMP/IOPF3
TDIRA/IOPB6				TDIRB/IOPF4
I DIRA/IOPB6				

Indicates optional modules

The memory size and peripheral selection of these modules change for different '240x devices. See Table 1 for device-specific details.

ADVANCE INFORMATION

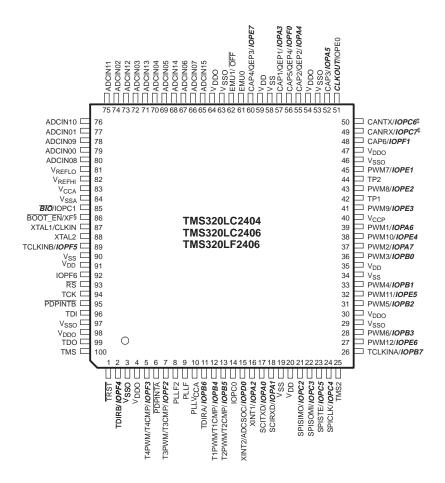
PGE PACKAGET (TOP VIEW)



[†] Bold, italicized pin names indicate pin function after reset.

[‡]BOOT_EN is available only on flash devices.

PZ PACKAGE† (TOP VIEW)

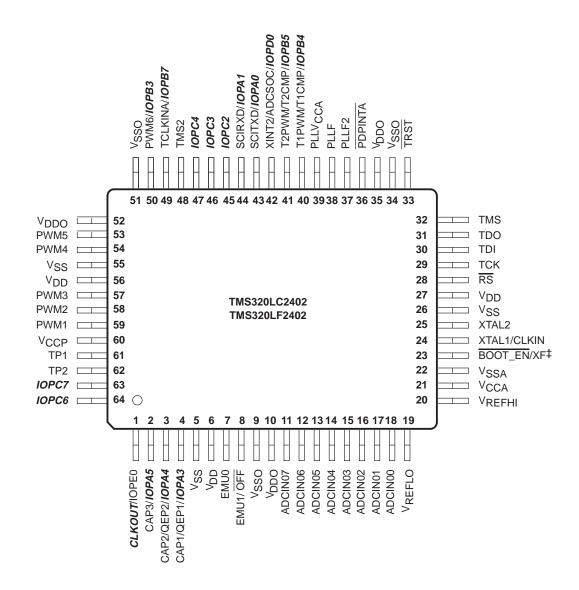


[†] Bold, italicized pin names indicate pin function after reset.

[‡] CANTX and CANRX are not available on 'LC2404 devices.

[§] BOOT_EN is available only on flash devices.

PG PACKAGE[†] (TOP VIEW)



[†] Bold, italicized pin names indicate pin function after reset.

[‡]BOOT_EN is available only on flash devices.

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pin functions

The TMS320LF2407 device is the superset of all the '240x devices. All signals are available on the '2407 device. Table 2 lists the key signals available in the '240x family of devices.

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡

PIN NAME	'LF2407	'2406	'LC2404	'2402	DESCRIPTION
			EVEN.	T MANAGE	ER A (EVA)
CAP1/QEP1/ <i>IOPA3</i>	83	57	57	4	Capture input #1/quadrature encoder pulse input #1 (EVA) or GPIO (↑)
CAP2/QEP2/ <i>IOPA4</i>	79	55	55	3	Capture input #2/quadrature encoder pulse input #2 (EVA) or GPIO (↑)
CAP3/ <i>IOPA5</i>	75	52	52	2	Capture input #3 (EVA) or GPIO (1)
PWM1/ <i>IOPA6</i>	56	39	39	59§	Compare/PWM output pin #1 (EVA) or GPIO (↑)
PWM2/ IOPA7	54	37	37	58§	Compare/PWM output pin #2 (EVA) or GPIO (↑)
PWM3/ <i>IOPB0</i>	52	36	36	57§	Compare/PWM output pin #3 (EVA) or GPIO (↑)
PWM4/ <i>IOPB1</i>	47	33	33	54§	Compare/PWM output pin #4 (EVA) or GPIO (↑)
PWM5/IOPB2	44	31	31	53§	Compare/PWM output pin #5 (EVA) or GPIO (↑)
PWM6/IOPB3	40	28	28	50	Compare/PWM output pin #6 (EVA) or GPIO (↑)
T1PWM/T1CMP/ <i>IOPB4</i>	16	12	12	40	Timer 1 compare output (EVA) or GPIO (1)
T2PWM/T2CMP/ <i>IOPB5</i>	18	13	13	41	Timer 2 compare output (EVA) or GPIO (↑)
TDIRA/ <i>IOPB6</i>	14	11	11		Counting direction for general-purpose (GP) timer (EVA) or GPIO. If TDIRA=1, upward counting is selected. If TDIRA=0, downward counting is selected. (↑)
TCLKINA/ <i>IOPB7</i>	37	26	26	49	External clock input for GP timer (EVA) or GPIO. Note that timer can also use the internal device clock. (\uparrow)
	-		EVEN.	T MANAGE	R B (EVB)
CAP4/QEP3/ <i>IOPE7</i>	88	60	60		Capture input #4/quadrature encoder pulse input #3 (EVB) or GPIO (↑)
CAP5/QEP4/ <i>IOPF0</i>	81	56	56		Capture input #5/quadrature encoder pulse input #4 (EVB) or GPIO (↑)
CAP6/IOPF1	69	48	48		Capture input #6 (EVB) or GPIO (↑)
PWM7/ IOPE1	65	45	45		Compare/PWM output pin #7 (EVB) or GPIO (↑)
PWM8/ <i>IOPE2</i>	62	43	43		Compare/PWM output pin #8 (EVB) or GPIO (1)
PWM9/IOPE3	59	41	41		Compare/PWM output pin #9 (EVB) or GPIO (↑)
PWM10/ IOPE4	55	38	38		Compare/PWM output pin #10 (EVB) or GPIO (↑)
PWM11/ <i>IOPE5</i>	46	32	32		Compare/PWM output pin #11 (EVB) or GPIO (1)
PWM12/ IOPE6	38	27	27		Compare/PWM output pin #12 (EVB) or GPIO (↑)
T3PWM/T3CMP/ <i>IOPF2</i>	8	7	7		Timer 3 compare output (EVB) or GPIO (↑)
T4PWM/T4CMP/ <i>IOPF3</i>	6	5	5		Timer 4 compare output (EVB) or GPIO (↑)
TDIRB/ <i>IOPF4</i>	2	2	2		Counting direction for general-purpose (GP) timer (EVB) or GPIO. If TDIRB=1, upward counting is selected. If TDIRB=0, downward counting is selected. (↑)
TCLKINB/ <i>IOPF5</i>	126	89	89		External clock input for GP timer (EVB) or GPIO. Note that timer can also use the internal device clock. (\uparrow)

[†] Bold, italicized pin names indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

[§] Pin changes with respect to SPRS094B data sheet.

pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME		'LF2407	'2406	'LC2404	'2402	DESCRIPTION		
		AN	ALOG-TO-	DIGITAL CO	ONVERTER	R (ADC)		
ADCIN00		112	79	79	18	Analog input #0 to the ADC		
ADCIN01		110	77	77	17	Analog input #1 to the ADC		
ADCIN02		107	74	74	16	Analog input #2 to the ADC		
ADCIN03		105	72	72	15	Analog input #3 to the ADC		
ADCIN04		103	70	70	14	Analog input #4 to the ADC		
ADCIN05		102	69	69	13	Analog input #5 to the ADC		
ADCIN06		100	67	67	12	Analog input #6 to the ADC		
ADCIN07		99	66	66	11	Analog input #7 to the ADC		
ADCIN08		113	80	80		Analog input #8 to the ADC		
ADCIN09		111	78	78		Analog input #9 to the ADC		
ADCIN10		109	76	76		Analog input #10 to the ADC		
ADCIN11		108	75	75		Analog input #11 to the ADC		
ADCIN12		106	73	73		Analog input #12 to the ADC		
ADCIN13		104	71	71		Analog input #13 to the ADC		
ADCIN14		101	68	68		Analog input #14 to the ADC		
ADCIN15		98	65	65		Analog input #15 to the ADC		
VREFHI		115	82	82	20	ADC analog high-voltage reference input		
VREFLO		114	81	81	19	ADC analog low-voltage reference input		
VCCA		116	83	83	21	Analog supply voltage for ADC (3.3 V). V _{CCA} must be isolated from digital supply voltage.		
VSSA		117	84	84	22	Analog ground reference for ADC		
CONTROLLER AREA	NETWORK (CAN), SER	AL COMM	UNICATION	S INTERFA	CE (SCI), SERIAL PERIPHERAL INTERFACE (SPI)		
CANDY/IODCZ	CANRX	70	49	-	_	CAN receive data or CRIO (A)		
CANRX/ <i>IOPC7</i>	IOPC7	70	49	49	63	CAN receive data or GPIO (1)		
CANTYLORGO	CANTX	72	50	-	-	CANUS CONTRACTOR OF CONTRACTOR		
CANTX/ <i>IOPC6</i>	IOPC6	72	50	50	64	CAN transmit data or GPIO (↑)		
SCITXD/IOPA0		25	17	17	43	SCI asynchronous serial port transmit data or GPIO (\uparrow)		
SCIRXD/ <i>IOPA1</i>		26	18	18	44	SCI asynchronous serial port receive data or or GPIO (↑)		
001011///0004	SPICLK	35	24	24	-			
SPICLK/ <i>IOPC4</i>	IOPC4	35	24	24	47	SPI clock or GPIO (1)		
CDICINO/ICEGO	SPISIMO	30	21	21	_	CDI along in transfer out or CDIC. (1)		
SPISIMO/IOPC2	IOPC2	30	21	21	45	SPI slave in, master out or GPIO (↑)		
CDICOM//OBC2	SPISOMI	32	22	22	_	CDI player out master in or CDIO (^)		
SPISOMI/ <i>IOPC3</i>	IOPC3	32	22	22	46	SPI slave out, master in or GPIO (1)		
CDICTE/JOBOS	SPISTE	33	23	23	-	CDI alous transmit analys (antique) as CDIO (A)		
SPISTE/ <i>IOPC5</i>	IOPC5	33	23	23	_	SPI slave transmit enable (optional) or GPIO (1)		

[†] Bold, italicized pin names indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

TMS320LF2407, TMS320LF2406, TMS320LF2402 TMS320LC2406, TMS320LC2404, TMS320LC2402 DSP CONTROLLERS SPRS094C - APRIL 1999 - REVISED OCTOBER 1999

pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME		'LF2407	'2406	'LC2404	'2402	DESCRIPTION
		L	EXTERNA	AL INTERR	UPTS, CL	оск
เ ร		133	93	93	28	Device reset. $\overline{\text{RS}}$ causes the '240x to terminate execution and sets PC = 0. When $\overline{\text{RS}}$ is brought to a high level, execution begins at location zero of program memory. $\overline{\text{RS}}$ affects (or sets to zero) various registers and status bits. When the watchdog timer overflows, it initiates a system reset pulse that is reflected on the $\overline{\text{RS}}$ pin. (\uparrow)
PDPINTA		7	6	6	36	Power drive protection interrupt input. This interrupt, when activated, puts the PWM output pins (EVA) in the high-impedance state should motor drive/power converter abnormalities, such as overvoltage or overcurrent, etc., arise. PDPINTA is a falling-edge-sensitive interrupt. (↑)
XINT1/ <i>IOPA2</i>		23	16	16		External user interrupt 1 or GPIO. Both XINT1 and XINT2 are edge-sensitive. The edge polarity is programmable. (↑)
XINT2/ADCSOC/ <i>IOPD0</i>		21	15	15	42	External user interrupt 2 and ADC start of conversion or GPIO. External "start-of-conversion" input for ADC/GPIO. Both XINT1 and XINT2 are edge-sensitive. The edge polarity is programmable. (↑)
CLKOUT/IOPE0		73	51	51	1	Clock output or GPIO. This pin outputs either the CPU clock (CLKOUT) or the watchdog clock (WDCLK). The selection is made by the CLKSRC bit (bit 14) of the System Control and Status Register (SCSR). This pin can be used as a GPIO if not used as a clock output pin. (↑)
PDPINTB		137	95	95		Power drive protection interrupt input. This interrupt, when activated, puts the PWM output pins (EVB) in the high-impedance state should motor drive/power converter abnormalities, such as overvoltage or overcurrent, etc., arise. PDPINT is a falling-edge-sensitive interrupt. (↑)
	C	SCILLATO	OR, PLL, F	LASH, BOO	OT, AND N	IISCELLANEOUS
XTAL1/CLKIN		123	87	87	24	PLL oscillator input pin. Crystal input to PLL/clock source input to PLL. XTAL1/CLKIN is tied to one side of a reference crystal.
XTAL2		124	88	88	25	Crystal output. PLL oscillator output pin. XTAL2 is tied to one side of a reference crystal. This pin goes in the high-impedance state when EMU1/OFF is active low.
PLLF		11	9	9	38	Filter input 1
PLLVCCA		12	10	10	39	PLL supply (3.3 V)
PLLF2		10	8	8	37	Filter input 2
BOOT_EN / XF	BOOT_EN	121	86	-	23	Boot ROM enable, GPO, XF. This pin will be sampled as input (BOOT_EN) to update SCSR2.3 (BOOT_EN bit) during reset and then driven as an output signal for
	XF	121	86	86	23	XF. ROM devices do not have boot ROM, hence, no BOOT_EN modes. (↑)

[†] Bold, italicized pin names indicate pin function after reset.



[‡]GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME	'LF2407	'2406	'LC2404	'2402	DESCRIPTION
	OSCILI	LATOR, PLI	L, FLASH, E	BOOT, AND	MISCELLANEOUS (CONTINUED)
V _{CCP} (5V)	58	40	40	60§	Flash programming voltage pin. This is the 5-V supply used for flash programming. Flash cannot be programmed if this pin is held at 0 V. Connect to 5-V supply for programming or tie it to GND during functional mode.
TP1 (Flash)	60	42	42	61§	Flash array test pin. Do not connect.
TP2 (Flash)	63	44	44	62§	Flash array test pin. Do not connect.
IOPF6	131	92	92		General-purpose I/O (↑)
BIO /IOPC1	119	85	85		Branch control input. BIO is polled by the BCND pma, BIO instruction. If BIO is low, a branch is executed. If BIO is not used, it should be pulled high. This pin is configured as a branch control input by all device resets. It can be used as a GPIO, if not used as a branch control input. (↑)
			EMU	JLATION AI	ND TEST
EMU0	90	61	61	7	Emulator I/O #0 with internal pullup. When TRST is driven high, this pin is used as an interrupt to or from the emulator system and is defined as input/output through the JTAG scan. (↑)
EMU1/OFF	91	62	62	8	Emulator pin 1. Emulator pin 1 disables all outputs. When TRST is driven high, EMU1/OFF is used as an interrupt to or from the emulator system and is defined as an input/output through the JTAG scan. When TRST is driven low, this pin is configured as OFF. EMU1/OFF, when active low, puts all output drivers in the high-impedance state. Note that OFF is used exclusively for testing and emulation purposes (not for multiprocessing applications). Therefore, for the OFF condition, the following apply: TRST = 0 EMU0 = 1 EMU1/OFF = 0
TCK	135	94	94	29	JTAG test clock with internal pullup (↑)
TDI	139	96	96	30	JTAG test data input (TDI) with internal pullup. TDI is clocked into the selected register (instruction or data) on a rising edge of TCK. (↑)
TDO	142	99	99	31	JTAG scan out, test data output (TDO). The contents of the selected register (instruction or data) is shifted out of TDO on the falling edge of TCK. (\downarrow)
TMS	144	100	100	32	JTAG test-mode select (TMS) with internal pullup. This serial control input is clocked into the TAP controller on the rising edge of TCK. (↑)
TMS2	36	25	25	48	JTAG test-mode select 2 (TMS) with internal pullup. This serial control input is clocked into the TAP controller on the rising edge of TCK. Used for test and emulation only. (1)
TRST	1	1	1	33	JTAG test reset with internal pulldown. TRST, when driven high, gives the scan system control of the operations of the device. If this signal is not connected or driven low, the device operates in its functional mode, and the test reset signals are ignored. (\$\driversigma\$)

[†] Bold, italicized pin names indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

[§] Pin changes with respect to SPRS094B data sheet.

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pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME		'LF2407	'2406	'LC2404	'2402	DESCRIPTION
		ADDRE	SS, DATA,	AND MEMO	RY CONTR	OL SIGNALS
DS		87				Data space strobe. IS, DS, and PS are always high unless low-level asserted for access to the relevant external memory space or I/O. They are placed in the high-impedance state during reset, power down, and when EMU1/OFF is active low.
ĪS		82				I/O space strobe. IS, DS, and PS are always high unless low-level asserted for access to the relevant external memory space or I/O. They are placed in the high-impedance state during reset, power down, and when EMU1/OFF is active low.
PS		84				Program space strobe. IS, DS, and PS are always high unless low-level asserted for access to the relevant external memory space or I/O. They are placed in the high-impedance state during reset, power down, and when EMU1/OFF is active low.
R∕₩		92				Read/write qualifier signal. R/W indicates transfer direction during communication to an external device. It is normally in read mode (high), unless low level is asserted for performing a write operation. It is placed in the high-impedance state when EMU1/OFF is active low and during power down.
<i>₩\</i> \(\bar{R}\)		19				Write/Read qualifier or GPIO. This is an inverted R/W signal useful for zero-wait-state memory interface. It is normally low, unless a memory write operation is
	IOPC0	19	14	14		performed. See Table 13, Port C section, for reset note regarding 'LF2406 and 'LF2402. (1)
RD		93				Read enable strobe. Read-select indicates an active, external read cycle. RD is active on all external program, data, and I/O reads. RD goes into the high-impedance state when EMU1/OFF is active low.
WE		89				Write enable strobe. The falling edge of WE indicates that the device is driving the external data bus (D15–D0). WE is active on all external program, data, and I/O writes. WE goes in the high-impedance state when EMU1/OFF is active low.
STRB		96				External memory access strobe. STRB is always high unless asserted low to indicate an external bus cycle. STRB is active for all off-chip accesses. It is placed in the high-impedance state during power down, and when EMU1/OFF is active low.
READY		120				READY is pulled low to add wait states for external accesses. READY indicates that an external device is prepared for a bus transaction to be completed. If the device is not ready, it pulls the READY pin low. The processor waits one cycle and checks READY again. Note that the processor performs READY-detection if at least one software wait state is programmed. To meet the external READY timings, the wait-state generator control register (WSGR) should be programmed for at least one wait state. (↑)

[†] Bold, italicized pin names indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME	'LF2407	'2406	'LC2404	'2402	DESCRIPTION		
ADDRESS, DATA, AND MEMORY CONTROL SIGNALS (CONTINUED)							
MP/MC	118				Microprocessor/Microcomputer mode select. If this pin is low during reset, the device is put in microcomputer mode and program execution begins at 0000h of internal program memory (flash EEPROM). A high value during reset puts the device in microprocessor mode and program execution begins at 0000h of external program memory. This line sets the MP/MC bit (bit 2 in the SCSR2 register). (\$\delta\$)		
ENA_144	122				Active high to enable external interface signals. If pulled low, the '2407 behaves like the '2406/'2404—i.e., it has no external memory and generates an illegal address if any of the three external spaces are accessed ($\overline{\text{IS}}$ and $\overline{\text{DS}}$ asserted). This pin has an internal pulldown. (\downarrow)		
VIS_OE	97				Visibility output enable (active when data bus is output). This pin is active (low) whenever the external databus is driving as an output during visibility mode. Can be used by external decode logic to prevent data bus contention while running in visibility mode.		
A0	80				Bit 0 of the 16-bit address bus		
A1	78				Bit 1 of the 16-bit address bus		
A2	74				Bit 2 of the 16-bit address bus		
A3	71				Bit 3 of the 16-bit address bus		
A4	68				Bit 4 of the 16-bit address bus		
A5	64				Bit 5 of the 16-bit address bus		
A6	61				Bit 6 of the 16-bit address bus		
A7	57				Bit 7 of the 16-bit address bus		
A8	53				Bit 8 of the 16-bit address bus		
A9	51				Bit 9 of the 16-bit address bus		
A10	48				Bit 10 of the 16-bit address bus		
A11	45				Bit 11 of the 16-bit address bus		
A12	43				Bit 12 of the 16-bit address bus		
A13	39				Bit 13 of the 16-bit address bus		
A14	34				Bit 14 of the 16-bit address bus		
A15	31				Bit 15 of the 16-bit address bus		
D0	127				Bit 0 of 16-bit data bus (1)		
D1	130				Bit 1 of 16-bit data bus (↑)		
D2	132				Bit 2 of 16-bit data bus (↑)		
D3	134				Bit 3 of 16-bit data bus (↑)		
D4	136				Bit 4 of 16-bit data bus (↑)		
D5	138				Bit 5 of 16-bit data bus (↑)		
D6	143				Bit 6 of 16-bit data bus (1)		
D7	5				Bit 7 of 16-bit data bus (↑)		
D8	9				Bit 8 of 16-bit data bus (↑)		

[†] **Bold, italicized pin names** indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

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pin functions (continued)

Table 2. 'LF240x and 'LC240x Pin List and Package Options†‡ (Continued)

PIN NAME	'LF2407	'2406	'LC2404	'2402	DESCRIPTION					
	ADD	RESS, DAT	A, AND ME	MORY CO	NTROL SIGNALS (CONTINUED)					
D9	13				Bit 9 of 16-bit data bus (1)					
D10	15				Bit 10 of 16-bit data bus (1)					
D11	17				Bit 11 of 16-bit data bus (↑)					
D12	20				Bit 12 of 16-bit data bus (1)					
D13	22				Bit 13 of 16-bit data bus (↑)					
D14	24				Bit 14 of 16-bit data bus (1)					
D15	27				Bit 15 of 16-bit data bus (1)					
			F	POWER SU	PPLY					
	29	20	20	6						
M	50	35	35	27	Cana ayanta ya 2 V Birital lania ayantaya kana					
V_{DD}	86	59	59	56§	Core supply +3.3 V. Digital logic supply voltage.					
	129	91	91							
	4	4	4	10						
	42	30	30	35	I/O buffer supply +3.3 V. Digital logic and buffer supply voltage.					
V _{DDO}	67	47	47	52§						
V DDO	77	54	54		1/O burier supply +3.5 v. Digital logic and burier supply voltage.					
	95	64	64							
	141	98	98							
	28	19	19	5						
V _{SS}	49	34	34	26	Core ground. Digital logic ground reference.					
VSS	85	58	58	55§	Core ground. Digital logic ground reference.					
	128	90	90							
	3	3	3	9						
	41	29	29	34						
	66	46	46	51§	_					
VSSO	76	53	53		I/O buffer ground. Digital logic and buffer ground reference.					
	94	63	63		_					
	125	97	97		_					
	140									

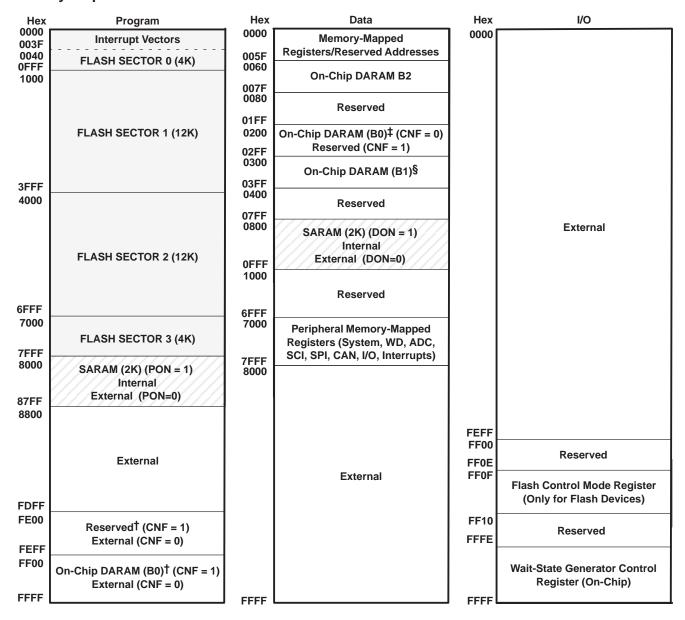
[†] Bold, italicized pin names indicate pin function after reset.



[‡] GPIO – General-purpose input/output pin. All GPIOs come up as input after reset.

[§] Pin changes with respect to SPRS094B data sheet.

memory maps - 'LF2407



On-Chip Flash Memory (Sectored) – if $MP/\overline{MC} = 0$ External Program Memory – if $MP/\overline{MC} = 1$

SARAM (See Table 1 for details.)

NOTE A: Boot ROM: If the boot ROM is enabled, then address 0000-00FF in the program space will be occupied by boot ROM.

Figure 1. TMS320LF2407 Memory Map



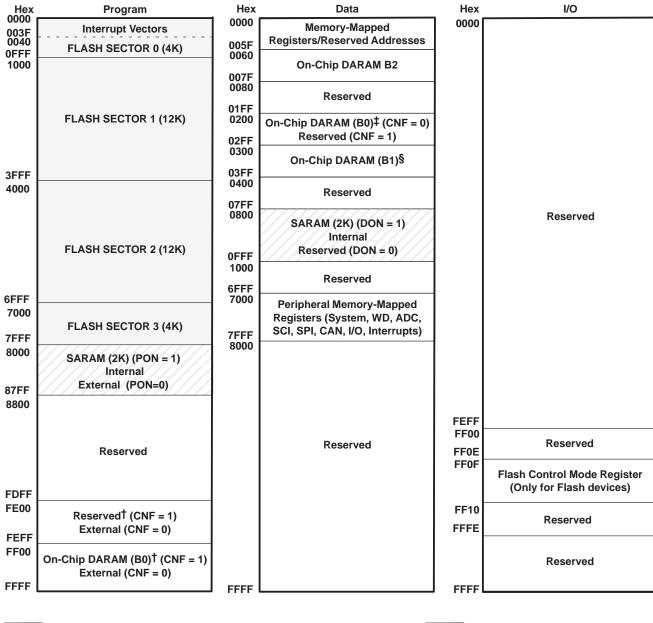
[†]When CNF = 1, addresses FE00h-FEFFh and FF00h-FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h-FEFFh are referred to as reserved when CNF = 1.

^{\$\}frac{1}{2}\$ When CNF = 0, addresses 0100h-01FFh and 0200h-02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h-01FFh are referred to as reserved.

[§] Addresses 0300h–03FFh and 0400h–04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h-04FFh are referred to as reserved.

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memory maps (continued) - 'LF2406



On-Chip Flash Memory (Sectored)

SARAM (See Table 1 for details.)

NOTE A: Boot ROM: If the boot ROM is enabled, then address 0000–00FF in the program space will be occupied by boot ROM. † When CNF = 1, addresses FE00h–FEFFh and FF00h–FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h–FEFFh are referred to as reserved when CNF = 1.

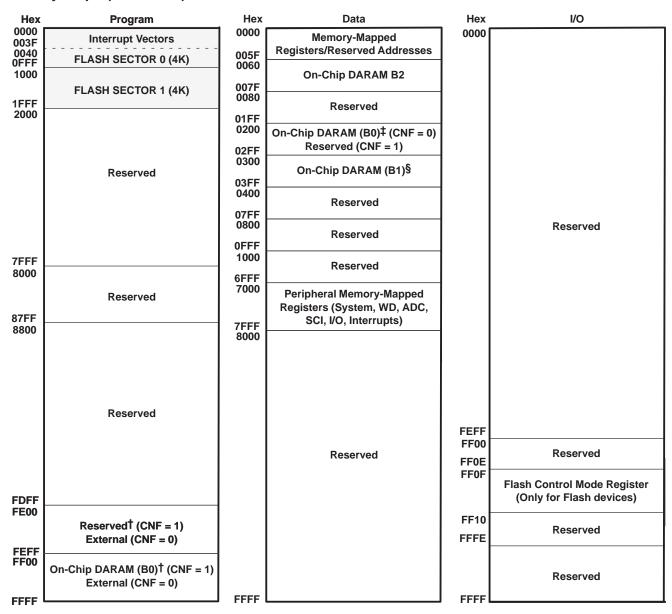
Figure 2. TMS320LF2406 Memory Map



When CNF = 0, addresses 0100h–01FFh and 0200h–02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h–01FFh are referred to as reserved.

[§] Addresses 0300h–03FFh and 0400h–04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h–04FFh are referred to as reserved.

memory maps (continued) - 'LF2402



On-Chip Flash Memory (Sectored)

NOTE A: Boot ROM: If the boot ROM is enabled, then address 0000-00FF in the program space will be occupied by boot ROM.

Figure 3. TMS320LF2402 Memory Map



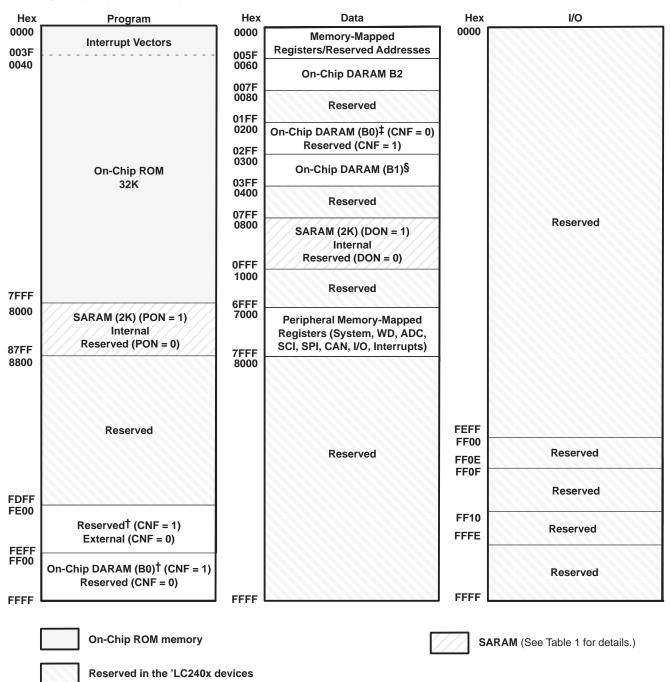
[†]When CNF = 1, addresses FE00h-FEFFh and FF00h-FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h-FEFFh are referred to as reserved when CNF = 1.

^{\$\}frac{1}{2}\$ When CNF = 0, addresses 0100h-01FFh and 0200h-02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h-01FFh are referred to as reserved.

[§] Addresses 0300h-03FFh and 0400h-04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h–04FFh are referred to as reserved.

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memory maps (continued) - 'LC2406



[†]When CNF = 1, addresses FE00h-FEFFh and FF00h-FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h-FEFFh are referred to as reserved when CNF = 1.

Figure 4. TMS320LC2406 Memory Map



^{\$\}frac{1}{2}\$ When CNF = 0, addresses 0100h–01FFh and 0200h–02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h-01FFh are referred to as reserved.

[§] Addresses 0300h–03FFh and 0400h–04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h-04FFh are referred to as reserved.

memory maps (continued) - 'LC2404 Hex I/O Data **Program** 0000 0000 0000 **Memory-Mapped Interrupt Vectors** Registers/Reserved Addresses 003F 005F 0040 0060 On-Chip DARAM B2 007F On-Chip ROM 0800 Reserved 16K 01FF 0200 On-Chip DARAM (B0)‡ (CNF = 0) 3FFF Reserved (CNF = 1) 02FF 4000 0300 On-Chip DARAM (B1)§ 03FF Reserved 0400 Reserved 7FFF 07FF Reserved 0800 8000 SARAM(1K)(PON = 1)SARAM (1K) (DON = 1)Internal Internal Reserved (DON = 0) Reserved (PON = 0) 0BFF 83FF 0C00 8400 Reserved 6FFF 7000 **Peripheral Memory-Mapped** Registers (System, WD, ADC, SCI, SPI, I/O, Interrupts) 7FFF 8000 Reserved **FEFF** FF00 Reserved Reserved FF0E FF0F Reserved **FDFF** FE00 FF10 Reserved[†] (CNF = 1) Reserved **FFFE** External (CNF = 0) FEFF FF00 On-Chip DARAM (B0)† (CNF = 1) Reserved Reserved (CNF = 0) **FFFF FFFF FFFF On-Chip ROM memory SARAM** (See Table 1 for details.) Reserved in the 'LC240x devices

Figure 5. TMS320LC2404 Memory Map



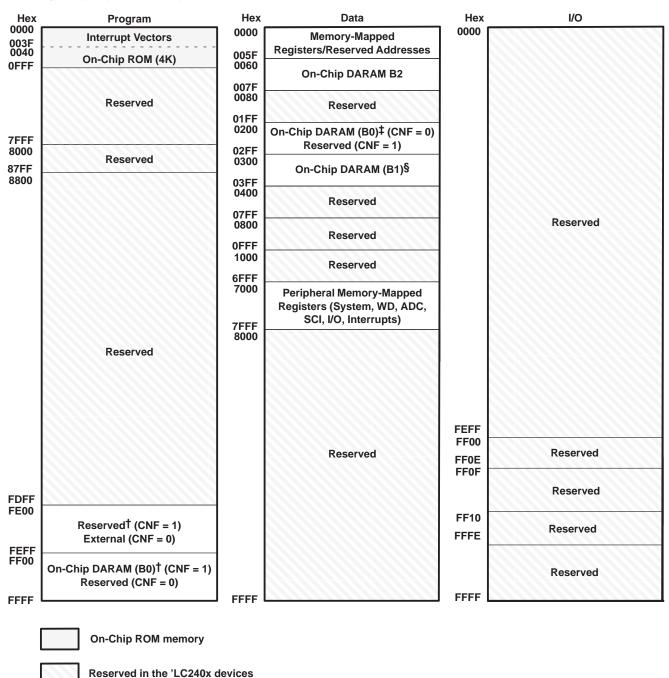
[†]When CNF = 1, addresses FE00h-FEFFh and FF00h-FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h-FEFFh are referred to as reserved when CNF = 1.

^{\$\}frac{1}{2}\$ When CNF = 0, addresses 0100h-01FFh and 0200h-02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h-01FFh are referred to as reserved.

[§] Addresses 0300h–03FFh and 0400h–04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h-04FFh are referred to as reserved.

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memory maps (continued) - 'LC2402



[†]When CNF = 1, addresses FE00h-FEFFh and FF00h-FFFFh are mapped to the same physical block (B0) in program-memory space. For example, a write to FE00h has the same effect as a write to FF00h. For simplicity, addresses FE00h-FEFFh are referred to as reserved when CNF = 1.

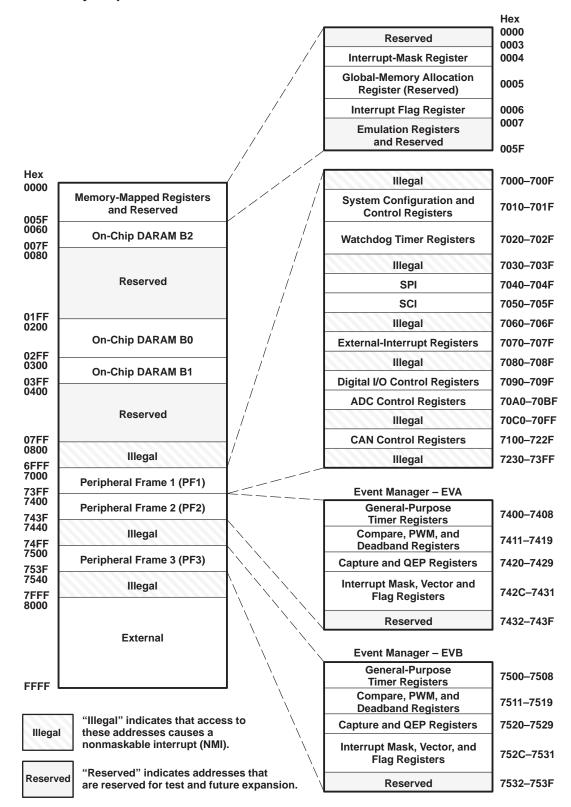
Figure 6. TMS320LC2402 Memory Map



^{\$\}frac{1}{2}\$ When CNF = 0, addresses 0100h–01FFh and 0200h–02FFh are mapped to the same physical block (B0) in data-memory space. For example, a write to 0100h has the same effect as a write to 0200h. For simplicity, addresses 0100h-01FFh are referred to as reserved.

[§] Addresses 0300h–03FFh and 0400h–04FFh are mapped to the same physical block (B1) in data-memory space. For example, a write to 0400h has the same effect as a write to 0300h. For simplicity, addresses 0400h–04FFh are referred to as reserved.

peripheral memory map of the 'LF240x/'LC240x





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device reset and interrupts

The TMS320x240x software-programmable interrupt structure supports flexible on-chip and external interrupt configurations to meet real-time interrupt-driven application requirements. The 'LF240x recognizes three types of interrupt sources.

- Reset (hardware- or software-initiated) is unarbitrated by the CPU and takes immediate priority over any
 other executing functions. All maskable interrupts are disabled until the reset service routine enables them.
 - The 'LF240x devices have two sources of reset: an external reset pin and a watchdog timer timeout (reset).
- Hardware-generated interrupts are requested by external pins or by on-chip peripherals. There are two
 types:
 - External interrupts are generated by one of four external pins corresponding to the interrupts XINT1, XINT2, PDPINTA, and PDPINTB. These four can be masked both by dedicated enable bits and by the CPU's interrupt mask register (IMR), which can mask each maskable interrupt line at the DSP core.
 - Peripheral interrupts are initiated internally by these on-chip peripheral modules: event manager A, event manager B, SPI, SCI, WD, CAN, and ADC. They can be masked both by enable bits for each event in each peripheral and by the CPU's IMR, which can mask each maskable interrupt line at the DSP core.
- Software-generated interrupts for the 'LF240x devices include:
 - The INTR instruction. This instruction allows initialization of any 'LF240x interrupt with software. Its
 operand indicates the interrupt vector location to which the CPU branches. This instruction globally
 disables maskable interrupts (sets the INTM bit to 1).
 - The NMI instruction. This instruction forces a branch to interrupt vector location 24h. This instruction
 globally disables maskable interrupts. '240x devices do not have the NMI hardware signal, only
 software activation is provided.
 - The TRAP instruction. This instruction forces the CPU to branch to interrupt vector location 22h. The
 TRAP instruction does not disable maskable interrupts (INTM is not set to 1); therefore, when the CPU
 branches to the interrupt service routine, that routine can be interrupted by the maskable hardware
 interrupts.
 - An emulator trap. This interrupt can be generated with either an INTR instruction or a TRAP instruction.

Six core interrupts (INT1–INT6) are expanded using a peripheral interrupt expansion (PIE) module identical to the 'F24x devices. The PIE manages all the peripheral interrupts from the '240x peripherals and are grouped to share the six-core level interrupts. Figure 7 shows the PIE block diagram for hardware-generated interrupts.

The PIE diagram (Figure 7) and the interrupt table (Table 3) explain the grouping and interrupt vector maps. 'LF240x devices have interrupts identical to the 'F24x devices and should be completely code-compatible. '240x devices also have peripheral interrupts identical to the 'F24x – plus additional interrupts for new peripherals such as event manager B. Though the new interrupts share the '24x interrupt grouping, they all have a unique vector to differentiate among the interrupts. See Table 3 for details.



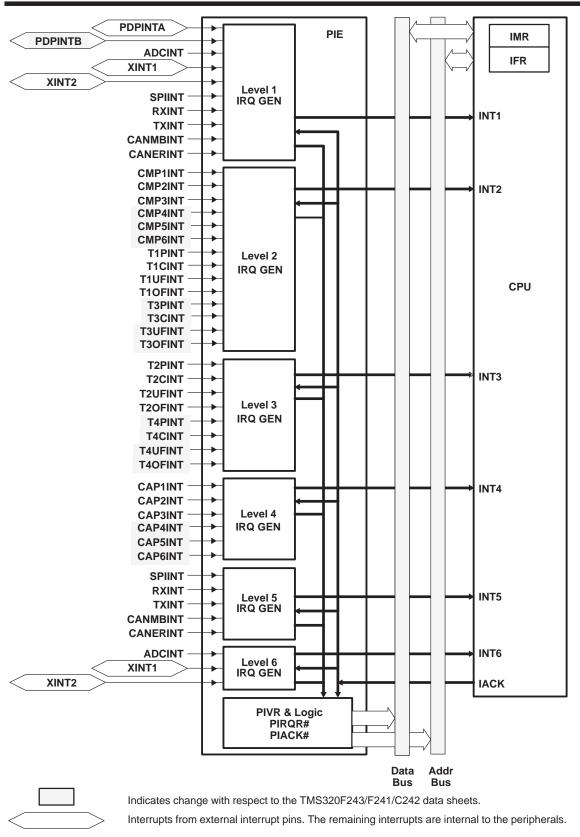


Figure 7. Peripheral Interrupt Expansion (PIE) Module Block Diagram for Hardware-Generated Interrupts



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interrupt request structure

Table 3. 'LF240x/'LC240x Interrupt Source Priority and Vectors

INTERRUPT NAME	OVERALL PRIORITY	CPU INTERRUPT AND VECTOR ADDRESS	BIT POSITION IN PIRQRX AND PIACKRX	PERIPHERAL INTERRUPT VECTOR (PIV)	MASK- ABLE?	SOURCE PERIPHERAL MODULE	DESCRIPTION
Reset	1	RSN 0000h		N/A	N	RS pin, Watchdog	Reset from pin, watchdog timeout
Reserved	2	– 0026h		N/A	N	CPU	Emulator trap
NMI	3	NMI 0024h		N/A	N	Nonmaskable Interrupt	Nonmaskable interrupt, software interrupt only
PDPINTA	4		0.0	0020h	Υ	EVA	Power device protection
PDPINTB	5	1	2.0	0019h	Υ	EVB	interrupt pins
ADCINT	6		0.1	0004h	Υ	ADC	ADC interrupt in high-priority mode
XINT1	7		0.2	0001h	Υ	External Interrupt Logic	External interrupt pins in high priority
XINT2	8		0.3	0011h	Υ	External Interrupt Logic	External interrupt pins in high priority
SPIINT	9	INT1 0002h	0.4	0005h	Υ	SPI	SPI interrupt pins in high priority
RXINT	10	0002	0.5	0006h	Υ	SCI	SCI receiver interrupt in high-priority mode
TXINT	11		0.6	0007h	Y	SCI	SCI transmitter interrupt in high-priority mode
CANMBINT	12		0.7	0040	Y	CAN	CAN mailbox in high-priority mode
CANERINT	13		0.8	0041	Υ	CAN	CAN error interrupt in high-priority mode
CMP1INT	14		0.9	0021h	Υ	EVA	Compare 1 interrupt
CMP2INT	15	1	0.10	0022h	Υ	EVA	Compare 2 interrupt
CMP3INT	16	1	0.11	0023h	Υ	EVA	Compare 3 interrupt
T1PINT	17	INITO	0.12	0027h	Υ	EVA	Timer 1 period interrupt
T1CINT	18	INT2 0004h	0.13	0028h	Υ	EVA	Timer 1 compare interrupt
T1UFINT	19]	0.14	0029h	Υ	EVA	Timer 1 underflow interrupt
T10FINT	20		0.15	002Ah	Υ	EVA	Timer 1 overflow interrupt
CMP4INT	21]	2.1	0024h	Υ	EVB	Compare 4 interrupt
CMP5INT	22		2.2	0025h	Υ	EVB	Compare 4 interrupt
CMP6INT	23]	2.3	0026h	Υ	EVB	Compare 4 interrupt
T3PINT	24]	2.4	002Fh	Υ	EVB	Timer 3 period interrupt
T3CINT	25]	2.5	0030h	Υ	EVB	Timer 3 compare interrupt
T3UFINT	26		2.6	0031h	Υ	EVB	Timer 3 underflow interrupt
T3OFINT	27		2.7	0032h	Υ	EVB	Timer 3 overflow interrupt

[†] Refer to the TMS320C240 DSP Controllers CPU, System, and Instruction Set Reference Guide (literature number SPRU160) and the TMS320F243/F241/C242 DSP Controllers System and Peripherals User's Guide (literature number SPRU276) for more information.

New peripheral interrupts and vectors with respect to the 'F243/'F241 devices.



interrupt request structure (continued)

Table 3.'LF240x/'LC240x Interrupt Source Priority and Vectors (Continued)

INTERRUPT NAME	OVERALL PRIORITY	CPU INTERRUPT AND VECTOR ADDRESS	BIT POSITION IN PIRQRX AND PIACKRX	PERIPHERAL INTERRUPT VECTOR (PIV)	MASK- ABLE?	SOURCE PERIPHERAL MODULE	DESCRIPTION
T2PINT	28		1.0	002Bh	Υ	EVA	Timer 2 period interrupt
T2CINT	29		1.1	002Ch	Υ	EVA	Timer 2 compare interrupt
T2UFINT	30		1.2	002Dh	Y	EVA	Timer 2 underflow interrupt
T20FINT	31	INT3	1.3	002Eh	Y	EVA	Timer 2 overflow interrupt
T4PINT	32	0006h	2.8	0039h	Υ	EVB	Timer 4 period interrupt
T4CINT	33		2.9	003Ah	Υ	EVB	Timer 4 compare interrupt
T4UFINT	34		2.10	003Bh	Υ	EVB	Timer 4 underflow interrupt
T40FINT	35		2.11	003Ch	Υ	EVB	Timer 4 overflow interrupt
CAP1INT	36		1.4	0033h	Υ	EVA	Capture 1 interrupt
CAP2INT	37		1.5	0034h	Y	EVA	Capture 2 interrupt
CAP3INT	38	INT4	1.6	0035h	Y	EVA	Capture 3 interrupt
CAP4INT	39	0008h	2.12	0036h	Y	EVB	Capture 4 interrupt
CAP5INT	40		2.13	0037h	Y	EVB	Capture 5 interrupt
CAP6INT	41		2.14	0038h	Υ	EVB	Capture 6 interrupt
SPIINT	42		1.7	0005h	Υ	SPI	SPI interrupt (low priority)
RXINT	43		1.8	0006h	Y	SCI	SCI receiver interrupt (low-priority mode)
TXINT	44	INT5 000Ah	1.9	0007h	Y	SCI	SCI transmitter interrupt (low-priority mode)
CANMBINT	45	OUDAII	1.10	0040h	Y	CAN	CAN mailbox interrupt (low-priority mode)
CANERINT	46		1.11	0041h	Y	CAN	CAN error interrupt (low-priority mode)
ADCINT	47		1.12	0004h	Y	ADC	ADC interrupt (low priority)
XINT1	48	INT6 000Ch	1.13	0001h	Υ	External Interrupt Logic	External interrupt pins (low-priority mode)
XINT2	49		1.14	0011h	Υ	External Interrupt Logic	External interrupt pins (low-priority mode)
Reserved		000Eh		N/A	Υ	CPU	Analysis interrupt
TRAP	N/A	0022h		N/A	N/A	CPU	TRAP instruction
Phantom Interrupt Vector	N/A	N/A		0000h	N/A	CPU	Phantom interrupt vector
INT8-INT16	N/A	0010h-0020h		N/A	N/A	CPU	Coffware intermediate +
INT20-INT31	N/A	00028h-0603Fh		N/A	N/A	CPU	Software interrupt vectors

TRefer to the TMS320C240 DSP Controllers CPU, System, and Instruction Set Reference Guide (literature number SPRU160) and the TMS320F243/F241/'C242 DSP Controllers System and Peripherals User's Guide (literature number SPRU276) for more information.

New peripheral interrupts and vectors with respect to the 'F243/'F241 devices.



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DSP CPU Core

The TMS320x240x devices use an advanced Harvard-type architecture that maximizes processing power by maintaining two separate memory bus structures — program and data — for full-speed execution. This multiple bus structure allows data and instructions to be read simultaneously. Instructions support data transfers between program memory and data memory. This architecture permits coefficients that are stored in program memory to be read in RAM, thereby eliminating the need for a separate coefficient ROM. This, coupled with a four-deep pipeline, allows the 'LF240x/'LC240x devices to execute most instructions in a single cycle. See the architectural block diagram of the '24x DSP Core for more information.

TMS320x240x instruction set

The 'x240x microprocessor implements a comprehensive instruction set that supports both numeric-intensive signal-processing operations and general-purpose applications, such as multiprocessing and high-speed control. Source code for the 'C1x and 'C2x DSPs is upwardly compatible with the 'x243/'x241 and '240x devices.

For maximum throughput, the next instruction is prefetched while the current one is being executed. Because the same data lines are used to communicate to external data, program, or I/O space, the number of cycles an instruction requires to execute varies, depending upon whether the next data operand fetch is from internal or external memory. Highest throughput is achieved by maintaining data memory on chip and using either internal or fast external program memory.

addressing modes

The TMS320x240x instruction set provides four basic memory-addressing modes: direct, indirect, immediate, and register.

In direct addressing, the instruction word contains the lower seven bits of the data memory address. This field is concatenated with the nine bits of the data memory page pointer (DP) to form the 16-bit data memory address. Therefore, in the direct-addressing mode, data memory is paged effectively with a total of 512 pages, with each page containing 128 words.

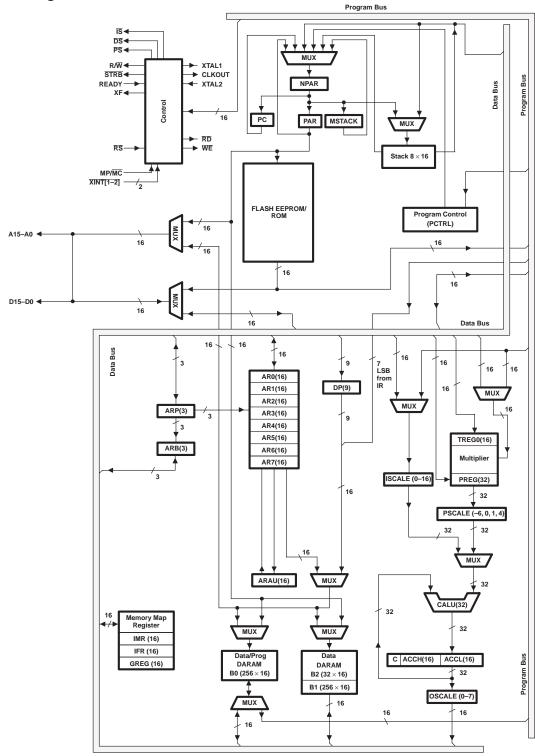
Indirect addressing accesses data memory through the auxiliary registers. In this addressing mode, the address of the instruction operand is contained in the currently selected auxiliary register. Eight auxiliary registers (AR0–AR7) provide flexible and powerful indirect addressing. To select a specific auxiliary register, the auxiliary register pointer (ARP) is loaded with a value from 0 to 7 for AR0 through AR7, respectively.

scan-based emulation

TMS320x2xx devices incorporate scan-based emulation logic for code-development and hardware-development support. Scan-based emulation allows the emulator to control the processor in the system without the use of intrusive cables to the full pinout of the device. The scan-based emulator communicates with the 'x2xx by way of the IEEE 1149.1-compatible (JTAG) interface. The 'x240x DSPs, like the TMS320F243/241, TMS320F206, TMS320C203, and TMS320LC203, do not include boundary scan. The scan chain of these devices is useful for emulation function only.



functional block diagram of the '240x DSP CPU



NOTES: A. See Table 4 for symbol descriptions.

- B. For clarity, the data and program buses are shown as single buses although they include address and data bits.
- C. Refer to the TMS320F243, TMS320F241 DSP Controllers data sheet (literature number SPRS064), the TMS320C240, TMS320F240 DSP Controllers data sheet (literature number SPRS042), and the TMS320C240 DSP Controllers CPU, System, and Instruction Set Reference Guide (literature number SPRU160) for CPU instruction set information.



TMS320LF2407, TMS320LF2406, TMS320LF2402 TMS320LC2406, TMS320LC2404, TMS320LC2402 DSP CONTROLLERS SPRS094C - APRIL 1999 - REVISED OCTOBER 1999

'240x legend for the internal hardware

Table 4. Legend for the '240x DSP CPU Internal Hardware

SYMBOL	NAME	DESCRIPTION						
ACC	Accumulator	32-bit register that stores the results and provides input for subsequent CALU operations. Also includes shift and rotate capabilities						
ARAU	Auxiliary Register Arithmetic Unit	An unsigned, 16-bit arithmetic unit used to calculate indirect addresses using the auxiliary registers as inputs and outputs						
AUX REGS	Auxiliary Registers 0-7	These 16-bit registers are used as pointers to anywhere within the data space address range. They operated upon by the ARAU and are selected by the auxiliary register pointer (ARP). AR0 can also be use an index value for AR updates of more than one and as a compare value to AR.						
С	Carry	Register carry output from CALU. C is fed back into the CALU for extended arithmetic operation. The C bit resides in status register 1 (ST1), and can be tested in conditional instructions. C is also used in accumulator shifts and rotates.						
CALU	Central Arithmetic Logic Unit	32-bit-wide main arithmetic logic unit for the TMS320C2xx core. The CALU executes 32-bit operations in a single machine cycle. CALU operates on data coming from ISCALE or PSCALE with data from ACC, and provides status results to PCTRL.						
DARAM	Dual-Access RAM	If the on-chip RAM configuration control bit (CNF) is set to 0, the reconfigurable data dual-access RAM (DARAM) block B0 is mapped to data space; otherwise, B0 is mapped to program space. Blocks B1 and B2 are mapped to data memory space only, at addresses 0300–03FF and 0060–007F, respectively. Blocks 0 and 1 contain 256 words, while block 2 contains 32 words.						
DP	Data Memory Page Pointer	The 9-bit DP register is concatenated with the seven least significant bits (LSBs) of an instruction word to form a direct memory address of 16 bits. DP can be modified by the LST and LDP instructions.						
GREG	Global Memory Allocation Register	GREG specifies the size of the global data memory space. Since the global memory space is not used in the '240x devices, this register is reserved.						
IMR	Interrupt Mask Register	IMR individually masks or enables the seven interrupts.						
IFR	Interrupt Flag Register	The 7-bit IFR indicates that the TMS320C2xx has latched an interrupt from one of the seven maskable interrupts.						
INT#	Interrupt Traps	A total of 32 interrupts by way of hardware and/or software are available.						
ISCALE	Input Data-Scaling Shifter	16- to 32-bit barrel left-shifter. ISCALE shifts incoming 16-bit data 0 to 16 positions left, relative to the 32-bit output within the fetch cycle; therefore, no cycle overhead is required for input scaling operations.						
MPY	Multiplier	16×16 -bit multiplier to a 32-bit product. MPY executes multiplication in a single cycle. MPY operates either signed or unsigned 2s-complement arithmetic multiply.						
MSTACK	Micro Stack	MSTACK provides temporary storage for the address of the next instruction to be fetched when program address-generation logic is used to generate sequential addresses in data space.						
MUX	Multiplexer	Multiplexes buses to a common input						
NPAR	Next Program Address Register	NPAR holds the program address to be driven out on the PAB in the next cycle.						
OSCALE	Output Data-Scaling Shifter	16- to 32-bit barrel left-shifter. OSCALE shifts the 32-bit accumulator output 0 to 7 bits left for quantization management and outputs either the 16-bit high- or low-half of the shifted 32-bit data to the data-write data bus (DWEB).						
PAR	Program Address Register	PAR holds the address currently being driven on PAB for as many cycles as it takes to complete all memory operations scheduled for the current bus cycle.						
PC	Program Counter	PC increments the value from NPAR to provide sequential addresses for instruction-fetching and sequential data-transfer operations.						
PCTRL	Program Controller	PCTRL decodes instruction, manages the pipeline, stores status, and decodes conditional operations.						



'240x legend for the internal hardware (continued)

Table 4. Legend for the '240x DSP CPU Internal Hardware (Continued)

SYMBOL	NAME	DESCRIPTION					
PREG	Product Register	32-bit register holds results of 16 × 16 multiply					
PSCALE	Product-Scaling Shifter	0-, 1-, or 4-bit left shift, or 6-bit right shift of multiplier product. The left-shift options are used to manage the additional sign bits resulting from the 2s-complement multiply. The right-shift option is used to scale down the number to manage overflow of product accumulation in the CALU. PSCALE resides in the path from the 32-bit product shifter and from either the CALU or the data-write data bus (DWEB), and requires no cycle overhead.					
STACK	Stack	STACK is a block of memory used for storing return addresses for subroutines and interrupt-service routines, or for storing data. The 'C2xx stack is 16-bit wide and eight-level deep.					
TREG	Temporary Register	16-bit register holds one of the operands for the multiply operations. TREG holds the dynamic shift count for the LACT, ADDT, and SUBT instructions. TREG holds the dynamic bit position for the BITT instruction.					

status and control registers

Two status registers, ST0 and ST1, contain the status of various conditions and modes. These registers can be stored into data memory and loaded from data memory, thus allowing the status of the machine to be saved and restored for subroutines.

The load status register (LST) instruction is used to write to ST0 and ST1. The store status register (SST) instruction is used to read from ST0 and ST1 — except for the INTM bit, which is not affected by the LST instruction. The individual bits of these registers can be set or cleared when using the SETC and CLRC instructions. Figure 8 shows the organization of status registers ST0 and ST1, indicating all status bits contained in each. Several bits in the status registers are reserved and are read as logic 1s. Table 5 lists status register field definitions.

	15		13	12	11	10	9	8								0
ST0		ARP		ov	OVM	1	INTM					DP				
	15		13	12	11	10	9	8	7	6	5	4	3	2	1	0
ST1		ARB		CNF	TC	SXM	С	1	1	1	1	XF	1	1		PM

Figure 8. Organization of Status Registers ST0 and ST1

Table 5. Status Register Field Definitions

FIELD	FUNCTION
ARB	Auxiliary register pointer buffer. When the ARP is loaded into ST0, the old ARP value is copied to the ARB except during an LST instruction. When the ARB is loaded by way of an LST #1 instruction, the same value is also copied to the ARP.
ARP	Auxiliary register (AR) pointer. ARP selects the AR to be used in indirect addressing. When the ARP is loaded, the old ARP value is copied to the ARB register. ARP can be modified by memory-reference instructions when using indirect addressing, and by the LARP, MAR, and LST instructions. The ARP is also loaded with the same value as ARB when an LST #1 instruction is executed.
С	Carry bit. C is set to 1 if the result of an addition generates a carry, or reset to 0 if the result of a subtraction generates a borrow. Otherwise, C is reset after an addition or set after a subtraction, except if the instruction is ADD or SUB with a 16-bit shift. In these cases, ADD can only set and SUB can only reset the carry bit, but cannot affect it otherwise. The single-bit shift and rotate instructions also affect C, as well as the SETC, CLRC, and LST #1 instructions. Branch instructions have been provided to branch on the status of C. C is set to 1 on a reset.
CNF	On-chip RAM configuration control bit. If CNF is set to 0, the reconfigurable data dual-access RAM blocks are mapped to data space; otherwise, they are mapped to program space. The CNF can be modified by the SETC CNF, CLRC CNF, and LST #1 instructions. RS sets the CNF to 0.

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status and control registers (continued)

Table 5. Status Register Field Definitions (Continued)

FIELD	FUNCTION
DP	Data memory page pointer. The 9-bit DP register is concatenated with the seven LSBs of an instruction word to form a direct memory address of 16 bits. DP can be modified by the LST and LDP instructions.
INTM	Interrupt mode bit. When INTM is set to 0, all unmasked interrupts are enabled. When set to 1, all maskable interrupts are disabled. INTM is set and reset by the SETC INTM and CLRC INTM instructions. RS also sets INTM. INTM has no effect on the unmaskable RS and NMI interrupts. Note that INTM is unaffected by the LST instruction. This bit is set to 1 by reset. It is also set to 1 when a maskable interrupt trap is taken.
OV	Overflow flag bit. As a latched overflow signal, OV is set to 1 when overflow occurs in the arithmetic logic unit (ALU). Once an overflow occurs, the OV remains set until a reset, BCND/D on OV/NOV, or LST instruction clears OV.
OVM	Overflow mode bit. When OVM is set to 0, overflowed results overflow normally in the accumulator. When set to 1, the accumulator is set to either its most positive or negative value upon encountering an overflow. The SETC and CLRC instructions set and reset this bit, respectively. LST can also be used to modify the OVM.
РМ	Product shift mode. If these two bits are 00, the multiplier's 32-bit product is loaded into the ALU with no shift. If PM = 01, the PREG output is left-shifted one place and loaded into the ALU, with the LSB zero-filled. If PM = 10, the PREG output is left-shifted by four bits and loaded into the ALU, with the LSBs zero-filled. PM = 11 produces a right shift of six bits, sign-extended. Note that the PREG contents remain unchanged. The shift takes place when transferring the contents of the PREG to the ALU. PM is loaded by the SPM and LST #1 instructions. PM is cleared by RS.
SXM	Sign-extension mode bit. SXM = 1 produces sign extension on data as it is passed into the accumulator through the scaling shifter. SXM = 0 suppresses sign extension. SXM does not affect the definitions of certain instructions; for example, the ADDS instruction suppresses sign extension regardless of SXM. SXM is set by the SETC SXM instruction and reset by the CLRC SXM instruction and can be loaded by the LST #1 instruction. SXM is set to 1 by reset.
TC	Test/control flag bit. TC is affected by the BIT, BITT, CMPR, LST #1, and NORM instructions. TC is set to a 1 if a bit tested by BIT or BITT is a 1, if a compare condition tested by CMPR exists between AR (ARP) and ARO, if the exclusive-OR function of the two most significant bits (MSBs) of the accumulator is true when tested by a NORM instruction. The conditional branch, call, and return instructions can execute based on the condition of TC.
XF	XF pin status bit. XF indicates the state of the XF pin, a general-purpose output pin. XF is set by the SETC XF instruction and reset by the CLRC XF instruction. XF is set to 1 by reset.

central processing unit

The TMS320x240x central processing unit (CPU) contains a 16-bit scaling shifter, a 16 x 16-bit parallel multiplier, a 32-bit central arithmetic logic unit (CALU), a 32-bit accumulator, and additional shifters at the outputs of both the accumulator and the multiplier. This section describes the CPU components and their functions. The functional block diagram shows the components of the CPU.

input scaling shifter

The TMS320x240x provides a scaling shifter with a 16-bit input connected to the data bus and a 32-bit output connected to the CALU. This shifter operates as part of the path of data coming from program or data space to the CALU and requires no cycle overhead. It is used to align the 16-bit data coming from memory to the 32-bit CALU. This is necessary for scaling arithmetic as well as aligning masks for logical operations.

The scaling shifter produces a left shift of 0 to 16 on the input data. The LSBs of the output are filled with zeros; the MSBs can either be filled with zeros or sign-extended, depending upon the value of the SXM bit (sign-extension mode) of status register ST1. The shift count is specified by a constant embedded in the instruction word or by a value in TREG. The shift count in the instruction allows for specific scaling or alignment operations specific to that point in the code. The TREG base shift allows the scaling factor to be adaptable to the system's performance.



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multiplier

The TMS320x240x devices use a 16 x 16-bit hardware multiplier that is capable of computing a signed or an unsigned 32-bit product in a single machine cycle. All multiply instructions, except the MPYU (multiply unsigned) instruction, perform a signed multiply operation. That is, two numbers being multiplied are treated as 2s-complement numbers, and the result is a 32-bit 2s-complement number. There are two registers associated with the multiplier, as follow:

- 16-bit temporary register (TREG) that holds one of the operands for the multiplier
- 32-bit product register (PREG) that holds the product

Four product-shift modes (PM) are available at the PREG output (PSCALE). These shift modes are useful for performing multiply/accumulate operations, performing fractional arithmetic, or justifying fractional products. The PM field of status register ST1 specifies the PM shift mode, as shown in Table 6.

PM	SHIFT	DESCRIPTION
00	No shift	Product feed to CALU or data bus with no shift
01	Left 1	Removes the extra sign bit generated in a 2s-complement multiply to produce a Q31 product
10	Left 4	Removes the extra 4 sign bits generated in a 16x13 2s-complement multiply to a produce a Q31 product when using the multiply-by-a-13-bit constant
11	Right 6	Scales the product to allow up to 128 product accumulation without the possibility of accumulator overflow

Table 6. PSCALE Product-Shift Modes

The product can be shifted one bit to compensate for the extra sign bit gained in multiplying two 16-bit 2s-complement numbers (MPY instruction). A four-bit shift is used in conjunction with the MPY instruction with a short immediate value (13 bits or less) to eliminate the four extra sign bits gained in multiplying a 16-bit number by a 13-bit number. Finally, the output of PREG can be right-shifted 6 bits to enable the execution of up to 128 consecutive multiply/accumulates without the possibility of overflow.

The LT (load TREG) instruction normally loads TREG to provide one operand (from the data bus), and the MPY (multiply) instruction provides the second operand (also from the data bus). A multiplication also can be performed with a 13-bit immediate operand when using the MPY instruction. Then, a product is obtained every two cycles. When the code is executing multiple multiplies and product sums, the CPU supports the pipelining of the TREG load operations with CALU operations using the previous product. The pipeline operations that run in parallel with loading the TREG include: load ACC with PREG (LTP); add PREG to ACC (LTA); add PREG to ACC and shift TREG input data (DMOV) to next address in data memory (LTD); and subtract PREG from ACC (LTS).

Two multiply/accumulate instructions (MAC and MACD) fully utilize the computational bandwidth of the multiplier, allowing both operands to be processed simultaneously. The data for these operations can be transferred to the multiplier each cycle by way of the program and data buses. This facilitates single-cycle multiply/accumulates when used with the repeat (RPT) instruction. In these instructions, the coefficient addresses are generated by program address generation (PAGEN) logic, while the data addresses are generated by data address generation (DAGEN) logic. This allows the repeated instruction to access the values from the coefficient table sequentially and step through the data in any of the indirect addressing modes.

The MACD instruction, when repeated, supports filter constructs (weighted running averages) so that as the sum-of-products is executed, the sample data is shifted in memory to make room for the next sample and to throw away the oldest sample.

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multiplier (continued)

The MPYU instruction performs an unsigned multiplication, which greatly facilitates extended-precision arithmetic operations. The unsigned contents of TREG are multiplied by the unsigned contents of the addressed data memory location, with the result placed in PREG. This process allows the operands of greater than 16 bits to be broken down into 16-bit words and processed separately to generate products of greater than 32 bits. The SQRA (square/add) and SQRS (square/subtract) instructions pass the same value to both inputs of the multiplier for squaring a data memory value.

After the multiplication of two 16-bit numbers, the 32-bit product is loaded into the 32-bit product register (PREG). The product from PREG can be transferred to the CALU or to data memory by way of the SPH (store product high) and SPL (store product low) instructions. Note: the transfer of PREG to either the CALU or data bus passes through the PSCALE shifter, and therefore is affected by the product shift mode defined by PM. This is important when saving PREG in an interrupt-service-routine context save as the PSCALE shift effects cannot be modeled in the restore operation. PREG can be cleared by executing the MPY #0 instruction. The product register can be restored by loading the saved low half into TREG and executing a MPY #1 instruction. The high half, then, is loaded using the LPH instruction.

central arithmetic logic unit

The TMS320x240x central arithmetic logic unit (CALU) implements a wide range of arithmetic and logical functions, the majority of which execute in a single clock cycle. This ALU is referred to as central to differentiate it from a second ALU used for indirect-address generation called the auxiliary register arithmetic unit (ARAU). Once an operation is performed in the CALU, the result is transferred to the accumulator (ACC) where additional operations, such as shifting, can occur. Data that is input to the CALU can be scaled by ISCALE when coming from one of the data buses (DRDB or PRDB) or scaled by PSCALE when coming from the multiplier.

The CALU is a general-purpose ALU that operates on 16-bit words taken from data memory or derived from immediate instructions. In addition to the usual arithmetic instructions, the CALU can perform Boolean operations, facilitating the bit-manipulation ability required for a high-speed controller. One input to the CALU is always provided from the accumulator, and the other input can be provided from the product register (PREG) of the multiplier or the output of the scaling shifter (that has been read from data memory or from the ACC). After the CALU has performed the arithmetic or logical operation, the result is stored in the accumulator.

The TMS320x240x devices support floating-point operations for applications requiring a large dynamic range. The NORM (normalization) instruction is used to normalize fixed-point numbers contained in the accumulator by performing left shifts. The four bits of the TREG define a variable shift through the scaling shifter for the LACT/ADDT/SUBT (load/add to /subtract from accumulator with shift specified by TREG) instructions. These instructions are useful in floating-point arithmetic where a number needs to be denormalized — that is, floating-point to fixed-point conversion. They are also useful in the execution of an automatic gain control (AGC) going into a filter. The BITT (bit test) instruction provides testing of a single bit of a word in data memory based on the value contained in the four LSBs of TREG.

The CALU overflow saturation mode can be enabled/disabled by setting/resetting the OVM bit of ST0. When the CALU is in the overflow saturation mode and an overflow occurs, the overflow flag is set and the accumulator is loaded with either the most positive or the most negative value representable in the accumulator, depending on the direction of the overflow. The value of the accumulator at saturation is 07FFFFFFh (positive) or 08000000h (negative). If the OVM (overflow mode) status register bit is reset and an overflow occurs, the overflowed results are loaded into the accumulator with modification. (Note that logical operations cannot result in overflow.)

The CALU can execute a variety of branch instructions that depend on the status of the CALU and the accumulator. These instructions can be executed conditionally based on any meaningful combination of these status bits. For overflow management, these conditions include OV (branch on overflow) and EQ (branch on accumulator equal to zero). In addition, the BACC (branch to address in accumulator) instruction provides the ability to branch to an address specified by the accumulator (computed goto). Bit test instructions (BIT and BITT), which do not affect the accumulator, allow the testing of a specified bit of a word in data memory.



central arithmetic logic unit (continued)

The CALU also has an associated carry bit that is set or reset depending on various operations within the device. The carry bit allows more efficient computation of extended-precision products and additions or subtractions. It is also useful in overflow management. The carry bit is affected by most arithmetic instructions as well as the single-bit shift and rotate instructions. It is not affected by loading the accumulator, logical operations, or other such non-arithmetic or control instructions.

The ADDC (add to accumulator with carry) and SUBB (subtract from accumulator with borrow) instructions use the previous value of carry in their addition/subtraction operation.

The one exception to the operation of the carry bit is in the use of ADD with a shift count of 16 (add to high accumulator) and SUB with a shift count of 16 (subtract from high accumulator) instructions. This case of the ADD instruction can set the carry bit only if a carry is generated, and this case of the SUB instruction can reset the carry bit only if a borrow is generated; otherwise, neither instruction affects it.

Two conditional operands, C and NC, are provided for branching, calling, returning, and conditionally executing, based upon the status of the carry bit. The SETC, CLRC, and LST #1 instructions also can be used to load the carry bit. The carry bit is set to one on a hardware reset.

accumulator

The 32-bit accumulator is the registered output of the CALU. It can be split into two 16-bit segments for storage in data memory. Shifters at the output of the accumulator provide a left shift of 0 to 7 places. This shift is performed while the data is being transferred to the data bus for storage. The contents of the accumulator remain unchanged. When the postscaling shifter is used on the high word of the accumulator (bits 16–31), the MSBs are lost and the LSBs are filled with bits shifted in from the low word (bits 0–15). When the postscaling shifter is used on the low word, the LSBs are zero-filled.

The SFL and SFR (in-place one-bit shift to the left/right) instructions and the ROL and ROR (rotate to the left/right) instructions implement shifting or rotating of the contents of the accumulator through the carry bit. The SXM bit affects the definition of the SFR (shift accumulator right) instruction. When SXM = 1, SFR performs an arithmetic right shift, maintaining the sign of the accumulator data. When SXM = 0, SFR performs a logical shift, shifting out the LSBs and shifting in a zero for the MSB. The SFL (shift accumulator left) instruction is not affected by the SXM bit and behaves the same in both cases, shifting out the MSB and shifting in a zero. Repeat (RPT) instructions can be used with the shift and rotate instructions for multiple-bit shifts.

auxiliary registers and auxiliary-register arithmetic unit (ARAU)

The '240x provides a register file containing eight auxiliary registers (AR0-AR7). The auxiliary registers are used for indirect addressing of the data memory or for temporary data storage. Indirect auxiliary-register addressing allows placement of the data memory address of an instruction operand into one of the auxiliary registers. These registers are referenced with a 3-bit auxiliary register pointer (ARP) that is loaded with a value from 0 through 7, designating AR0 through AR7, respectively. The auxiliary registers and the ARP can be loaded from data memory, the ACC, the product register, or by an immediate operand defined in the instruction. The contents of these registers also can be stored in data memory or used as inputs to the CALU.

The auxiliary register file (AR0–AR7) is connected to the ARAU. The ARAU can autoindex the current auxiliary register while the data memory location is being addressed. Indexing either by ± 1 or by the contents of the AR0 register can be performed. As a result, accessing tables of information does not require the CALU for address manipulation; therefore, the CALU is free for other operations in parallel.

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internal memory

The TMS320x240x devices are configured with the following memory modules:

- Dual-access random-access memory (DARAM)
- Single-access random-access memory (SARAM)
- Flash
- ROM
- Boot ROM

dual-access RAM (DARAM)

There are 544 words × 16 bits of DARAM on the '240x devices. The '240x DARAM allows writes to and reads from the RAM in the same cycle. The DARAM is configured in three blocks: block 0 (B0), block 1 (B1), and block 2 (B2). Block 1 contains 256 words and Block 2 contains 32 words, and both blocks are located only in data memory space. Block 0 contains 256 words, and can be configured to reside in either data or program memory space. The SETC CNF (configure B0 as data memory) and CLRC CNF (configure B0 as program memory) instructions allow dynamic configuration of the memory maps through software.

When using on-chip RAM or high-speed external memory, the '240x runs at full speed with no wait states. The ability of the DARAM to allow two accesses to be performed in one cycle, coupled with the parallel nature of the '240x architecture, enables the device to perform three concurrent memory accesses in any given machine cycle. Externally, the READY line or on-chip software wait-state generator can be used to interface the '240x to slower, less expensive external memory. Downloading programs from slow off-chip memory to on-chip RAM can speed processing while cutting system costs.

single-access RAM (SARAM)

There are 2K words × 16 bits of SARAM on some of the '240x devices.† The '240x SARAM allows writes to and reads from the RAM in the same cycle. The PON and DON bits select SARAM (2K) mapping in program space, data space, or both. See Table 18 for details on the SCSR2 register and the PON and DON bits. At reset, these bits are 11, and the on-chip SARAM is mapped in both the program and data spaces. The SARAM addresses (8000h in program memory and 0800h in data memory) are accessible in external memory space, if the on-chip SARAM is not enabled.

flash EEPROM

Flash EEPROM provides an attractive alternative to masked program ROM. Like ROM, flash is nonvolatile. However, it has the advantage of "in-target" reprogrammability. The 'LF240x incorporates one 32K \times 16-bit flash EEPROM module in program space. This type of memory expands the capabilities of the 'LF240x in the areas of prototyping, early field-testing, and single-chip applications. The flash module has multiple sectors that can be individually protected while erasing or programming. The sector size is non-uniform and partitioned as 4K/12K/12K/4K sectors.

Unlike most discrete flash memory, the 'LF240x flash does not require a dedicated state machine, because the algorithms for programming and erasing the flash are executed by the DSP core. This enables several advantages, including: reduced chip size and sophisticated, adaptive algorithms. For production programming, the IEEE Standard 1149.1 ‡ (JTAG) scan port provides easy access to the on-chip RAM for downloading the algorithms and flash code. This flash requires 5 V for programming (at V_{CCP} pin only) the array. The flash runs at zero wait state while the device is powered at 3.3 V.

FIEEE Standard 1149.1–1990, IEEE Standard Test Access Port.



[†] See Table 1 for device-specific features.

ADVANCE INFORMATION

The 'LC240x devices contain mask-programmable ROM located in program memory space. Customers can arrange to have this ROM programmed with contents unique to any particular application. See Table 1 for the ROM memory capacity of each 'LC240x device.

boot ROM

ROM

Boot ROM is a 256-word ROM memory mapped in program space 0000–00FF. This ROM will be enabled if the BOOTEN pin is low during reset. The BOOT_EN bit (bit 3 of the SCSR2 register) will be set to 1 if the BOOTEN pin is low at reset. Boot ROM can also be enabled by writing 1 to the SCSR2.3 bit and disabled by writing 0 to this bit.

The boot ROM has a generic bootloader to transfer code through SCI or SPI ports. The incoming code should disable the BOOT_ROM bit by writing 0 to bit 3 of the SCSR2 register, or else, the whole flash array will not be enabled.

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PERIPHERALS

The integrated peripherals of the TMS320x240x are described in the following subsections:

- Two event-manager modules (EVA, EVB)
- Enhanced analog-to-digital converter (ADC) module
- Controller area network (CAN) module
- Serial communications interface (SCI) module
- Serial peripheral interface (SPI) module
- PLL-based clock module
- Digital I/O and shared pin functions
- External memory interfaces ('LF2407 only)
- Watchdog (WD) timer module

event manager modules (EVA, EVB)

The event-manager modules include general-purpose (GP) timers, full-compare/PWM units, capture units, and quadrature-encoder pulse (QEP) circuits. EVA's and EVB's timers, compare units, and capture units function identically. However, timer/unit names differ for EVA and EVB. Table 7 shows the module and signal names used. Table 7 shows the features and functionality available for the event-manager modules and highlights EVA nomenclature.

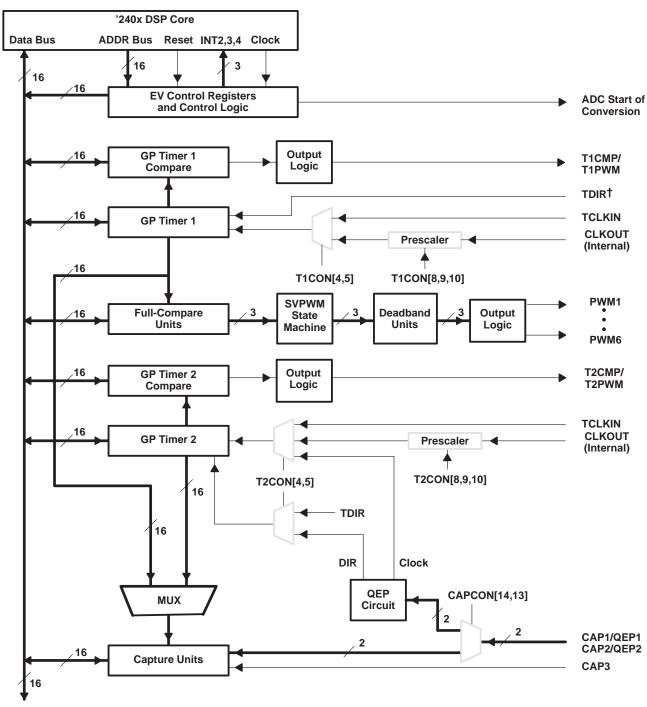
Event managers A and B have identical peripheral register sets with EVA starting at 7400h and EVB starting at 7500h. The paragraphs in this section describe the function of GP timers, compare units, capture units, and QEPs using EVA nomenclature. These paragraphs are applicable to EVB with regard to function—however, module/signal names would differ.

Table 7. Module and Signal Names for EVA and EVB

EVENT MANAGER MODULES	EVA MODULE	SIGNAL	EVB MODULE	SIGNAL	
GP Timers	Timer 1	T1PWM/T1CMP	Timer 3	T3PWM/T3CMP	
	Timer 2	T2PWM/T2CMP	Timer 4	T4PWM/T4CMP	
Compare Units	Compare 1	PWM1/2	Compare 4	PWM7/8	
	Compare 2	PWM3/4	Compare 5	PWM9/10	
	Compare 3	PWM5/6	Compare 6	PWM11/12	
Capture Units	Capture 1	CAP1	Capture 4	CAP4	
	Capture 2	CAP2	Capture 5	CAP5	
	Capture 3	CAP3	Capture 6	CAP6	
QEP	QEP1	QEP1	QEP3	QEP3	
	QEP2	QEP2	QEP4	QEP4	
External Inputs	Direction	TDIRA	Direction	TDIRB	
	External Clock	TCLKINA	External Clock	TCLKINB	



event-manager modules (EVA, EVB) (continued)



† '2402 devices do not support external direction control. TDIR is not available.

Figure 9. Event-Manager Block Diagram

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general-purpose (GP) timers

There are two GP timers: The GP timer x (x = 1 or 2 for EVA; x = 3 or 4 for EVB) includes:

- A 16-bit timer, up-/down-counter, TxCNT, for reads or writes
- A 16-bit timer-compare register, TxCMPR (double-buffered with shadow register), for reads or writes
- A 16-bit timer-period register, TxPR (double-buffered with shadow register), for reads or writes
- A 16-bit timer-control register, TxCON, for reads or writes
- Selectable internal or external input clocks
- A programmable prescaler for internal or external clock inputs
- Control and interrupt logic, for four maskable interrupts: underflow, overflow, timer compare, and period interrupts
- A selectable direction input pin (TDIR) (to count up or down when directional up-/down-count mode is selected)

The GP timers can be operated independently or synchronized with each other. The compare register associated with each GP timer can be used for compare function and PWM-waveform generation. There are three continuous modes of operations for each GP timer in up- or up/down-counting operations. Internal or external input clocks with programmable prescaler are used for each GP timer. GP timers also provide the time base for the other event-manager submodules: GP timer 1 for all the compares and PWM circuits, GP timer 2/1 for the capture units and the quadrature-pulse counting operations. Double-buffering of the period and compare registers allows programmable change of the timer (PWM) period and the compare/PWM pulse width as needed.

full-compare units

There are three full-compare units on each event manager. These compare units use GP timer1 as the time base and generate six outputs for compare and PWM-waveform generation using programmable deadband circuit. The state of each of the six outputs is configured independently. The compare registers of the compare units are double-buffered, allowing programmable change of the compare/PWM pulse widths as needed.

programmable deadband generator

The deadband generator circuit includes three 8-bit counters and an 8-bit compare register. Desired deadband values (from 0 to $24\,\mu s$) can be programmed into the compare register for the outputs of the three compare units. The deadband generation can be enabled/disabled for each compare unit output individually. The deadband-generator circuit produces two outputs (with or without deadband zone) for each compare unit output signal. The output states of the deadband generator are configurable and changeable as needed by way of the double-buffered ACTR register.

PWM waveform generation

Up to eight PWM waveforms (outputs) can be generated simultaneously by each event manager: three independent pairs (six outputs) by the three full-compare units with *programmable deadbands*, and two independent PWMs by the GP-timer compares.



PWM characteristics

Characteristics of the PWMs are as follows:

- 16-bit registers
- Programmable deadband for the PWM output pairs, from 0 to 24 μs
- Minimum deadband width of 50 ns
- Change of the PWM carrier frequency for PWM frequency wobbling as needed
- Change of the PWM pulse widths within and after each PWM period as needed
- External-maskable power and drive-protection interrupts
- Pulse-pattern-generator circuit, for programmable generation of asymmetric, symmetric, and four-space vector PWM waveforms
- Minimized CPU overhead using auto-reload of the compare and period registers

capture unit

The capture unit provides a logging function for different events or transitions. The values of the GP timer 2 counter are captured and stored in the two-level-deep FIFO stacks when selected transitions are detected on capture input pins, CAPx (x = 1, 2, or 3 for EVA; and x = 4, 5, or 6 for EVB). The capture unit consists of three capture circuits.

- Capture units include the following features:
 - One 16-bit capture control register, CAPCON (R/W)
 - One 16-bit capture FIFO status register, CAPFIFO (eight MSBs are read-only, eight LSBs are write-only)
 - Selection of GP timer 2 as the time base
 - Three 16-bit 2-level-deep FIFO stacks, one for each capture unit
 - Three Schmitt-triggered capture input pins (CAP1, CAP2, and CAP3)—one input pin per capture unit.
 [All inputs are synchronized with the device (CPU) clock. In order for a transition to be captured, the input must hold at its current level to meet two rising edges of the device clock. The input pins CAP1 and CAP2 can also be used as QEP inputs to the QEP circuit.]
 - User-specified transition (rising edge, falling edge, or both edges) detection
 - Three maskable interrupt flags, one for each capture unit

quadrature-encoder pulse (QEP) circuit

Two capture inputs (CAP1 and CAP2 for EVA; CAP4 and CAP5 for EVB) can be used to interface the on-chip QEP circuit with a quadrature encoder pulse. Full synchronization of these inputs is performed on-chip. Direction or leading-quadrature pulse sequence is detected, and GP timer 2 is incremented or decremented by the rising and falling edges of the two input signals (four times the frequency of either input pulse).

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enhanced analog-to-digital converter (ADC) module

A simplified functional block diagram of the ADC module is shown in Figure 10. The ADC module consists of a 10-bit ADC with a built-in sample-and-hold (S/H) circuit. Functions of the ADC module include:

- 10-bit ADC core with built-in S/H
- Fast conversion time (S/H + Conversion) of 500 ns
- 16-channel, muxed inputs
- Autosequencing capability provides up to 16 "autoconversions" in a single session. Each conversion can be programmed to select any 1 of 16 input channels
- Sequencer can be operated as two independent 8-state sequencers or as one large 16-state sequencer
 (i.e., two cascaded 8-state sequencers)
- Sixteen result registers (individually addressable) to store conversion values
- Multiple triggers as sources for the start-of-conversion (SOC) sequence
 - S/W software immediate start
 - EVA Event manager A (multiple event sources within EVA)
 - EVB Event manager B (multiple event sources within EVB)
 - Ext External pin (ADCSOC)
- Flexible interrupt control allows interrupt request on every end of sequence (EOS) or every other EOS
- Sequencer can operate in "start/stop" mode, allowing multiple "time-sequenced triggers" to synchronize conversions
- EVA and EVB triggers can operate independently in dual-sequencer mode
- Sample-and-hold (S/H) acquisition time window has separate prescale control
- Built-in calibration mode
- Built-in self-test mode

The ADC module in the '240x has been enhanced to provide flexible interface to event managers A and B. The ADC interface is built around a fast, 10-bit ADC module with total conversion time of 500 ns (S/H + conversion). The ADC module has 16 channels, configurable as two independent 8-channel modules to service event managers A and B. The two independent 8-channel modules can be cascaded to form a 16-channel module. Figure 10 shows the block diagram of the '240x ADC module.

The two 8-channel modules have the capability to autosequence a series of conversions, each module has the choice of selecting any one of the respective eight channels available through an analog mux. In the cascaded mode, the autosequencer functions as a single 16-channel sequencer. On each sequencer, once the conversion is complete, the selected channel value is stored in its respective RESULT register. Autosequencing allows the system to convert the same channel multiple times, allowing the user to perform oversampling algorithms. This gives increased resolution over traditional single-sampled conversion results.



enhanced analog-to-digital converter (ADC) module (continued)

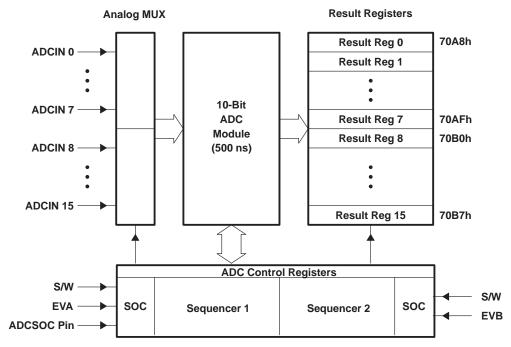


Figure 10. Block Diagram of the '240x ADC Module

controller area network (CAN) module

The CAN module is a full-CAN controller designed as a 16-bit peripheral module and supports the following features:

- CAN specification 2.0B (active)
 - Standard data and remote frames
 - Extended data and remote frames
- Six mailboxes for objects of 0- to 8-byte data length
 - Two receive mailboxes, two transmit mailboxes
 - Two configurable transmit/receive mailboxes
- Local acceptance mask registers for mailboxes 0 and 1 and mailboxes 2 and 3
 - Configurable standard or extended message identifier
- Programmable global mask registers for objects 1 and 2 and one for object 3 and 4
 - Configurable standard or extended message identifier
- Programmable bit rate
- Programmable interrupt scheme
- Readable error counters
- Self-test mode

In this mode, the CAN module operates in a loop-back fashion, receiving its own transmitted message.



controller area network (CAN) module (continued)

The CAN module is a 16-bit peripheral. The accesses are split into the control/status-registers accesses and the mailbox-RAM accesses.

CAN peripheral registers: The CPU can access the CAN peripheral registers only using 16-bit write accesses. The CAN peripheral always presents full 16-bit data to the CPU bus during read cycles.

CAN controller architecture

Figure 11 shows the basic architecture of the CAN controller through this block diagram of the CAN Peripherals.

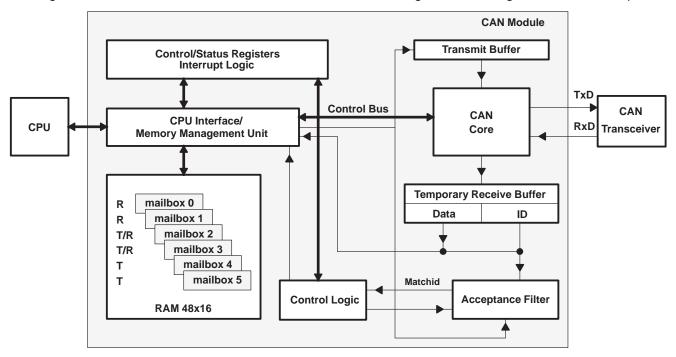


Figure 11. CAN Module Block Diagram

The mailboxes are situated in one 48-word x 16-bit RAM. It can be written to or read by the CPU or the CAN. The CAN write or read access, as well as the CPU read access, needs one clock cycle. The CPU write access needs two clock cycles. In these two clock cycles, the CAN performs a read-modify-write cycle and, therefore, inserts one wait state for the CPU.

Address bit 0 of the address bus used when accessing the RAM decides if the lower (0) or the higher (1) 16-bit word of the 32-bit word is taken. The RAM location is determined by the upper bits 5 to 1 of the address bus

Table 9 shows the mailbox locations in RAM. One half-word has 16 bits.

CAN interrupt logic

There are two interrupt requests from the CAN module to the peripheral interrupt expansion (PIE) controller: the mailbox interrupt and the error interrupt. Both interrupts can assert either a high-priority request or a low-priority request to the CPU. Since CAN mailboxes can generate multiple interrupts, the software should read the CAN_IFR register for every interrupt and prioritize the interrupt service, or else, these multiple interrupts will not be recognized by the CPU and PIE hardware logic. Each interrupt routine should service all the interrupt bits that are set and clear them after service.



CAN memory map

Table 8 and Table 9 show the register and mailbox locations in the CAN module.

Table 8. Register Addresses†

ADDRESS OFFSET	NAME	DESCRIPTION
00h	MDER	Mailbox Direction/Enable Register (bits 7 to 0)
01h	TCR	Transmission Control Register (bits 15 to 0)
02h	RCR	Receive Control Register (bits 15 to 0)
03h	MCR	Master Control Register (bits 13 to 6, 1, 0)
04h	BCR2	Bit Configuration Register 2 (bits 7 to 0)
05h	BCR1	Bit Configuration Register 1 (bits 10 to 0)
06h	ESR	Error Status Register (bits 8 to 0)
07h	GSR	Global Status Register (bits 5 to 0)
08h	CEC	Transmit and Receive Error Counters (bits 15 to 0)
09h	CAN_IFR	Interrupt Flag Register (bits 13 to 8, 6 to 0)
0Ah	CAN_IMR	Interrupt Mask Register (bits 15, 13 to 0)
0Bh	LAM0_H	Local Acceptance Mask Mailbox 0 and 1 (bits 31, 28 to 16)
0Ch	LAM0_L	Local Acceptance Mask Mailbox 0 and 1 (bits 15 to 0)
0Dh	LAM1_H	Local Acceptance Mask Mailbox 2 and 3 (bits 31, 28 to 16)
0Eh	LAM1_L	Local Acceptance Mask Mailbox 2 and 3 (bits 15 to 0)
0Fh	Reserved	Accesses assert the CAADDRx signal from the CAN peripheral (which asserts an Illegal Address error)

[†] All unimplemented register bits are read as zero, writes have no effect. Register bits are initialized to zero, unless otherwise stated in the definition.

Table 9. Mailbox Addresses‡

ADDRESS OFFSET [5:0]	NAME	DESCRIPTION UPPER HALF-WORD ADDRESS BIT 0 = 1	DESCRIPTION LOWER HALF-WORD ADDRESS BIT 0 = 0
00h	MSGID0	Message ID for mailbox 0	Message ID for mailbox 0
02h	MSGCTRL0	Unused	RTR and DLC (bits 4 to 0)
0.41	D	Databyte 0, Databyte 1 (DBO = 1)	Databyte 2, Databyte 3 (DBO = 1)
04h	Datalow0	Databyte 3, Databyte 2 (DBO = 0)	Databyte 1, Databyte 0 (DBO = 0)
001	Databiaho	Databyte 4, Databyte 5 (DBO = 1)	Databyte 6, Databyte 7 (DBO = 1)
06h	Datahigh0	Databyte 7, Databyte 6 (DBO = 0)	Databyte 5, Databyte 4 (DBO = 0)
08h	MSGID1	Message ID for mailbox 1	Message ID for mailbox 1
0Ah	MSGCTRL1	Unused	RTR and DLC (bits 4 to 0)
201	5.1.4	Databyte 0, Databyte 1 (DBO = 1)	Databyte 2, Databyte 3 (DBO = 1)
0Ch	Datalow1	Databyte 3, Databyte 2 (DBO = 0)	Databyte 1, Databyte 0 (DBO = 0)
0Eh	Datahigh1	Databyte 4, Databyte 5 (DBO = 1)	Databyte 6, Databyte 7 (DBO = 1)
28h	MSGID5	Message ID for mailbox 5	Message ID for mailbox 5
2Ah	MSGCTRL5	Unused	RTR and DLC (bits 4 to 0)
001	Datalaus	Databyte 0, Databyte 1 (DBO = 1)	Databyte 2, Databyte 3 (DBO = 1)
2Ch Datalow5		Databyte 3, Databyte 2 (DBO = 0)	Databyte 3, Databyte 2 (DBO = 0)
2Eh	Dotobiah5	Databyte 4, Databyte 5 (DBO = 1)	Databyte 6, Databyte 7 (DBO = 1)
ZEN	Datahigh5	Databyte 7, Databyte 6 (DBO = 0)	Databyte 5, Databyte 4 (DBO = 0)

[‡] The DBO (data byte order) bit is located in the MCR register and is used to define the order in which the data bytes are stored in the mailbox when received and the order in which the data bytes are transmitted. Byte 0 is the first byte in the message and Byte 7 is the last one shown in the CAN message.



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serial communications interface (SCI) module

The '240x devices include a serial communications interface (SCI) module. The SCI module supports digital communications between the CPU and other asynchronous peripherals that use the standard non-return-to-zero (NRZ) format. The SCI receiver and transmitter are double-buffered, and each has its own separate enable and interrupt bits. Both can be operated independently or simultaneously in the full-duplex mode. To ensure data integrity, the SCI checks received data for break detection, parity, overrun, and framing errors. The bit rate is programmable to over 65000 different speeds through a 16-bit baud-select register. Features of the SCI module include:

- Two external pins:
 - SCITXD: SCI transmit-output pin
 - SCIRXD: SCI receive-input pin

NOTE: Both pins can be used as GPIO if not used for SCI.

- Baud rate programmable to 64K different rates
 - Up to 1875 Kbps at 30-MHz CPUCLK
- Data-word format
 - One start bit
 - Data-word length programmable from one to eight bits
 - Optional even/odd/no parity bit
 - One or two stop bits
- Four error-detection flags: parity, overrun, framing, and break detection
- Two wake-up multiprocessor modes: idle-line and address bit
- Half- or full-duplex operation
- Double-buffered receive and transmit functions
- Transmitter and receiver operations can be accomplished through interrupt-driven or polled algorithms with status flags.
 - Transmitter: TXRDY flag (transmitter-buffer register is ready to receive another character) and TX EMPTY flag (transmitter-shift register is empty)
 - Receiver: RXRDY flag (receiver-buffer register is ready to receive another character), BRKDT flag (break condition occurred), and RX ERROR flag (monitoring four interrupt conditions)
- Separate enable bits for transmitter and receiver interrupts (except BRKDT)
- NRZ (non-return-to-zero) format
- Ten SCI module control registers located in the control register frame beginning at address 7050h
 NOTE: All registers in this module are 8-bit registers that are connected to the 16-bit peripheral bus. When a register is accessed, the register data is in the lower byte (7-0), and the upper byte (15-8) is read as zeros. Writing to the upper byte has no effect.

Figure 12 shows the SCI module block diagram.



serial communications interface (SCI) module (continued)

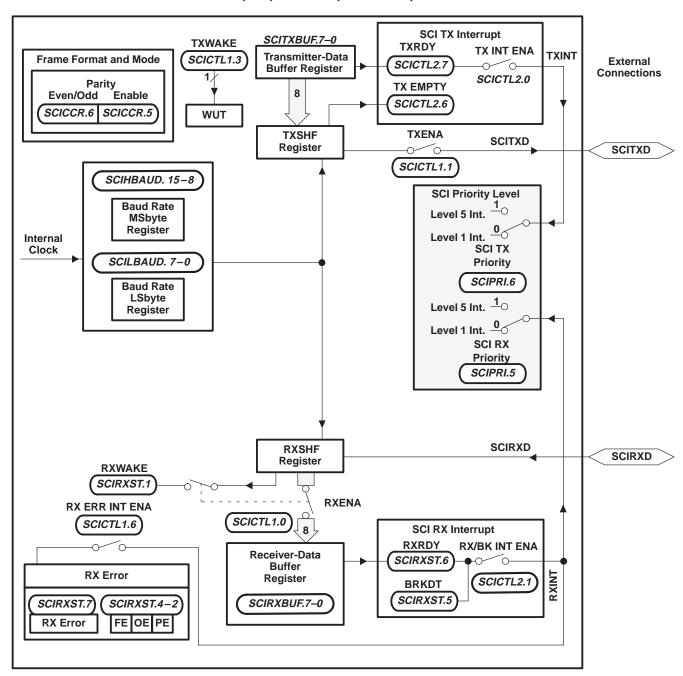


Figure 12. Serial Communications Interface (SCI) Module Block Diagram

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serial peripheral interface (SPI) module

Some '240x devices include the four-pin serial peripheral interface (SPI) module. The SPI is a high-speed, synchronous serial I/O port that allows a serial bit stream of programmed length (one to sixteen bits) to be shifted into and out of the device at a programmable bit-transfer rate. Normally, the SPI is used for communications between the DSP controller and external peripherals or another processor. Typical applications include external I/O or peripheral expansion through devices such as shift registers, display drivers, and ADCs. Multidevice communications are supported by the master/slave operation of the SPI.

The SPI module features include:

- Four external pins:
 - SPISOMI: SPI slave-output/master-input pin
 - SPISIMO: SPI slave-input/master-output pin
 - SPISTE: SPI slave transmit-enable pin
 - SPICLK: SPI serial-clock pin

NOTE: All four pins can be used as GPIO, if the SPI module is not used.

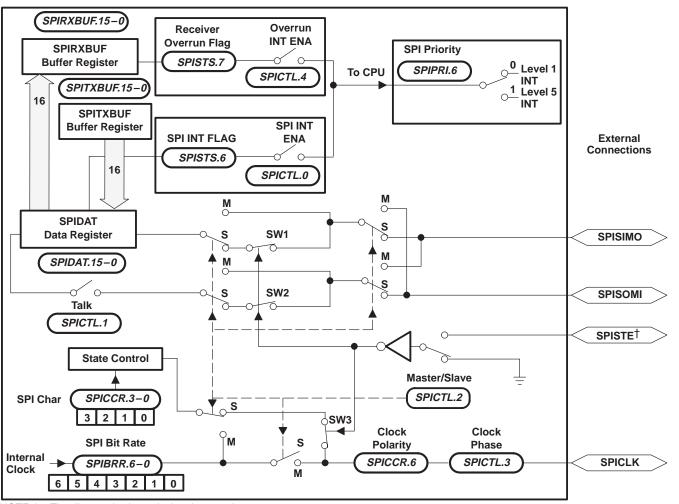
- Two operational modes: master and slave
- Baud rate: 125 different programmable rates/7.5 Mbps at 30-MHz CPUCLK
- Data word length: one to sixteen data bits
- Four clocking schemes (controlled by clock polarity and clock phase bits) include:
 - Falling edge without phase delay: SPICLK active high. SPI transmits data on the falling edge of the SPICLK signal and receives data on the rising edge of the SPICLK signal.
 - Falling edge with phase delay: SPICLK active high. SPI transmits data one half-cycle ahead of the falling edge of the SPICLK signal and receives data on the falling edge of the SPICLK signal.
 - Rising edge without phase delay: SPICLK inactive low. SPI transmits data on the rising edge of the SPICLK signal and receives data on the falling edge of the SPICLK signal.
 - Rising edge with phase delay: SPICLK inactive low. SPI transmits data one half-cycle ahead of the falling edge of the SPICLK signal and receives data on the rising edge of the SPICLK signal.
- Simultaneous receive and transmit operation (transmit function can be disabled in software)
- Transmitter and receiver operations are accomplished through either interrupt-driven or polled algorithms.
- Nine SPI module control registers: Located in control register frame beginning at address 7040h.

NOTE: All registers in this module are 16-bit registers that are connected to the 16-bit peripheral bus. When a register is accessed, the register data is in the lower byte (7-0), and the upper byte (15-8) is read as zeros. Writing to the upper byte has no effect.



serial peripheral interface (SPI) module (continued)

Figure 13 is a block diagram of the SPI in slave mode.



NOTE A: The diagram is shown in the slave mode.

Figure 13. Four-Pin Serial Peripheral Interface Module Block Diagram

[†] The SPISTE pin is shown as being disabled, meaning that data cannot be transmitted in this mode. Note that SW1, SW2, and SW3 are closed in this configuration.

PLL-based clock module

The '240x has an on-chip, PLL-based clock module. This module provides all the necessary clocking signals for the device, as well as control for low-power mode entry. The PLL has a 3-bit ratio control to select different CPU clock rates. See Figure 14 for the PLL Clock Module Block Diagram, Table 11 for the loop filter component values, and Table 10 for clock rates.

The PLL-based clock module provides two modes of operation:

- Crystal-operation
 - This mode allows the use of an external crystal/resonator to provide the time base to the device.
- External clock source operation

This mode allows the internal oscillator to be bypassed. The device clocks are generated from an external clock source input on the XTAL1/CLKIN pin. In this case, an external oscillator clock is connected to the XTAL1/CLKIN pin.

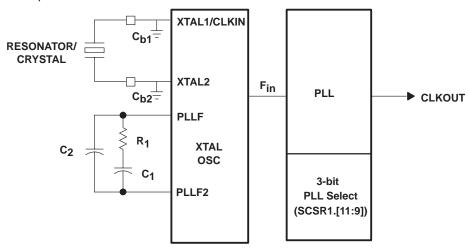


Figure 14. PLL Clock Module Block Diagram

Table 10. PLL Clock Selection Through Blts (11-9) in SCSR1 Register

CLK PS2	CLK PS1	CLK PS0	CLKOUT
0	0	0	$4 \times F_{in}$
0	0	1	$2 \times F_{in}$
0	1	0	1.33 × F _{in}
0	1	1	1×F _{in}
1	0	0	$0.8 \times F_{in}$
1	0	1	0.66 × F _{in}
1	1	0	0.57 × F _{in}
1	1	1	$0.5 \times F_{in}$

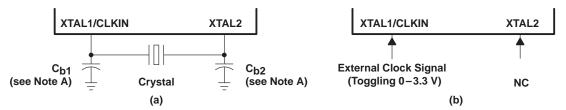
Default multiplication factor after reset is (1,1,1), i.e., $0.5 \times F_{in}$.

external reference crystal clock option

The internal oscillator is enabled by connecting a crystal across XTAL1/CLKIN and XTAL2 pins as shown in Figure 15a. The crystal should be in fundamental operation and parallel resonant, with an effective series resistance of 30Ω – 150Ω and a power dissipation of 1 mW; it should be specified at a load capacitance of 20 pF.

external reference oscillator clock option

The internal oscillator is disabled by connecting a TTL-level clock signal to XTAL1/CLKIN and leaving the XTAL2 input pin unconnected as shown in Figure 15b.



NOTE A: TI recommends that customers have the resonator/crystal vendor characterize the operation of their device with the DSP chip. The resonator/crystal vendor has the equipment and expertise to tune the tank circuit. The vendor can also advise the customer regarding the proper tank component values that will ensure start-up and stability over the entire operating range.

Figure 15. Recommended Crystal/Clock Connection

loop filter

The PLL module uses an external loop filter circuit for jitter minimization. The components for the loop filter circuit are R1, C1, and C2. The capacitors (C1 and C2) must be non-polarized. This loop filter circuit is connected between the PLLF and PLLF2 pins (see Figure 14). For examples of component values of R1, C1, and C2 at a specified oscillator frequency (XTAL1), see Table 11.

Table 11. Loop Filter Component Values With Damping Factor = 2.0

XTAL1/CLKIN FREQUENCY (MHz)	R1 (Ω)	C1 (μF)	C2 (μF)
4	4.7	3.9	0.082
5	5.6	2.7	0.056
6	6.8	1.8	0.039
7	8.2	1.5	0.033
8	9.1	1	0.022
9	10	0.82	0.015
10	11	0.68	0.015
11	12	0.56	0.012
12	13	0.47	0.01
13	15	0.39	0.0082
14	15	0.33	0.0068
15	16	0.33	0.0068
16	18	0.27	0.0056
17	18	0.22	0.0047
18	20	0.22	0.0047
19	22	0.18	0.0039
20	24	0.15	0.0033



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low-power modes

The '240x has an IDLE instruction. When executed, the IDLE instruction stops the clocks to all circuits in the CPU, but the clock output from the CPU continues to run. With this instruction, the CPU clocks can be shut down to save power while the peripherals (clocked with CLKOUT) continue to run. The CPU exits the IDLE state if it is reset, or, if it receives an interrupt request.

clock domains

All '240x-based devices have two clock domains:

- 1. CPU clock domain consists of the clock for most of the CPU logic
- 2. System clock domain consists of the peripheral clock (which is derived from CLKOUT of the CPU) and the clock for the interrupt logic in the CPU.

When the CPU goes into IDLE mode, the CPU clock domain is stopped while the system clock domain continues to run. This mode is also known as IDLE1 mode. The '240x CPU also contains support for a second IDLE mode, IDLE2. By asserting IDLE2 to the '240x CPU, both the CPU clock domain and the system clock domain are stopped, allowing further power savings. A third low-power mode, HALT mode, the deepest, is possible if the oscillator and WDCLK are also shut down when in IDLE2 mode.

Two control bits, LPM1 and LPM0, specify which of the three possible low-power modes is entered when the IDLE instruction is executed (see Table 12). These bits are located in the System Control and Status Register 1 (SCSR1), and they are described in the *TMS320F243/'F241/'C242 DSP Controllers System and Peripherals User's Guide* (literature number SPRU276).

LOW-POWER MODE	LPMx BITS SCSR1 [13:12]	CPU CLOCK DOMAIN	SYSTEM CLOCK DOMAIN	WDCLK STATUS	PLL STATUS	OSC STATUS	FLASH POWER	EXIT CONDITION
CPU running normally	XX	On	On	On	On	On	On	_
IDLE1 – (LPM0)	00	Off	On	On	On	On	On	Peripheral Interrupt, External Interrupt, Reset, PDPINTA/B
IDLE2 – (LPM1)	01	Off	Off	On	On	On	On	Wakeup Interrupts, External Interrupt, Reset, PDPINTA/B
HALT – (LPM2) [PLL/OSC power down]	1X	Off	Off	Off	Off	Off	Off	Reset, PDPINTA/B

Table 12. Low-Power Modes Summary

other power-down options

'240x devices have clock enable bits to the following on-chip peripherals: ADC, SCI, SPI, CAN, EVB, and EVA. Clock to these peripherals are disabled after reset; thus, start-up power can be low for the device.

Depending on the application, these peripherals can be turned on/off to achieve low power.

Refer to the SCSR2 register for details on the peripheral clock enable bits.



digital I/O and shared pin functions

The '240x has up to 41 general-purpose, bidirectional, digital I/O (GPIO) pins—most of which are shared between primary functions and I/O. Most I/O pins of the '240x are shared with other functions. The digital I/O ports module provides a flexible method for controlling both dedicated I/O and shared pin functions. All I/O and shared pin functions are controlled using eight 16-bit registers. These registers are divided into two types:

- Output Control Registers used to control the multiplexer selection that chooses between the primary function of a pin or the general-purpose I/O function.
- Data and Control Registers used to control the data and data direction of bidirectional I/O pins.

description of shared I/O pins

The control structure for shared I/O pins is shown in Figure 16, where each pin has three bits that define its operation:

- Mux control bit this bit selects between the primary function (1) and I/O function (0) of the pin.
- I/O direction bit if the I/O function is selected for the pin (mux control bit is set to 0), this bit determines whether the pin is an input (0) or an output (1).
- I/O data bit if the I/O function is selected for the pin (mux control bit is set to 0) and the direction selected is an input, data is read from this bit; if the direction selected is an output, data is written to this bit.

The mux control bit, I/O direction bit, and I/O data bit are in the I/O control registers.

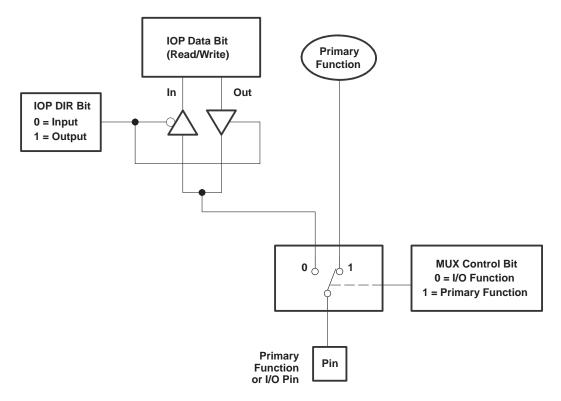


Figure 16. Shared Pin Configuration

A summary of shared pin configurations and associated bits is shown in Table 13.



TMS320LF2407, TMS320LF2406, TMS320LF2402 TMS320LC2406, TMS320LC2404, TMS320LC2402 DSP CONTROLLERS SPRS094C - APRIL 1999 - REVISED OCTOBER 1999

description of shared I/O pins (continued)

Table 13. Shared Pin Configurations†

PIN FUNCTION	SELECTED	MUX	MUX	I/O PORT DA	TA AND DIR	ECTION‡
(MCRx.n = 1) Primary Function	(MCRx.n = 0) I/O	CONTROL REGISTER (name.bit #)	CONTROL VALUE AT RESET (MCRx.n)	REGISTER	DATA BIT NO.§	DIR BIT NO.¶
				PORT A		
SCITXD	IOPA0	MCRA.0	0	PADATDIR	0	8
SCIRXD	IOPA1	MCRA.1	0	PADATDIR	1	9
XINT1	IOPA2	MCRA.2	0	PADATDIR	2	10
CAP1/QEP1	IOPA3	MCRA.3	0	PADATDIR	3	11
CAP2/QEP2	IOPA4	MCRA.4	0	PADATDIR	4	12
CAP3	IOPA5	MCRA.5	0	PADATDIR	5	13
PWM1	IOPA6	MCRA.6	0	PADATDIR	6	14
PWM2	IOPA7	MCRA.7	0	PADATDIR	7	15
		Ì		PORT B		
PWM3	IOPB0	MCRA.8	0	PBDATDIR	0	8
PWM4	IOPB1	MCRA.9	0	PBDATDIR	1	9
PWM5	IOPB2	MCRA.10	0	PBDATDIR	2	10
PWM6	IOPB3	MCRA.11	0	PBDATDIR	3	11
T1PWM/T1CMP	IOPB4	MCRA.12	0	PBDATDIR	4	12
T2PWM/T2CMP	IOPB5	MCRA.13	0	PBDATDIR	5	13
TDIRA	IOPB6	MCRA.14	0	PBDATDIR	6	14
TCLKINA	IOPB7	MCRA.15	0	PBDATDIR	7	15
				PORT C		
W/R [#]	IOPC0	MCRB.0	1	PCDATDIR	0	8
BIO	IOPC1	MCRB.1	1	PCDATDIR	1	9
SPISIMO	IOPC2	MCRB.2	0	PCDATDIR	2	10
SPISOMI	IOPC3	MCRB.3	0	PCDATDIR	3	11
SPICLK	IOPC4	MCRB.4	0	PCDATDIR	4	12
SPISTE	IOPC5	MCRB.5	0	PCDATDIR	5	13
CANTX	IOPC6	MCRB.6	0	PCDATDIR	6	14
CANRX	IOPC7	MCRB.7	0	PCDATDIR	7	15
				PORT D		
XINT2/ADCSOC	IOPD0	MCRB.8	0	PDDATDIR	0	8
EMU0	Reserved	MCRB.9	1	PDDATDIR	1	9
EMU1	Reserved	MCRB.10	1	PDDATDIR	2	10
TCK	Reserved	MCRB.11	1	PDDATDIR	3	11
TDI	Reserved	MCRB.12	1	PDDATDIR	4	12
TDO	Reserved	MCRB.13	1	PDDATDIR	5	13
TMS	Reserved	MCRB.14	1	PDDATDIR	6	14
TMS2	Reserved	MCRB.15	1	PDDATDIR	7	15

[†] Bold, italicized pin names indicate pin functions at reset.

[#] At reset, 'LF2406 and 'LF2402 come up in W/R mode. Application software should select this pin to be IOPC0.



[‡] Valid only if the I/O function is selected on the pin

[§] If the GPIO pin is configured as an output, these bits can be written to. If the pin is configured as an input, these bits are read from.

[¶] If the DIR bit is 0, the GPIO pin functions as an input. For a value of 1, the pin is configured as an output.

description of shared I/O pins (continued)

Table 13. Shared Pin Configurations[†] (Continued)

PIN FUNCTION	SELECTED	MUX	MUX CONTROL	I/O PORT DA	TA AND DIRI	ECTION‡
(MCRx.n = 1) Primary Function	(MCRx.n = 0) I/O	CONTROL REGISTER (name.bit #)	VALUE AT RESET (MCRx.n)	REGISTER	DATA BIT NO.§	DIR BIT NO.¶
				PORT E		
CLKOUT	IOPE0	MCRC.0	1	PEDATDIR	0	8
PWM7	IOPE1	MCRC.1	0	PEDATDIR	1	9
PWM8	IOPE2	MCRC.2	0	PEDATDIR	2	10
PWM9	IOPE3	MCRC.3	0	PEDATDIR	3	11
PWM10	IOPE4	MCRC.4	0	PEDATDIR	4	12
PWM11	IOPE5	MCRC.5	0	PEDATDIR	5	13
PWM12	IOPE6	MCRC.6	0	PEDATDIR	6	14
CAP4/QEP3	IOPE7	MCRC.7	0	PEDATDIR	7	15
				PORT F		
CAP5/QEP4	IOPF0	MCRC.8	0	PFDATDIR	0	8
CAP6	IOPF1	MCRC.9	0	PFDATDIR	1	9
T3PWM/T3CMP	IOPF2	MCRC.10	0	PFDATDIR	2	10
T4PWM/T4CMP	IOPF3	MCRC.11	0	PFDATDIR	3	11
TDIRB	IOPF4	MCRC.12	0	PFDATDIR	4	12
TCLKINB	IOPF5	MCRC.13	0	PFDATDIR	5	13
IOPF6	IOPF6	MCRC.14	0	PFDATDIR	6	14

[†] Bold, italicized pin names indicate pin functions at reset.

digital I/O control registers

Table 14 lists the registers available in the digital I/O module. As with other '240x peripherals, these registers are memory-mapped to the data space.

Table 14. Addresses of Digital I/O Control Registers

ADDRESS	REGISTER	NAME
7090h	MCRA	I/O mux control register A
7092h	MCRB	I/O mux control register B
7094h	MCRC	I/O mux control register C
7095h	PEDATDIR	I/O port E data and direction register
7096h	PFDATDIR	I/O port F data and direction register
7098h	PADATDIR	I/O port A data and direction register
709Ah	PBDATDIR	I/O port B data and direction register
709Ch	PCDATDIR	I/O port C data and direction register
709Eh	PDDATDIR	I/O port D data and direction register

[‡] Valid only if the I/O function is selected on the pin

[§] If the GPIO pin is configured as an output, these bits can be written to. If the pin is configured as an input, these bits are read from.

[¶] If the DIR bit is 0, the GPIO pin functions as an input. For a value of 1, the pin is configured as an output.

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external memory interface ('LF2407)

The TMS320LF2407 can address up to $64K \times 16$ words of memory (or registers) in each of the program, data, and I/O spaces. On-chip memory, when enabled, occupies some of this off-chip range.

The CPU of the TMS320LF2407 schedules a program fetch, data read, and data write on the same machine cycle. This is because from on-chip memory, the CPU can execute all three of these operations in the same cycle. However, the external interface multiplexes the internal buses to one address bus and one data bus. The external interface sequences these operations to complete first the data write, then the data read, and finally the program read.

The 'LF2407 supports a wide range of system interfacing requirements. Program, data, and I/O address spaces provide interface to memory and I/O, thereby maximizing system throughput. The full 16-bit address and data buses, along with the \overline{PS} , \overline{DS} , and \overline{IS} space-select signals, allow addressing of 64K 16-bit words in program, data, and I/O space. Since on-chip peripheral registers occupy positions of data-memory space (7000–7FFF), the externally addressable data-memory space is 32K 16-bit words (8000–FFFF). Note that the global memory space of the 'C2xx core is not used for '240x DSP devices. Therefore, the global memory allocation register (GREG) is reserved for all these devices.

Input/output (I/O) design is simplified by having I/O space treated the same way as memory. I/O devices are accessed in the I/O address space using the processor's external address and data buses in the same manner as memory-mapped devices.

The 'LF2407 external parallel interface provides various control signals to facilitate interfacing to the device. The R/\overline{W} output signal is provided to indicate whether the current cycle is a read or a write. The \overline{STRB} output signal provides a timing reference for all external cycles. For convenience, the device also provides the \overline{RD} and the \overline{WE} output signals, which indicate a read cycle and a write cycle, respectively, along with timing information for those cycles. The availability of these signals minimizes external gating necessary for interfacing external devices to the 'LF2407.

The '2407 provides \overline{RD} and W/\overline{R} signals to help the zero-wait-state external memory interface. At higher CLKOUT speeds, \overline{RD} may not meet the slow memory device's timing. In such instances, the W/\overline{R} signal could be used as an alternative signal with some tradeoffs. See the timings for details.

The TMS320LF2407 supports zero-wait-state reads on the external interface. However, to avoid bus conflicts, writes take two cycles. This allows the TMS320LF2407 to buffer the transition of the data bus from input to output (or from output to input) by a half cycle. In most systems, the TMS320LF2407 ratio of reads to writes is significantly large to minimize the overhead of the extra cycle on writes.

wait-state generation ('LF2407 only)

Wait-state generation is incorporated in the 'LF2407 without any external hardware for interfacing the 'LF2407 with slower off-chip memory and I/O devices. Adding wait states lengthens the time the CPU waits for external memory or an external I/O port to respond when the CPU reads from or writes to that external memory or I/O port. Specifically, the CPU waits one extra cycle (one CLKOUT cycle) for every wait state. The wait states operate on CLKOUT cycle boundaries.

To avoid bus conflicts, writes from the 'LF2407 always take at least two CLKOUT cycles. The 'LF2407 offers two options for generating wait states:

- READY Signal. With the READY signal, you can externally generate any number of wait states. The READY pin has no effect on accesses to internal memory.
- On-Chip Wait-State Generator. With this generator, you can generate zero to seven wait states.



generating wait states with the READY signal

When the READY signal is low, the 'LF2407 waits one CLKOUT cycle and then checks READY again. The 'LF2407 does not continue executing until the READY signal is driven high; therefore, if the READY signal is not used, it should be pulled high.

The READY pin can be used to generate any number of wait states. However, when the 'LF2407 operates at full speed, it may not respond fast enough to provide a READY-based wait state for the first cycle. For extended wait states using external READY logic, the on-chip wait-state generator should be programmed to generate at least one wait state.

generating wait states with the 'LF2407 on-chip software wait-state generator

The software wait-state generator can be programmed to generate zero to seven wait states for a given off-chip memory space (program, data, or I/O), regardless of the state of the READY signal. These zero to seven wait states are controlled by the wait-state generator register (WSGR) (I/O FFFFh). For more detailed information on the WSGR and associated bit functions, refer to the *TMS320F243/'F241/'C242 DSP Controllers System and Peripherals User's Guide* (literature number SPRU276).

watchdog (WD) timer module

The 'x240x devices include a watchdog (WD) timer module. The WD function of this module monitors software and hardware operation by generating a system reset if it is not periodically serviced by software by having the correct key written. The WD timer operates independently of the CPU. It does not need any CPU initialization to function. When a system reset occurs, the WD timer defaults to the fastest WD timer rate available (WDCLK signal = CLKOUT/512). As soon as reset is released internally, the CPU starts executing code, and the WD timer begins incrementing. This means that, to avoid a premature reset, WD setup should occur early in the power-up sequence. See Figure 17 for a block diagram of the WD module. The WD module features include the following:

WD Timer

- Seven different WD overflow rates
- A WD-reset key (WDKEY) register that clears the WD counter when a correct value is written, and generates a system reset if an incorrect value is written to the register
- WD check bits that initiate a system reset if an incorrect value is written to the WD control register (WDCR)
- Automatic activation of the WD timer, once system reset is released
 - Three WD control registers located in control register frame beginning at address 7020h.

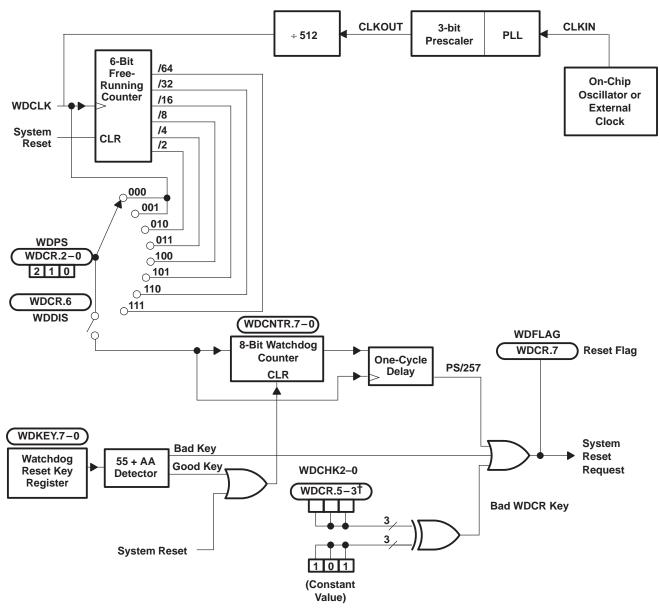
NOTE: All registers in this module are 8-bit registers. When a register is accessed, the register data is in the lower byte, the upper byte is read as zeros. Writing to the upper byte has no effect.

Figure 17 shows the WD block diagram. Table 15 shows the different WD overflow (timeout) selections.

The watchdog can be disabled in software by writing '1' to bit 6 of the WDCR register (WDCR.6) while bit 5 of the SCSR2 register (SCSR2.5) is 1. If SCSR2.5 is 0, the watchdog will not be disabled. SCSR2.5 is equivalent to the WDDIS pin of the TMS320F243/241 devices.



watchdog (WD) timer module (continued)



†Writing to bits WDCR.5–3 with anything but the correct pattern (101) generates a system reset.

Figure 17. Block Diagram of the WD Module

watchdog (WD) timer module (continued)

Table 15. WD Overflow (Timeout) Selections

WD PRESCALE SELECT BITS			WDCLK DIVIDER	WATCHDOG CLOCK RATE [†]
WDPS2	WDPS1	WDPS0		FREQUENCY (Hz)
0	0	X‡	1	WDCLK/1
0	1	0	2	WDCLK/2
0	1	1	4	WDCLK/4
1	0	0	8	WDCLK/8
1	0	1	16	WDCLK/16
1	1	0	32	WDCLK/32
1	1	1	64	WDCLK/64

[†]WDCLK = CLKOUT/512

[‡] X = Don't care

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development support

Texas Instruments (TI) offers an extensive line of development tools for the 'x240x generation of DSPs, including tools to evaluate the performance of the processors, generate code, develop algorithm implementations, and fully integrate and debug software and hardware modules.

The following products support development of 'x240x-based applications:

Software Development Tools:

Assembler/linker
Simulator
Optimizing ANSI C compiler
Application algorithms
C/Assembly debugger and code profiler

Hardware Development Tools:

Emulator XDS510 (supports 'x24x multiprocessor system debug)

The *TMS320 DSP Development Support Reference Guide* (literature number SPRU011) contains information about development support products for all TMS320 family member devices, including documentation. Refer to this document for further information about TMS320 documentation or any other TMS320 support products from Texas Instruments. There is also an additional document, the *TMS320 Third-Party Support Reference Guide* (literature number SPRU052), which contains information about TMS320-related products from other companies in the industry. To receive copies of TMS320 literature, contact the Literature Response Center at 800/477-8924.

See Table 16 and Table 17 for complete listings of development support tools for the 'x240x. For information on pricing and availability, contact the nearest TI field sales office or authorized distributor.

Table 16. Development Support Tools

DEVELOPMENT TOOL	PLATFORM	PART NUMBER				
Software						
Compiler/Assembler/Linker	SPARC™	TMDS3242555-08				
Compiler/Assembler/Linker	PC-DOS™	TMDS3242855-02				
Assembler/Linker	PC-DOS, OS/2™	TMDS3242850-02				
'C2xx Simulator	PC-DOS, WIN™	TMDX324x851-02				
'C2xx Simulator	SPARC	TMDX324x551-09				
Digital Filter Design Package	PC-DOS	DFDP				
'C2xx Debugger/Emulation Software	PC-DOS, OS/2, WIN	TMDX324012xx				
'C2xx Debugger/Emulation Software	SPARC	TMDX324062xx				
Hardware						
XDS510XL™ Emulator	PC-DOS, OS/2	TMDS00510				
XDS510WS™ Emulator	SPARC	TMDS00510WS				

SPARC is a trademark of SPARC International, Inc.
PC-DOS and OS/2 are trademarks of International Business Machines Corp.
WIN is a trademark of Microsoft Corp.
XDS510XL and XDS510WS are trademarks of Texas Instruments Incorporated.



development support (continued)

Table 17. TMS320x24x-Specific Development Tools

DEVELOPMENT TOOL	PLATFORM	PART NUMBER
	Hardware	
TMS320F240 EVM	PC	TMDX326P124x
TMS320F243 EVM	PC	TMDS3P604030

The 'F240 and 'F243 Evaluation Modules (EVM) provide designers of motor and motion control applications with a complete and cost-effective way to take their designs from concept to production. These tools offer both a hardware and software development environment and include:

- Flash-based '24x evaluation board
- Code Generation Tools
- Assembler/Linker
- C Compiler ('F243 EVM)
- Source code debugger
- 'C24x Debugger ('F240 EVM)
- Code Composer IDE ('F243 EVM)
- XDS510PP JTAG-based emulator
- Sample applications code
- Universal 5VDC power supply
- Documentation and cables

device and development support tool nomenclature

To designate the stages in the product development cycle, Texas Instruments assigns prefixes to the part numbers of all TMS320 devices and support tools. Each TMS320 member has one of three prefixes: TMX, TMP, or TMS. Texas Instruments recommends two of three possible prefix designators for its support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully qualified production devices/tools (TMS/TMDS). This development flow is defined below.

Support tool development evolutionary flow:

TMDX Development support product that has not completed TI's internal qualification testing

TMDS Fully qualified development support product

TMX and TMP devices and TMDX development support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

TMS devices and TMDS development support tools have been fully characterized, and the quality and reliability of the device have been fully demonstrated. Tl's standard warranty applies.



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device and development support tool nomenclature (continued)

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, PG, PGE, and PZ) and temperature range (for example, A). Figure 18 provides a legend for reading the complete device name for any TMS320x2xx family member. Refer to the timing section for specific options that are available on '240x devices.

Predictions show that prototype devices (TMX or TMP) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

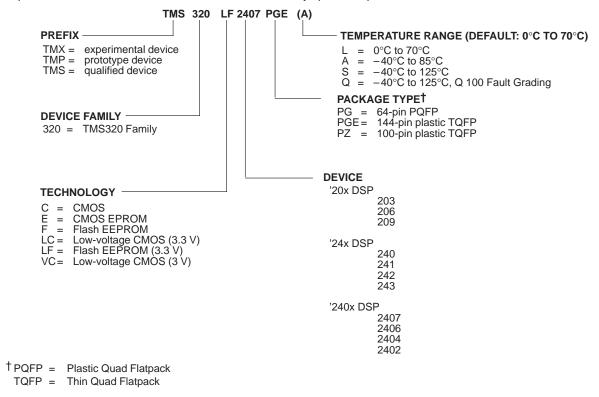


Figure 18. TMS320 Device Nomenclature

documentation support

Extensive documentation supports all of the TMS320 family generations of devices from product announcement through applications development. The types of documentation available include: data sheets, such as this document, with design specifications; complete user's guides for all devices and development support tools; and hardware and software applications. Useful reference documentation includes:

Data sheets

- TMS320C242 DSP Controller (literature number SPRS063)
- TMS320F243, TMS320F241 DSP Controllers (literature number SPRS064)

User Guides

- TMS320C240 DSP Controllers CPU, System, and Instruction Set Reference Guide (literature number SPRU160)
- TMS320C240 DSP Controllers Peripheral Library and Specific Devices (literature number SPRU161)
- 'F243/'F241/'C242 DSP Controllers System and Peripherals User's Guide (literature number SPRU276)

Application Reports

3.3V DSP for Digital Motor Control (literature number SPRA550)

A series of DSP textbooks is published by Prentice-Hall and John Wiley & Sons to support digital signal processing research and education. The TMS320 newsletter, *Details on Signal Processing*, is published quarterly and distributed to update TMS320 customers on product information.

Updated information on the TMS320 DSP controllers can be found on the worldwide web at: http://www.ti.com.

To send comments regarding the '240x data sheet (SPRS094), use the *comments@books.sc.ti.com* email address, which is a repository for feedback. For questions and support, contact the Product Information Center listed at the http://www.ti.com/sc/docs/pic/home.htm site.



ADVANCE INFORMATION

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

		,
Supply voltage range, V _{DD} , PLLV _{CCA} , V _D	_{DOO} , and V _{CCA} (see Note 1)	- 0.3 V to 4.6 V
V _{CCP} range		0.3 V to 5.5 V
Input voltage range, V _I		– 0.3 V to 4.6 V
Output voltage range, VO 'LF240x		- 0.3 V to 4.6 V
Output voltage range, VO 'LC240x		- 0.3 V to 4.6 V
Input clamp current, IIK (VI < 0 or VI > VCC	c)	± 20 mA
	> V _{CC})	
Operating free-air temperature range, T _A :	A version	-40°C to 85°C
	(TMS320LF2407PGE)	
	(TMS320LF2406PZ, TMS320LC2404PZ, TMS3	20LC2406PZ)
	(TMS320LF2402PG, TMS320LC2402PG)	
	S version	– 40°C to 125°C
	(TMS320LF2407PGE)	
	(TMS320LF2406PZ, TMS320LC2404PZ, TMS3	20LC2406PZ)
	(TMS320LF2402PG, TMS320LC2402PG)	
Storage temperature range, T _{stg}		- 65°C to 150°C

[†] Clamp current stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. NOTE 1: All voltage values are with respect to VSS.

recommended operating conditions‡

			MIN	NOM	MAX	UNIT
V_{DD}	Supply voltage (±10% of 3.3 V)	3.3-V operation	3.0	3.3	3.6	V
V _{SS}	Supply ground		0	0	0	V
PLLV _{CCA}	PLL supply voltage	3.3-V operation	3.0	3.3	3.6	V
VCCA	ADC supply voltage	3.3-V operation	3.0	3.3	3.6	V
VCCP	Flash programming supply voltage (±5%)		4.75	5.0	5.25	V
fCLKOUT	Device clock frequency	- 40°C to 125°C			30	MHz
VIH	High-level input voltage	All inputs	2.0			V
V _{IL}	Low-level input voltage	All inputs			0.8	V
		Output pins Group 1§			-2.0	mA
loн	High-level output source current, $V_{OH} = 2.4 \text{ V}$	Output pins Group 2§			-4.0	mA
		Output pins Group 3§			-8.0	mA
		Output pins Group 1§			2.0	mA
loL	Low-level output sink current, VOL = VOL MAX	Output pins Group 2§			4.0	mA
		Output pins Group 3§			8.0	mA
_	Operating free-air temperature	A version	- 40	25	85	
TA	(excluding flash programming)	S version	- 40	25	125	°C
T _{stg}	Storage temperature		- 65		150	°C
T _{FP}	Flash programming temperature		- 40	25	85	°C
Tį	Junction temperature		- 40	25	150	°C
Nf	Flash endurance for the array (Write/erase cycles)	At room temperature		10K		cycles

[‡]Refer to the mechanical data package page for thermal resistance values, ΘJA (junction-to-ambient) and ΘJC (junction-to-case).

SPISOMI, SPISIMO, SPISTE, EMU0, EMU1, TDO, TMS2

Group 3: TDIRA, TDIRB, SCIRXD, SCITXD, XINT1, XINT2, CLKOUT



[§] Primary signals and their GPIOs:

PWM1-PWM6, CAP1-CAP6, TCLKINA, RS, IOPF6, IOPC1, TCK, TDI, TMS, XF Group 1:

PS/DS/IS, RD, W/R, STRB, R/W, VIS_OE, A0-A15, D0-D15, T1PWM-T4PWM, PWM7-PWM12, CANTX, CANRX, SPICLK, Group 2:

ADVANCE INFORMATION

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
.,	LPak lavel sytemtockers		$V_{DD} = 3.0V$, $I_{OH} = 2$ mA, 4 mA, 8 mA		2.4			.,
VOH	V _{OH} High-level output voltage		All outputs at 50 μA		2.7			V
VOL	Low-level output voltage		I _{OL} = 2 mA, 4 mA, 8 mA				0.4	V
IIL	Input current (low level)		V _I = 0 V				±20	μΑ
lн	Input current (high level)		$V_I = V_{DD}$				±20	μΑ
loz	Output current, high-impedance		$V_O = V_{DD}$ or 0 V				±5	μΑ
			3.3-V operation,CPUCLK = 30 MHz, all peripherals running	'LF2407		180		
	Supply current, operating mode	'LF2406			150		mA	
				'LF2402		115		
			LPM0 [†] 3.3-V operation, t _{C(CO)} = 30 MHz [†]	'LF2407		80		mA
	Supply current, Idle 1 low-power mode	LPM0†		'LF2406		70		
	linedo			'LF2402		55		
IDD				'LF2407		45		
	Supply current, Idle 2 low-power mode	LPM1 [†]	3.3-V operation, t _{C(CO)} = 30 MHz [†]	'LF2406		45		mA
	mede		, ,	'LF2402		45		
				'LF2407		80		
	Supply current, PLL/OSC power-down mode	LPM2†	3.3-V operation, at room temperature†	'LF2406		80		μΑ
	1 22 CCC power down mode		temperature.	'LF2402		80		
Ci	C _i Input capacitance					2		pF
Со	Output capacitance					3		pF

[†] Test condition: These current measurements are estimates when the CPU is running a dummy code in B0 RAM.

PARAMETER MEASUREMENT INFORMATION

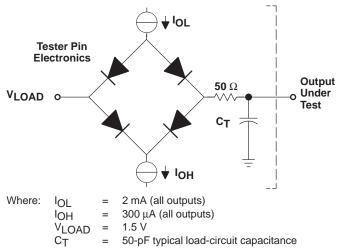


Figure 19. Test Load Circuit

signal transition levels

The data in this section is shown for the 3.3-V version. Note that some of the signals use different reference voltages, see the recommended operating conditions table. Output levels are driven to a minimum logic-high level of 2.4 V and to a maximum logic-low level of 0.8 V.

Figure 20 shows output levels.

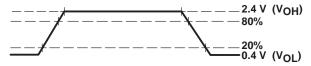


Figure 20. Output Levels

Output transition times are specified as follows:

- For a *high-to-low transition*, the level at which the output is said to be no longer high is below 80% of the total voltage range and lower and the level at which the output is said to be low is 20% of the total voltage range and lower.
- For a *low-to-high transition*, the level at which the output is said to be no longer low is 20% of the total voltage range and higher and the level at which the output is said to be high is 80% of the total voltage range and higher.

Figure 21 shows the input levels.

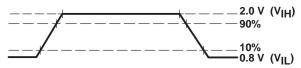


Figure 21. Input Levels

Input transition times are specified as follows:

- For a high-to-low transition on an input signal, the level at which the input is said to be no longer high is 90% of the total voltage range and lower and the level at which the input is said to be low is 10% of the total voltage range and lower.
- For a low-to-high transition on an input signal, the level at which the input is said to be no longer low is 10% of the total voltage range and higher and the level at which the input is said to be high is 90% of the total voltage range and higher.



ADVANCE INFORMATION

PARAMETER MEASUREMENT INFORMATION

timing parameter symbology

Timing parameter symbols used are created in accordance with JEDEC Standard 100-A. To shorten the symbols, some of the pin names and other related terminology have been abbreviated as follows:

Α	A[15:0]	MS	Memory strobe pins \overline{IS} , \overline{DS} , or \overline{PS}
CI	XTAL1/CLKIN	R	READY
CO	CLKOUT	RD	Read cycle or RD
D	D[15:0]	RS	RESET pin RS
INT	NMI, XINT1, XINT2	W	Write cycle or WE
Lowerca	se subscripts and their meanings:	Letters and	d symbols and their meanings:
а	access time	Н	High
	1 (1 / 1 1)		

С cycle time (period) d delay time fall time h hold time rise time setup time su transition time

valid time pulse duration (width)

٧

L Low Valid

Χ Unknown, changing, or don't care level High impedance

general notes on timing parameters

All output signals from the 'F243/'F241 devices (including CLKOUT) are derived from an internal clock such that all output transitions for a given half-cycle occur with a minimum of skewing relative to each other.

The signal combinations shown in the following timing diagrams may not necessarily represent actual cycles. For actual cycle examples, refer to the appropriate cycle description section of this data sheet.

ADVANCE INFORMATION

external reference crystal/clock with PLL circuit enabled

timings with the PLL circuit enabled

PARAMETER		MIN	TYP	MAX	UNIT	
		Resonator	4		13	
f _X	f _x Input clock frequency [†]	Crystal	4		20	MHz
		CLKIN	4		20	

TInput frequency should be adjusted (CLK PS bits in SCSR1 register) such that CLKOUT = 30 MHz maximum.

switching characteristics over recommended operating conditions [H = $0.5 t_{c(CO)}$] (see Figure 22)

	PARAMETER	PLL MODE	MIN	TYP	MAX	UNIT
t _C (CO)	Cycle time, CLKOUT	×4 mode†	33			ns
t _f (CO)	Fall time, CLKOUT			4		ns
t _{r(CO)}	Rise time, CLKOUT			4		ns
tw(COL)	Pulse duration, CLKOUT low		H-3	Н	H+3	ns
tw(COH)	Pulse duration, CLKOUT high		H –3	Н	H+3	ns
tp	Transition time, PLL synchronized after RS pin high				4096t _{C(CI)}	ns

[†] Input frequency should be adjusted (CLK PS bits in SCSR1 register) such that CLKOUT = 30 MHz maximum.

timing requirements (see Figure 22)

		MIN	MAX	UNIT
t _C (CI)	Cycle time, XTAL1/CLKIN	133		ns
t _f (CI)	Fall time, XTAL1/CLKIN		5	ns
tr(CI)	Rise time, XTAL1/CLKIN		5	ns
t _w (CIL)	Pulse duration, XTAL1/CLKIN low as a percentage of t _{C(CI)}	40	60	%
tw(CIH)	Pulse duration, XTAL1/CLKIN high as a percentage of t _{C(Cl)}	40	60	%

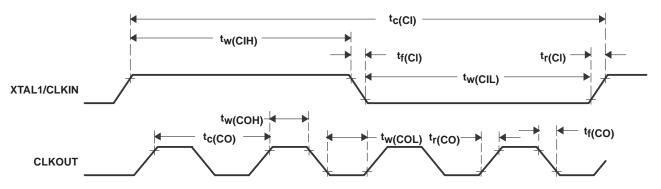


Figure 22. CLKIN-to-CLKOUT Timing with PLL and External Clock in ×4 Mode

RS timings

switching characteristics over recommended operating conditions for a reset [H = $0.5t_{c(CO)}$] (see Figure 23)

	PARAMETER	MIN	MAX	UNIT
tw(RSL1)	Pulse duration, RS low [†]	128t _{C(CI)}		ns
^t d(EX)	Delay time, reset vector executed after PLL lock time	36H		ns
tp	PLL lock time (input cycles)		4096	cycles

 $[\]overline{\dagger}$ The parameter $t_{W(RSL1)}$ refers to the time \overline{RS} is an output.

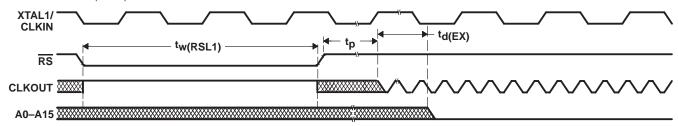
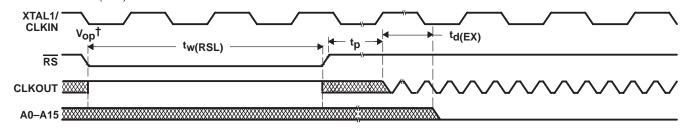


Figure 23. Watchdog Reset Pulse

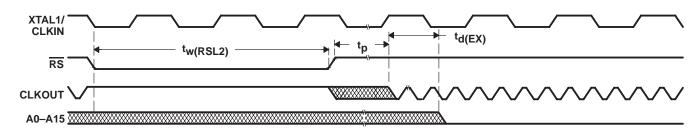
timing requirements for a reset $[H = 0.5t_{c(CO)}]$ (see Figure 24)

		MIN	MAX	UNIT
tw(RSL)	Pulse duration, RS low‡	1		ms
tw(RSL2)	Pulse duration, RS low	8t _C (CI)		ns
t _{d(EX)}	Delay time, reset vector executed after PLL lock time	36H		ns

‡The parameter tw(RSL) refers to the time RS is an input



Case A. Power-on reset



Case B. External reset after power-on

Figure 24. Reset Timing



 $^{^\}dagger V_{OD}$ is the V_{CC} voltage below which the device is non-operational, typically around 1.1 V.

XF, BIO, and MP/MC timings

switching characteristics over recommended operating conditions (see Figure 25)

	PARAMETER	MIN	MAX	UNIT
t _d (XF)	Delay time, CLKOUT high to XF high/low	-3	7	ns

timing requirements (see Figure 25)

		MIN	MAX	UNIT
t _{su(BIO)CO}	Setup time, BIO or MP/MC low before CLKOUT low	0		ns
th(BIO)CO	Hold time, BIO or MP/MC low after CLKOUT low	19		ns

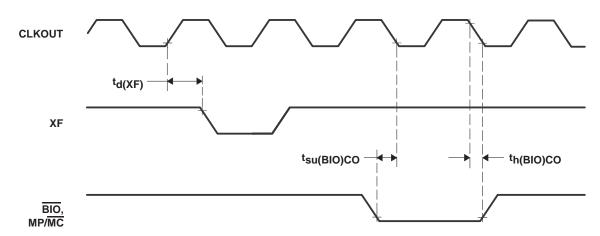


Figure 25. XF and BIO Timing

TIMING EVENT MANAGER INTERFACE

PWM timings

PWM refers to PWM outputs on PWM1, PWM2, PWM3, PWM4, PWM5, PWM6, T1PWM, and T2PWM.

switching characteristics over recommended operating conditions for PWM timing $[H=0.5t_{c(CO)}]$ (see Figure 26)

	PARAMETER	MIN	MAX	UNIT
tw(PWM) [†]	Pulse duration, PWM output high/low	2H+5		ns
td(PWM)CO	Delay time, CLKOUT low to PWM output switching		15	ns

 $[\]dagger$ PWM outputs may be 100%, 0%, or increments of $t_{C(CO)}$ with respect to the PWM period.

timing requirements \ddagger [H = 0.5t_{c(CO)}] (see Figure 27)

		MIN	MAX	UNIT
tw(TMRDIR)	Pulse duration, TMRDIR low/high	4H+5		ns
tw(TMRCLK)	Pulse duration, TMRCLK low as a percentage of TMRCLK cycle time	40	60	%
twh(TMRCLK)	Pulse duration, TMRCLK high as a percentage of TMRCLK cycle time	40	60	%
tc(TMRCLK)	Cycle time, TMRCLK	$4 \times t_{C(CO)}$		ns

[‡] Parameter TMRDIR is equal to the pin TDIR, and parameter TMRCLK is equal to the pin TCLKIN.

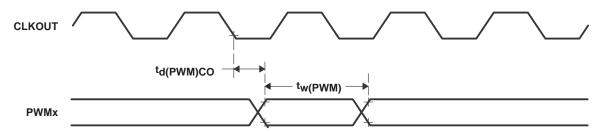


Figure 26. PWM Output Timing

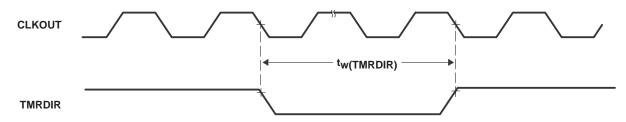


Figure 27. Capture/TMRDIR Timing

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capture and QEP timings

CAP refers to CAP1/QEP0/IOPA3, CAP2/QEP1/IOPA4, and CAP3/IOPA5.

timing requirements $[H = 0.5t_{C(CO)}]$ (see Figure 28)

		MIN	MAX	UNIT
t _w (CAP)	Pulse duration, CAP input low/high	4H +15		ns

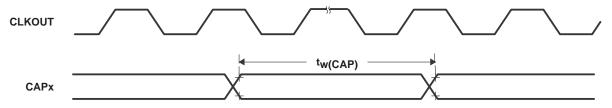


Figure 28. Capture Input and QEP Timing

interrupt timings

INT refers to NMI, XINT1, and XINT2/IO. PDP refers to PDPINT.

switching characteristics over recommended operating conditions (see Figure 29)

	PARAMETER	MIN	MAX	UNIT
thz(PWM)PDP	Delay time, PDPINT low to PWM to high-impedance state		12	ns
t _d (INT)	Delay time, INT low/high to interrupt-vector fetch	10t _C (CO)		ns

timing requirements $[H = 0.5t_{C(CO)}]$ (see Figure 29)

		MIN	MAX	UNIT
tw(INT)	Pulse duration, INT input low/high	2H+15		ns
tw(PDP)	Pulse duration, PDPINT input low	4H+5		ns

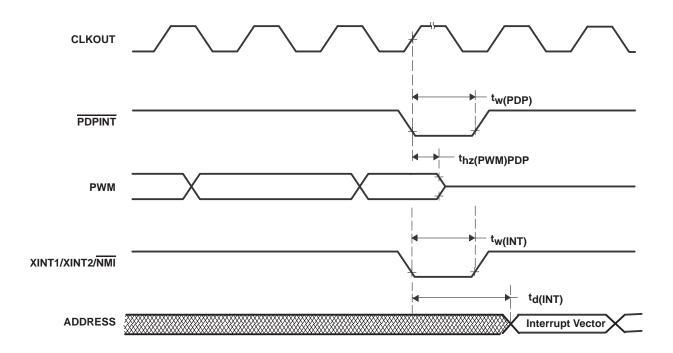


Figure 29. Power Drive Protection Interrupt Timing

general-purpose input/output timings

switching characteristics over recommended operating conditions (see Figure 30)

PARAMETER		MIN	MAX	UNIT	
t _d (GPO)CO	Delay time, CLKOUT low to GPIO low/high	All GPIOs		9	ns
tr(GPO)	Rise time, GPIO switching low to high	All GPIOs		8	ns
tf(GPO)	Fall time, GPIO switching high to low	All GPIOs		6	ns

timing requirements $[H = 0.5t_{C(CO)}]$ (see Figure 31)

		MIN	MAX	UNIT
tw(GPI)	Pulse duration, GPI high/low	2H+15		ns

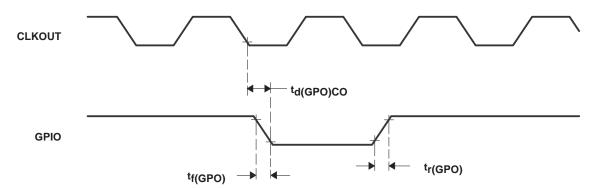


Figure 30. General-Purpose Output Timing

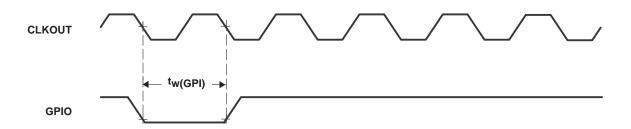


Figure 31. General-Purpose Input Timing

SPI MASTER MODE TIMING PARAMETERS

SPI master mode timing information is listed in the following tables.

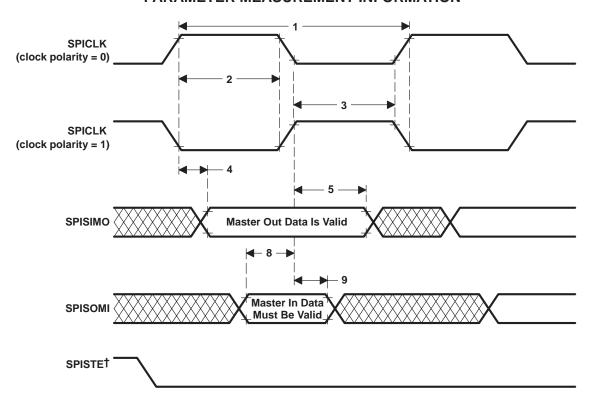
SPI master mode external timing parameters (clock phase = 0)^{†‡} (see Figure 32)

O			SPI WHEN (SPIBRR + 1) IS EVEN OR SPIBRR = 0 OR 2	+ 1) IS EVEN 0 OR 2	SPI WHEN (SPIBRR + 1) IS ODD AND SPIBRR > 3	IBRR + 1) PIBRR > 3	LIND
			MIN	MAX	NIM	MAX	
_	t _c (SPC)M	Cycle time, SPICLK	4t _C (CO)	128t _c (CO)	5tc(CO)	127tc(CO)	ns
ų	tw(SPCH)M	Pulse duration, SPICLK high (clock polarity = 0)	0.5t _C (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}^{-0.5t_{\rm C}({\rm CO})}^{-10}$	$0.5t_{\rm C}({\rm SPC}){\rm M} - 0.5t_{\rm C}({\rm CO})$!
87	tw(SPCL)M	Pulse duration, SPICLK low (clock polarity = 1)	0.5t _C (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}{-}0.5t_{\rm C}({\rm CO}){-}10$	$0.5t_{\rm C}({\rm SPC}){\rm M}$ $-0.5t_{\rm C}({\rm CO})$	ns
ď	tw(SPCL)M	Pulse duration, SPICLK low (clock polarity = 0)	0.5t _C (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}+0.5t_{\rm C}({\rm CO})^{-10}$	$0.5t_{\rm C}({\rm SPC}){\rm M} + 0.5t_{\rm C}({\rm CO})$	9
33	tw(SPCH)M	Pulse duration, SPICLK high (clock polarity = 1)	0.5t _C (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}+0.5t_{\rm C}({\rm CO})^{-10}$	$0.5t_{\rm C}({\rm SPC}){\rm M} + 0.5t_{\rm C}({\rm CO})$	SU
ų	td(SPCH-SIMO)M	Delay time, SPICLK high to SPISIMO valid (clock polarity = 0)	- 10	10	- 10	10	9
գ ռ	td(SPCL-SIMO)M	Delay time, SPICLK low to SPISIMO valid (clock polarity = 1)	- 10	10	- 10	10	SU
ű	t _v (SPCL-SIMO)M	Valid time, SPISIMO data valid after SPICLK low (clock polarity =0)	$0.5t_{\rm C}({\rm SPC}){\rm M}-10$		0.5t _C (SPC)M+0.5t _C (CO)-10		
n C	t _v (SPCH-SIMO)M	Valid time, SPISIMO data valid after SPICLK high (clock polarity =1)	0.5t _C (SPC)M-10		$0.5t_{\rm C}({\rm SPC}){\rm M}+0.5t_{\rm C}({\rm CO})-10$		Su
ų	tsu(SOMI-SPCL)M	Setup time, SPISOMI before SPICLK low (clock polarity = 0)	0		0		
n xx	tsu(SOMI-SPCH)M	Setup time, SPISOMI before SPICLK high (clock polarity = 1)	0		0		NS
ų	t _V (SPCL-SOMI)M	Valid time, SPISOMI data valid after SPICLK low (clock polarity = 0)	$0.25t_{\rm C}({\rm SPC}){\rm M}{-}10$		$0.5t_{\rm C}({\rm SPC}){\rm M} - 0.5t_{\rm C}({\rm CO}) - 10$		Ġ
n D	tv(SPCH-SOMI)M	Valid time, SPISOMI data valid after SPICLK high (clock polarity = 1)	0.25t _c (SPC)M-10		$0.5t_{\rm C}({\rm SPC}){\rm M}$ $-0.5t_{\rm C}({\rm CO})$ -10		<u>e</u>
- N		HOIGO : LOVIIG XOO O FI	. (6) HO				

[†] The MASTER/SLAVE bit (SPICTL.2) is set and the CLOCK PHASE bit (SPICTL.3) is cleared.

 $\ddagger\,t_{C}=$ system clock cycle time = 1/CLKOUT = $t_{C}(CO)$ § The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

PARAMETER MEASUREMENT INFORMATION



[†] The SPISTE signal must be active before the SPI communication stream starts; the SPISTE signal must remain active until the SPI communication stream is complete.

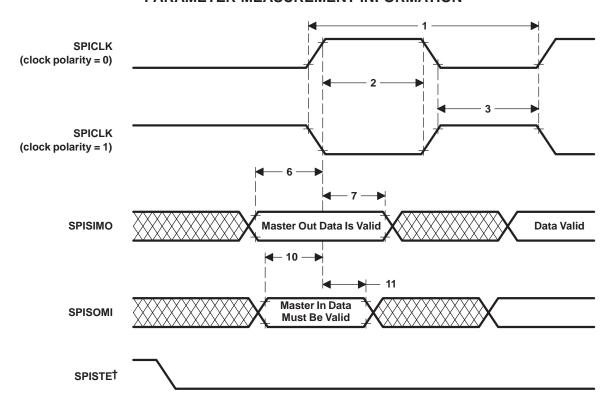
Figure 32. SPI Master Mode External Timing (Clock Phase = 0)

ADVANCE INFORMATION

SPI m	SPI master mode external timing pa		rameters (clock phase = 1) ¹⁺ (see Figure 33) SPI WHEN (SPIBRR + 1) IS EVEN OR SPIBRR = 0 OR 2	1+ (see Figu (+1) IS EVEN 0 OR 2	re 33) SPI WHEN (SPIBRR + 1) IS ODD AND SPIBRR > 3	BRR + 1) PIBRR > 3	TIND
			NIM	MAX	MIN	MAX	
1	t _c (SPC)M	Cycle time, SPICLK	4t _c (CO)	128t _c (CO)	5tc(CO)	127t _c (CO)	ns
(tw(SPCH)M	Pulse duration, SPICLK high (clock polarity = 0)	0.5t _c (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}^{-0.5t_{\rm C}}({\rm CO})^{-10}$	0.5tc(SPC)M -0.5tc(CO)	
8	tw(SPCL)M	Pulse duration, SPICLK low (clock polarity = 1)	0.5t _c (SPC)M-10	0.5t _c (SPC)M	$0.5t_{\rm C}({\rm SPC}){\rm M}^{-0.5t_{\rm C}}({\rm CO})^{-10}$	0.5tc(SPC)M -0.5tc(CO)	Su
ų	tw(SPCL)M	Pulse duration, SPICLK low (clock polarity = 0)	0.5t _c (SPC)M-10	0.5t _c (SPC)M	0.5t _C (SPC)M+0.5t _C (CO)-10	$0.5t_{\rm C}({\rm SPC}){\rm M} + 0.5t_{\rm C}({\rm CO})$	
n m	tw(SPCH)M	Pulse duration, SPICLK high (clock polarity = 1)	0.5t _c (SPC)M-10	0.5t _c (SPC)M	0.5t _C (SPC)M+0.5t _C (CO)-10	$0.5t_{\rm C}({\rm SPC}){\rm M} + 0.5t_{\rm C}({\rm CO})$	Su
ű	tsu(SIMO-SPCH)M	Setup time, SPISIMO data valid before SPICLK high (clock polarity = 0)	0.5t _c (SPC)M-10		0.5t _C (SPC)M -10		
n 0	tsu(SIMO-SPCL)M	Setup time, SPISIMO data valid before SPICLK low (clock polarity = 1)	0.5t _c (SPC)M-10		0.5t _C (SPC)M -10		s
ų	t _v (SPCH-SIMO)M	Valid time, SPISIMO data valid after SPICLK high (clock polarity =0)	0.5t _c (SPC)M-10		0.5t _C (SPC)M -10		,
ຶ້	tv(SPCL-SIMO)M	Valid time, SPISIMO data valid after SPICLK low (clock polarity =1)	0.5t _c (SPC)M-10		0.5t _C (SPC)M -10		SU
ν.	^t su(SOMI-SPCH)M	Setup time, SPISOMI before SPICLK high (clock polarity = 0)	0		0		
<u>8</u> 01	tsu(SOMI-SPCL)M	Setup time, SPISOMI before SPICLK low (clock polarity = 1)	0		0		2
, ,	t _v (SPCH-SOMI)M	Valid time, SPISOMI data valid after SPICLK high (clock polarity = 0)	0.25t _C (SPC)M-10		0.5t _c (SPC)M-10		ú
2	tv(SPCL-SOMI)M	Valid time, SPISOMI data valid after SPICLK low (clock polarity = 1)	0.25t _c (SPC)M-10		$0.5t_{\rm C}({\rm SPC}){\rm M}{-}10$		2
T The M	ASTER/SLAVE bit (SPICTL.	The MASTER/SLAVE bit (SPICTL.2) is set and the CLOCK PHASE bit (SPICTL.3) is set.	it (SPICTL.3) is set.				

The MASTER/SLAVE bit (SPIC) 16.59 set and the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

PARAMETER MEASUREMENT INFORMATION



[†] The SPISTE signal must be active before the SPI communication stream starts; the SPISTE signal must remain active until the SPI communication stream is complete.

Figure 33. SPI Master Mode External Timing (Clock Phase = 1)



SPI SLAVE MODE TIMING PARAMETERS

Slave mode timing information is listed in the following tables.

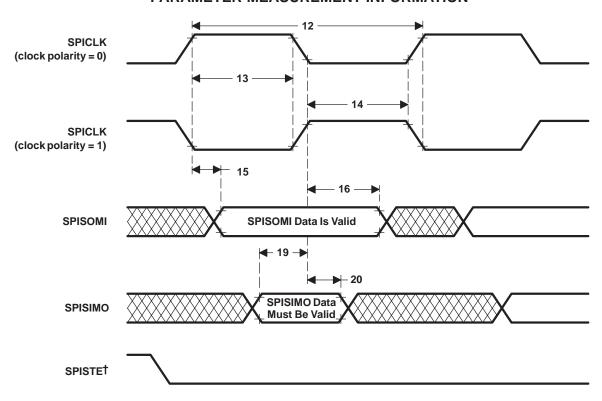
SPI slave mode external timing parameters (clock phase = 0)^{†‡} (see Figure 34)

NO.			MIN	MAX	UNIT
12	t _C (SPC)S	Cycle time, SPICLK	4t _{c(CO)} ‡		ns
13§	tw(SPCH)S	Pulse duration, SPICLK high (clock polarity = 0)	0.5t _C (SPC)S-10	0.5t _C (SPC)S	
138	tw(SPCL)S	Pulse duration, SPICLK low (clock polarity = 1)	0.5t _C (SPC)S-10	0.5t _C (SPC)S	ns
14§	tw(SPCL)S	Pulse duration, SPICLK low (clock polarity = 0)	0.5t _C (SPC)S-10	0.5t _C (SPC)S	
143	tw(SPCH)S	Pulse duration, SPICLK high (clock polarity = 1)	0.5t _C (SPC)S-10	0.5t _C (SPC)S	ns
15§	td(SPCH-SOMI)S	Delay time, SPICLK high to SPISOMI valid (clock polarity = 0)	0.375t _C (SPC)S-10		ns
	td(SPCL-SOMI)S	Delay time, SPICLK low to SPISOMI valid (clock polarity = 1)	0.375t _C (SPC)S-10		
2-2-1	tv(SPCL-SOMI)S	Valid time, SPISOMI data valid after SPICLK low (clock polarity =0)	0.75t _C (SPC)S		
16§	tv(SPCH-SOMI)S	Valid time, SPISOMI data valid after SPICLK high (clock polarity =1)	0.75t _C (SPC)S		ns
30.1	tsu(SIMO-SPCL)S	Setup time, SPISIMO before SPICLK low (clock polarity = 0)	0		
19§	t _{su(SIMO-SPCH)S}	Setup time, SPISIMO before SPICLK high (clock polarity = 1)	0		ns
20§	tv(SPCL-SIMO)S	Valid time, SPISIMO data valid after SPICLK low (clock polarity = 0)	0.5t _C (SPC)S		ns
208	t _V (SPCH-SIMO)S	Valid time, SPISIMO data valid after SPICLK high (clock polarity = 1)	0.5t _C (SPC)S		ns

[†] The MASTER/SLAVE bit (SPICTL.2) is cleared and the CLOCK PHASE bit (SPICTL.3) is cleared.

 $[\]ddagger$ t_C = system clock cycle time = 1/CLKOUT = t_C(CO) § The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

PARAMETER MEASUREMENT INFORMATION



[†] The SPISTE signal must be active before the SPI communication stream starts; the SPISTE signal must remain active until the SPI communication stream is complete.

Figure 34. SPI Slave Mode External Timing (Clock Phase = 0)

TMS320LF2407,TMS320LF2406,TMS320LF2402 TMS320LC2406,TMS320LC2404,TMS320LC2402 DSP CONTROLLERS SPRS094C – APRIL 1999 – REVISED OCTOBER 1999

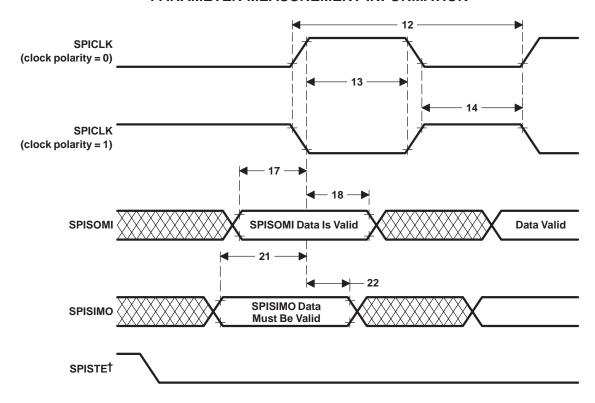
SPI slave mode external timing parameters (clock phase = 1) $^{\dagger \ddagger}$ (see Figure 35)

NO.			MIN	MAX	UNIT
12	t _C (SPC)S	Cycle time, SPICLK	8t _C (CO)		ns
13§	tw(SPCH)S	Pulse duration, SPICLK high (clock polarity = 0)	0.5t _{C(SPC)S} -10	0.5t _C (SPC)S	
138	tw(SPCL)S	Pulse duration, SPICLK low (clock polarity = 1)	0.5t _{C(SPC)S} -10	0.5t _C (SPC)S	ns
14§	tw(SPCL)S	Pulse duration, SPICLK low (clock polarity = 0)	0.5t _{C(SPC)S} -10	0.5t _C (SPC)S	
148	tw(SPCH)S	Pulse duration, SPICLK high (clock polarity = 1)	0.5t _{C(SPC)S} -10	0.5t _C (SPC)S	ns
17§	tsu(SOMI-SPCH)S	Setup time, SPISOMI before SPICLK high (clock polarity = 0)	0.125t _C (SPC)S		20
1/3	tsu(SOMI-SPCL)S	Setup time, SPISOMI before SPICLK low (clock polarity = 1)	0.125t _C (SPC)S		ns
2	tv(SPCH-SOMI)S	Valid time, SPISOMI data valid after SPICLK high (clock polarity =0)	0.75t _C (SPC)S		
18§	tv(SPCL-SOMI)S	Valid time, SPISOMI data valid after SPICLK low (clock polarity =1)	0.75t _C (SPC)S		ns
346	tsu(SIMO-SPCH)S	Setup time, SPISIMO before SPICLK high (clock polarity = 0)	0		
21§	tsu(SIMO-SPCL)S	Setup time, SPISIMO before SPICLK low (clock polarity = 1)	0		ns
22§	tv(SPCH-SIMO)S	Valid time, SPISIMO data valid after SPICLK high (clock polarity = 0)	0.5t _C (SPC)S		ns
223	t _V (SPCL-SIMO)S	Valid time, SPISIMO data valid after SPICLK low (clock polarity = 1)	0.5t _C (SPC)S		110

[†] The MASTER/SLAVE bit (SPICTL.2) is cleared and the CLOCK PHASE bit (SPICTL.3) is set.

 $[\]ddagger$ t_C = system clock cycle time = 1/CLKOUT = $t_{C(CO)}$ \$ The active edge of the SPICLK signal referenced is controlled by the CLOCK POLARITY bit (SPICCR.6).

PARAMETER MEASUREMENT INFORMATION



[†] The SPISTE signal must be active before the SPI communication stream starts; the SPISTE signal must remain active until the SPI communication stream is complete.

Figure 35. SPI Slave Mode External Timing (Clock Phase = 1)

ADVANCE INFORMATION

external memory interface read timings

switching characteristics over recommended operating conditions for an external memory interface read (see Figure 36)

	PARAMETER	MIN	MAX	UNIT
td(COL-CNTL)	Delay time, CLKOUT low to control valid		3	ns
td(COL-CNTH)	Delay time, CLKOUT low to control inactive		3	ns
td(COL-A)RD	Delay time, CLKOUT low to address valid		5	ns
td(COH-RDL)	Delay time, CLKOUT high to RD strobe active		4	ns
td(COL-RDH)	Delay time, CLKOUT low to RD strobe inactive high	-4	0	ns
td(COL-SL)	Delay time, CLKOUT low to STRB strobe active low		3	ns
td(COL-SH)	Delay time, CLKOUT low to STRB strobe inactive high		3	ns
th(A)COL	Hold time, address valid after CLKOUT low	-4		ns
t _{su(A)RD}	Setup time, address valid before RD strobe active low	22		ns
th(A)RD	Hold time, address valid after RD strobe inactive high	-1		ns

timing requirements $[H = 0.5t_{C(CO)}]$ (see Figure 36)

		MIN	MAX	UNIT
ta(A)	Access time, read data from address valid		2H-13	ns
t _{su(D)RD}	Setup time, read data before RD strobe inactive high	12		ns
th(D)RD	Hold time, read data after RD strobe inactive high	0		ns
th(AIV-D)	Hold time, read data after address invalid	-3		ns

external memory interface read timings (continued)

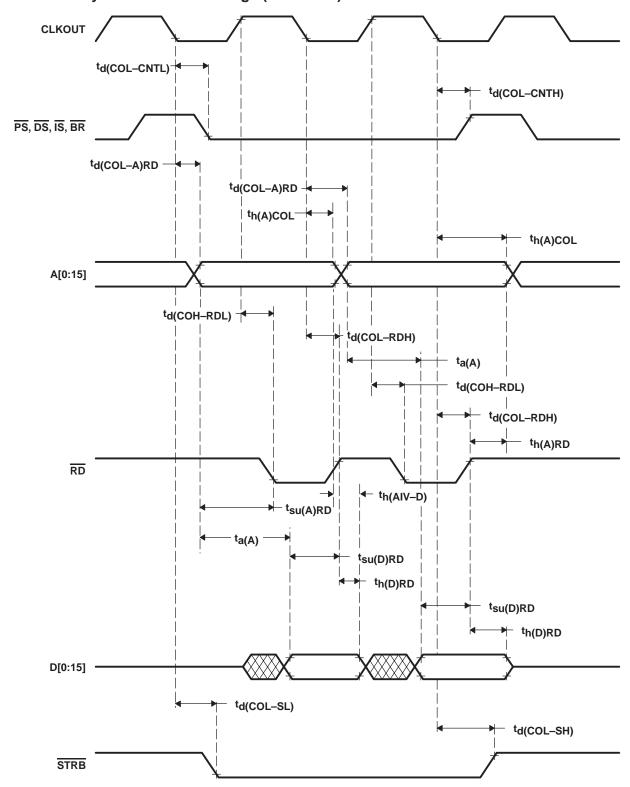


Figure 36. Memory Interface Read/Read Timings



ADVANCE INFORMATION

external memory interface write timings

switching characteristics over recommended operating conditions for an external memory interface write [H = $0.5t_{C(CO)}$] (see Figure 37)

	PARAMETER	MIN	MAX	UNIT
td(COH-CNTL)	Delay time, CLKOUT high to control valid		9	ns
td(COH-CNTH)	Delay time, CLKOUT high to control inactive		9	ns
td(COH-A)W	Delay time, CLKOUT high to address valid		11	ns
td(COH-RWL)	Delay time, CLKOUT high to R/\overline{W} low		6	ns
td(COH-RWH)	Delay time, CLKOUT high to R/W high		6	ns
td(COL-WL)	Delay time, CLKOUT low to WE strobe active low	-4	0	ns
td(COL-WH)	Delay time, CLKOUT low to WE strobe inactive high	-4	0	ns
ten(D)COL	Enable time, data bus driven from CLKOUT low	7		ns
td(COL-SL)	Delay time, CLKOUT low to STRB active low		3	ns
td(COL-SH)	Delay time, CLKOUT low to STRB inactive high		3	ns
th(A)COHW	Hold time, address valid after CLKOUT high	H–1		ns
t _{su(A)W}	Setup time, address valid before WE strobe active low	H-9		ns
t _{su(D)W}	Setup time, write data before WE strobe inactive high	2H-1		ns
th(D)W	Hold time, write data after WE strobe inactive high	3		ns
tdis(W-D)	Disable time, data bus high impedance from WE high	4		ns

external memory interface write timings (continued) CLKOUT td(COH-CNTL) td(COH-CNTH) td(COH-CNTL) ★ PS, DS, IS, BR td(COH-A)W th(A)COHW A[0:15] td(COH-RWL) td(COH-RWH) tsu(A)W R/W td(COL-WL) td(COL-WH) td(COL-WH) td(COL-WL) WE tdis(W-D) ten(D)COL ten(D)COL tsu(D)W tsu(D)W th(D)W th(D)W D[0:15] td(COL-SL) td(COL-SL) [†] td(COL-SH) td(COL-SH) STRB ENA_144 **CLKOUT** 2H 2H VIS_OE

NOTE A: ENA_144 when active low along with BVIS bits (10,9 set to 01 or 11) in register WSGR - IO@FFFFh, CLKOUT and VIS_OE will be visible at pins xx ('LF240x), and xx ('LF240x), respectively. CLKOUT and VIS_OE indicate internal memory write cycles (program/data). During VIS_OE cycles, the external bus will be driven. CLKOUT is to be used along with VIS_OE for trace capabilities.

Figure 37. Address Visibility Mode



external memory interface ready-on-read timings

switching characteristics over recommended operating conditions for an external memory interface ready-on-read (see Figure 38)

	PARAMETER	MIN	MAX	UNIT
td(COL-A)RD	Delay time, CLKOUT low to address valid		5	ns

timing requirements for an external memory interface ready-on-read (see Figure 38)

		MIN	MAX	UNIT
th(RDY)COH	Hold time, READY after CLKOUT high	-5		ns
t _{su(D)RD}	Setup time, read data before RD strobe inactive high	12		ns
t _v (RDY)ARD	Valid time, READY after address valid on read		4	ns
tsu(RDY)COH	Setup time, READY before CLKOUT high	17		ns

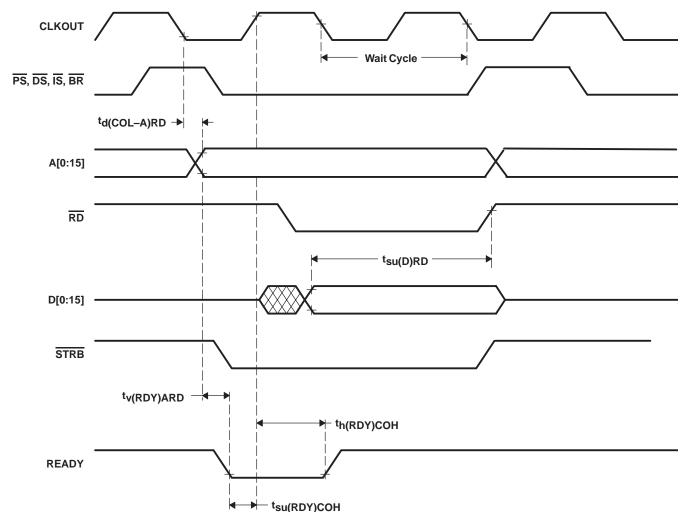


Figure 38. Ready-on-Read Timings

ADVANCE INFORMATION

external memory interface ready-on-write timings

switching characteristics over recommended operating conditions for an external memory interface ready-on-write (see Figure 39)

	PARAMETER	MIN	MAX	UNIT
td(COH-A)W	Delay time, CLKOUT high to address valid		11	ns

timing requirements for an external memory interface ready-on-write $[H = 0.5t_{C(CO)}]$ (see Figure 39)

		MIN	MAX	UNIT
th(RDY)COH	Hold time, READY after CLKOUT high	- 5		ns
t _{su(D)W}	Setup time, write data before WE strobe inactive high	2H-1	2H	ns
^t v(RDY)AW	Valid time, READY after address valid on write		4	ns
t _{su(RDY)} COH	Setup time, READY before CLKOUT high	17		ns

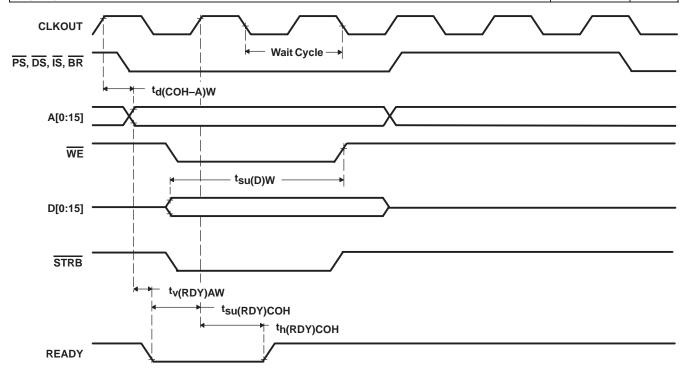


Figure 39. Ready-on-Write Timings

10-bit analog-to-digital converter (ADC)

The 10-bit ADC has a separate power bus for its analog circuitry. These pins are referred to as V_{CCA} and V_{SSA} . The power bus isolation is to enhance ADC performance by preventing digital switching noise of the logic circuitry that can be present on V_{SSA} and V_{CC} from coupling into the ADC analog stage. All ADC specifications are given with respect to V_{SSA} unless otherwise noted.

Resolution	
Monotonic	Assured
Output conversion mode	000h to 3FFh (000h for $V_1 \le V_{SSA}$; 3FFh for $V_1 \ge V_{CCA}$)
Conversion time (including sample time)	500 ns

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCCA	Analog supply voltage	3.0	3.3	3.6	V
VSSA	Analogground		0		V
VREFHI	Analog supply reference source [†]	VREFLO		VCCA	V
VREFLO	Analog ground reference source†	VSSA		VREFHI	V
VAI	Analog input voltage, ADCIN00-ADCIN07	V _{SSA}		VCCA	V

[†] V_{REFHI} and V_{REFLO} must be stable, within ±1/2 LSB of the required resolution, during the entire conversion time.

ADC operating frequency

	MIN	MAX	UNIT
ADC operating frequency		30	MHz

TMS320LF2407, TMS320LF2406, TMS320LF2402 TMS320LC2406, TMS320LC2404, TMS320LC2402 DSP CONTROLLERS

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operating characteristics over recommended operating condition ranges[†]

	PARAMETER	DESCRIPT	ΓΙΟΝ	MIN	MAX	UNIT
		V 0.0V	Converting		10	^
loca	Analog supply current	V _{CCA} = 3.3 V	Non-converting		2	mA
ICCA	Analog supply current	VCCA = VREFHI = 3.3 V	PLL or OSC power down		1	μΑ
0	Andrews	Typical capacitive load on	Non-sampling		10	5
Cai	Analog input capacitance	analog input pin	Sampling		30	pF
E _{DNL}	Differential nonlinearity error	Difference between the actual value	step width and the ideal		±2	LSB
E _{INL}	Integral nonlinearity error	Maximum deviation from the b the ADC transfer characteristic quantization error	0		±2	LSB
t _d (PU)	Delay time, power-up to ADC valid	Time to stabilize analog stage	after power-up		10	μS
Z _{AI}	Analog input source impedance	Analog input source impedance remain within specifications at			10	Ω

[†] Absolute resolution = 4.89 mV. At VREFHI = 3.3 V and VREFLO = 0 V, this is one LSB. As VREFHI decreases, VREFLO increases, or both, the LSB size decreases. Therefore, the absolute accuracy and differential/integral linearity errors in terms of LSBs increase.



internal ADC module timings (see Figure 40)

		MIN	MAX	UNIT
t _{c(AD)}	Cycle time, ADC prescaled clock	33.3		ns
tw(SHC)	Pulse duration, total sample/hold and conversion time†	500		ns
tw(SH)	Pulse duration, sample and hold time	2t _{C(AD)} ‡	32t _{C(AD)}	ns
t _{w(C)}	Pulse duration, total conversion time	10t _{C(AD)}		ns
td(SOC-SH)	Delay time, start of conversion to beginning of sample and hold	3t _C (CO)		ns
td(EOC-FIFO)	Delay time, end of conversion to data loaded into result register	2t _C (CO)		ns
td(ADCINT)	Delay time, ADC flag to ADC interrupt	2t _C (CO)		ns

 $[\]dagger$ The total sample/hold and conversion time is determined by the summation of $t_{d(SOC-SH)}$, $t_{w(SH)}$, $t_{w(C)}$, and $t_{d(EOC-FIFO)}$.

[‡] Can be varied by ACQ Prescalar bits in the ADCCTRL1 register

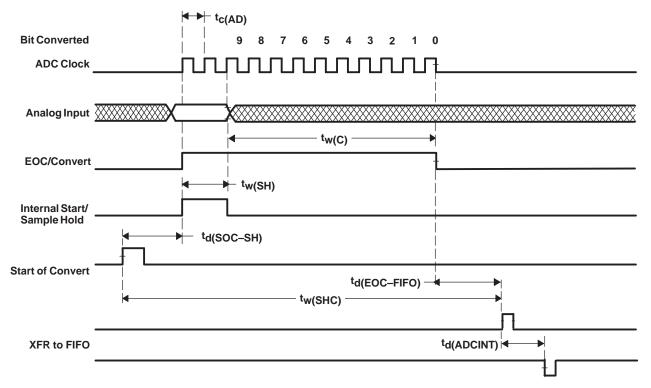


Figure 40. Analog-to-Digital Internal Module Timing

ADVANCE INFORMATION

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peripheral register description

Table 18 is a collection of all the programmable registers of the 'LF240x/'LC240x and is provided as a quick reference.

Table 18. 'LF240x/'LC240x DSP Peripheral Register Description

[BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8		
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG	
			<u> </u>	DATA MEN	MORY SPACE		<u> </u>		7	
1				CPU STATU	S REGISTERS				7	
1		ARP		OV	OVM	1	INTM	DP(8)		
ĺ	DP(7)	DP(6)	DP(5)	DP(4)	DP(3)	DP(2)	DP(1)	DP(0)	ST0	
Ī		ARB	•	CNF	TC	SXM	С	1	7	
ĺ	1	1	1	XF	1	1	ſ	PM	ST1	
			GLOBAL	MEMORY AND C	PU INTERRUPT	REGISTERS	_	_		
00004h	_	_	_	_	_	_	_	_	IMR	
0000411	_	_	INT6 MASK	INT5 MASK	INT4 MASK	INT3 MASK	INT2 MASK	INT1 MASK	livir	
00005h				Res	served				GREG	
00006h	_	_	_	_	_	_	_	_	IFR	
0000011	_	_	INT6 FLAG	INT5 FLAG	INT4 FLAG	INT3 FLAG	INT2 FLAG	INT1 FLAG	IFK	
				SYSTEM	REGISTERS					
07010h	IRQ0.15	IRQ0.14	IRQ0.13	IRQ0.12	IRQ0.11	IRQ0.10	IRQ0.9	IRQ0.8	PIRQR	
0701011	IRQ0.7	IRQ0.6	IRQ0.5	IRQ0.4	IRQ0.3	IRQ0.2	IRQ0.1	IRQ0.0	PIKQK	
07011h	IRQ1.15	IRQ1.14	IRQ1.13	IRQ1.12	IRQ1.11	IRQ1.10	IRQ1.9	IRQ1.8	PIRQR	
0/01111	IRQ1.7	IRQ1.6	IRQ1.5	IRQ1.4	IRQ1.3	IRQ1.2	IRQ1.1	IRQ1.0	PIKQK	
07012h	Reserved									
07013h	Reserved									
07014h	IAK0.15	IAK0.14	IAK0.13	IAK0.12	IAK0.11	IAK0.10	IAK0.9	IAK0.8	PIACKI	
0701411	IAK0.7	IAK0.6	IAK0.5	IAK0.4	IAK0.3	IAK0.2	IAK0.1	IAK0.0	PIACKI	
07015h	IAK1.15	IAK1.14	IAK1.13	IAK1.12	IAK1.11	IAK1.10	IAK1.9	IAK1.8	PIACKI	
070150	IAK1.7	IAK1.6	IAK1.5	IAK1.4	IAK1.3	IAK1.2	IAK1.1	IAK1.0	PIACKI	
07016h				Res	served				PIACKI	
07017h				Res	served					
070405	OSC FAIL FLAG	CLKSRC	LPM1	LPM0	CLK PS2	CLK PS1	CLK PS0	OSC FAIL RESET	000004	
07018h	ADC CLKEN	SCI CLKEN	SPI CLKEN	CAN CLKEN	EVB CLKEN	EVA CLKEN	NMI EN (test only)	ILLADR	SCSR1	
	_	_	_	_	_	_	_	_		
07019h	_	_	WD OVERRIDE	XMIF HI Z	BOOT_EN	MP/MC	DON	PON	SCSR2	
0701Ah to 0701Bh				Res	served				1	
	DIN15	DIN14	DIN13	DIN12	DIN11	DIN10	DIN9	DIN8	┪	
0701Ch	DIN7	DIN6	DIN5	DIN4	DIN3	DIN2	DIN1	DIN0	DINR	
0701Dh		==			served				┪	
	V15	V14	V13	V12	V11	V10	V9	V8	┪	
0701Eh	V7	V6	V 10	V4	V3	V2	V1	V0	PIVR	
					served				\dashv	



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
				WD CONTRO	OL REGISTERS			•	
07020h to 07022h				Res	served				1
07023h	D7	D6	D5	D4	D3	D2	D1	D0	WDCNTR
07024h				Res	served				
07025h	D7	D6	D5	D4	D3	D2	D1	D0	WDKEY
07026h to 07028h				Res	served				
07029h	WD FLAG	WDDIS	WDCHK2	WDCHK1	WDCHK0	WDPS2	WDPS1	WDPS0	WDCR
0702Ah to 07031h				Res	served				
07032h to 07038h				Res	served				
07039h to 0703Fh				Res	served				1
		SERIAL	PERIPHERAL IN	ITERFACE (SPI)	CONFIGURATI	ION CONTROL R	EGISTERS		
07040h	SPI SW RESET	CLOCK POLARITY	_	_	SPI CHAR3	SPI CHAR2	SPI CHAR1	SPI CHAR0	SPICCR
07041h	_	_	_	OVERRUN INT ENA	CLOCK PHASE	MASTER/ SLAVE	TALK	SPI INT ENA	SPICTL
07042h	RECEIVER OVERRUN FLAG	SPI INT FLAG	TX BUF FULL FLAG	ı	I	_	_	_	SPISTS
07043h				Res	served				
07044h	_	SPI BIT RATE 6	SPI BIT RATE 5	SPI BIT RATE 4	SPI BIT RATE 3	SPI BIT RATE 2	SPI BIT RATE 1	SPI BIT RATE 0	SPIBRR
07045h				Res	served				
07046h	ERXB15	ERXB14	ERXB13	ERXB12	ERXB11	ERXB10	ERXB9	ERXB8	SPIRXEMU
	ERXB7	ERXB6	ERXB5	ERXB4	ERXB3	ERXB2	ERXB1	ERXB0	_
07047h	RXB15	RXB14	RXB13	RXB12	RXB11	RXB10	RXB9	RXB8	SPIRXBUF
	RXB7	RXB6	RXB5	RXB4	RXB3	RXB2	RXB1	RXB0	
07048h	TXB15	TXB14	TXB13	TXB12	TXB11	TXB10	TXB9	TXB8	SPITXBUF
	TXB7	TXB6	TXB5	TXB4	TXB3	TXB2	TXB1	TXB0	_
07049h	SDAT15	SDAT14	SDAT13	SDAT12	SDAT11	SDAT10	SDAT9	SDAT8 SDAT0	SPIDAT
0704Ah	SDAT7	SDAT6	SDAT5	SDAT4	SDAT3	SDAT2	SDAT1	SDATO	\dashv
to 0704Eh				Res	served				
0704Fh	_	SPI PRIORITY	SPI SUSP SOFT	SPI SUSP FREE	_	_	_	_	SPIPRI



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	7
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		SERIAL CO	MMUNICATION	S INTERFACE (S	SCI) CONFIGUR	ATION CONTRO	L REGISTERS		1
07050h	STOP BITS	EVEN/ODD PARITY	PARITY ENABLE	LOOP BACK ENA	ADDR/IDLE MODE	SCI CHAR2	SCI CHAR1	SCI CHAR0	SCICCR
07051h	_	RX ERR INT ENA	SW RESET	_	TXWAKE	SLEEP	TXENA	RXENA	SCICTL1
07052h	BAUD15 (MSB)	BAUD14	BAUD13	BAUD12	BAUD11	BAUD10	BAUD9	BAUD8	SCIHBAUD
07053h	BAUD7	BAUD6	BAUD5	BAUD4	BAUD3	BAUD2	BAUD1	BAUD0 (LSB)	SCILBAUD
07054h	TXRDY	TX EMPTY	_	_	_	_	RX/BK INT ENA	TX INT ENA	SCICTL2
07055h	RX ERROR	RXRDY	BRKDT	FE	OE	PE	RXWAKE	_	SCIRXST
07056h	ERXDT7	ERXDT6	ERXDT5	ERXDT4	ERXDT3	ERXDT2	ERXDT1	ERXDT0	SCIRXEMU
07057h	RXDT7	RXDT6	RXDT5	RXDT4	RXDT3	RXDT2	RXDT1	RXDT0	SCIRXBUF
07058h				Re	served				
07059h	TXDT7	TXDT6	TXDT5	TXDT4	TXDT3	TXDT2	TXDT1	TXDT0	SCITXBUF
0705Ah to 0705Eh				Re	served				
0705Fh	_	SCITX PRIORITY	SCIRX PRIORITY	SCI SOFT	SCI FREE	_	_	_	SCIPRI
07060h				•					1
to 0706Fh				Re	served				
0700111			FXTER	NAL INTERRUF	PT CONTROL RE	GISTERS			1
	XINT1	1	LXILI	I	TOOKINGE KE	OIOTERO	1		1
	FLAG	_	_	_	_	_	_	_	VII.IT. (0.D.
07070h	_	_	_	_	_	XINT1 POLARITY	XINT1 PRIORITY	XINT1 ENA	XINT1CR
070745	XINT2 FLAG	_	_	_	_	_	_	_	VINITOOD
07071h	_	_	_	_	_	XINT2 POLARITY	XINT2 PRIORITY	XINT2 ENA	XINT2CR
07072h to 0708Fh				Re	served				
				DIGITAL I/O CON	NTROL REGISTE	ERS			1
	MCRA.15	MCRA.14	MCRA.13	MCRA.12	MCRA.11	MCRA.10	MCRA.9	MCRA.8	
07090h	MCRA.7	MCRA.6	MCRA.5	MCRA.4	MCRA.3	MCRA.2	MCRA.1	MCRA.0	MCRA
07091h			•	Re	served	•	•	•	1
070001	MCRB.15	MCRB.14	MCRB.13	MCRB.12	MCRB.11	MCRB.10	MCRB.9	MCRB.8	14055
07092h	MCRB.7	MCRB.6	MCRB.5	MCRB.4	MCRB.3	MCRB.2	MCRB.1	MCRB.0	MCRB
07093h				Re	served				
07004	MCRC.15	MCRC.14	MCRC.13	MCRC.12	MCRC.11	MCRC.10	MCRC.9	MCRC.8	MODO
07094h	MCRC.7	MCRC.6	MCRC.5	MCRC.4	MCRC.3	MCRC.2	MCRC.1	MCRC.0	MCRC
070054	E7DIR	E6DIR	E5DIR	E4DIR	E3DIR	E2DIR	E1DIR	E0DIR	חבריים
07095h	IOPE7	IOPE6	IOPE5	IOPE4	IOPE3	IOPE2	IOPE1	IOPE0	PEDATDIR

Indicates change with respect to the 'F243/'F241, 'C242 device register maps.



ADVANCE INFORMATION

Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	1
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		<u> </u>	DIGITAL I	O CONTROL R	EGISTERS (CO	NTINUED)	<u> </u>		1
.=	F7DIR	F6DIR	F5DIR	F4DIR	F3DIR	F2DIR	F1DIR	F0DIR	
07096h	IOPF7	IOPF6	IOPF5	IOPF4	IOPF3	IOPF2	IOPF1	IOPF0	PFDATDIR
.=	A7DIR	A6DIR	A5DIR	A4DIR	A3DIR	A2DIR	A1DIR	A0DIR	1
07098h	IOPA7	IOPA6	IOPA5	IOPA4	IOPA3	IOPA2	IOPA1	IOPA0	PADATDIR
07099h		•	•	Res	erved	•	•		1
070045	B7DIR	B6DIR	B5DIR	B4DIR	B3DIR	B2DIR	B1DIR	B0DIR	DDDATDID
0709Ah	IOPB7	IOPB6	IOPB5	IOPB4	IOPB3	IOPB2	IOPB1	IOPB0	PBDATDIR
0709Bh				Res	erved]
0700Ch	C7DIR	C6DIR	C5DIR	C4DIR	C3DIR	C2DIR	C1DIR	C0DIR	DCDATDID
0709Ch	IOPC7	IOPC6	IOPC5	IOPC4	IOPC3	IOPC2	IOPC1	IOPC0	PCDATDIR
0709Dh				Res	erved]
0700Eh	D7DIR	D6DIR	D5DIR	D4DIR	D3DIR	D2DIR	D1DIR	D0DIR	DDDATDIB
0709Eh	IOPD7	IOPD6	IOPD5	IOPD4	IOPD3	IOPD2	IOPD1	IOPD0	PDDATDIR
0709Fh				Res	erved]
			ANALOG-TO	D-DIGITAL CON	VERTER (ADC)	REGISTERS			
	_	ADC	SOFT	FREE	ACQ	ACQ	ACQ	ACQ	1
070A0h		S/W RESET			PRESCALE3	PRESCALE2	PRESCALE1	PRESCALE0	ADCCTRL1
	CONV PRE- SCALE (CPS)	CONTIN- UOUS RUN	INT PRIORITY	SEQ1/2 CASCADE	CALIB EN	BRIDGE EN	HI / LO	FSTEST EN	
	EVB SOC EN SEQ1	Reset SEQ1 Start CALIB	SOC SEQ1	SEQ1 BUSY	INT ENA SEQ1 Mode1	INT ENA SEQ1 Mode0	INT FLAG SEQ1	EVA SOC EN SEQ1	
070A1h	EXT SOC EN SEQ1	Reset SEQ2	SOC SEQ2	SEQ2 BUSY	INT ENA SEQ2 Mode1	INT ENA SEQ2 Mode0	INT FLAG SEQ2	EVB SOC EN SEQ2	ADCCTRL2
	_	_	_	_	_	_	_	_	1
070A2h	_	MAXCONV2 2	MAXCONV2 1	MAXCONV2 0	MAXCONV1 3	MAXCONV1 2	MAXCONV1 1	MAXCONV1 0	MAXCONV
	CONV 3	CONV 3	CONV 3	CONV 3	CONV 2	CONV 2	CONV 2	CONV 2	1
070A3h	CONV 1	CONV 1	CONV 1	CONV 1	CONV 0	CONV 0	CONV 0	CONV 0	CHSELSEQ1
	CONV 7	CONV 7	CONV 7	CONV 7	CONV 6	CONV 6	CONV 6	CONV 6	1
070A4h	CONV 5	CONV 5	CONV 5	CONV 5	CONV 4	CONV 4	CONV 4	CONV 4	CHSELSEQ2
	CONV 11	CONV 11	CONV 11	CONV 11	CONV 10	CONV 10	CONV 10	CONV 10	
070A5h	CONV 9	CONV 9	CONV 9	CONV 9	CONV 8	CONV 8	CONV 8	CONV 8	CHSELSEQ3
070465	CONV 15	CONV 15	CONV 15	CONV 15	CONV 14	CONV 14	CONV 14	CONV 14	011051.0504
070A6h	CONV 13	CONV 13	CONV 13	CONV 13	CONV 12	CONV 12	CONV 12	CONV 12	CHSELSEQ4
	_	_	_	_	SEQ CNTR3	SEQ CNTR2	SEQ CNTR1	SEQ CNTR0	1
070A7h	SEQ2-STATE	SEQ2 STATE 2	SEQ2 STATE 1	SEQ2 STATE 0	SEQ1-STATE	SEQ1-STATE	SEQ1 STATE 1	SEQ1-STATE 0	AUTO_SEQ_SR
	D9	D8	D7	D6	D5	D4	D3	D2	1
070A8h	D3	D0	0	0	0	0	0	0	RESULT0
	D1	D8	D7	D6	D5	D4	D3	D2	1
070A9h	D9 D1	D0	0	0	0	0	0	0	RESULT1
									-
070AAh	D9	D8	D7	D6	D5	D4	D3	D2	RESULT2
	D1	D0	0	0	0	0	0	0	J



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

ADDB	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	7
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		AN	ALOG-TO-DIGIT	AL CONVERTE	R (ADC) REGIS	TERS (CONTIN	UED)		7
070 A D L	D9	D8	D7	D6	D5	D4	D3	D2	DECLUTO
070ABh	D1	D0	0	0	0	0	0	0	RESULT3
070406	D9	D8	D7	D6	D5	D4	D3	D2	DECLUTA
070ACh	D1	D0	0	0	0	0	0	0	RESULT4
070406	D9	D8	D7	D6	D5	D4	D3	D2	DECLUTE
070ADh	D1	D0	0	0	0	0	0	0	RESULT5
070AEh	D9	D8	D7	D6	D5	D4	D3	D2	RESULT6
UTUALII	D1	D0	0	0	0	0	00	0	RESULIO
070AFh	D9	D8	D7	D6	D5	D4	D3	D2	RESULT7
070ALII	D1	D0	0	0	0	0	0	0	RESOLIT
070B0h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT8
0700011	D1	D0	0	0	0	0	0	0	RESOLIO
070B1h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT9
0700111	D1	D0	0	0	0	0	0	0	_ KESOLIS
070B2h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT10
0700211	D1	D0	0	0	0	0	0	0	_ KESOLI 10
070B3h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT11
0700311	D1	D0	0	0	0	0	0	0	_ KESOLI II
070B4h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT12
0700411	D1	D0	0	0	0	0	0	0	_ KEGGEI 12
070B5h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT13
0702011	D1	D0	0	0	0	0	0	0	
070B6h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT14
0702011	D1	D0	0	0	0	0	0	0	
070B7h	D9	D8	D7	D6	D5	D4	D3	D2	RESULT15
0.02	D1	D0	0	0	0	0	0	0	
070B8h		<u> </u>						 	CALIBRATION
070B9h to 070FFh				Res	erved				
		CONTRO	LLER AREA NE	TWORK (CAN)	CONFIGURATION	ON CONTROL R	EGISTERS		7
.=	_	_	_	_	_	_	_	_	٦.,,,,,,,
07100h	MD3	MD2	ME5	ME4	ME3	ME2	ME1	ME0	MDER
	TA5	TA4	TA3	TA2	AA5	AA4	AA3	AA2	7
07101h	TRS5	TRS4	TRS3	TRS2	TRR5	TRR4	TRR3	TRR2	TCR
074001	RFP3	RFP2	RFP1	RFP0	RML3	RML2	RML1	RML0	
07102h	RMP3	RMP2	RMP1	RMP0	OPC3	OPC2	OPC1	OPC0	RCR
07400	_	_	SUSP	CCR	PDR	DBO	WUBA	CDR	7,400
07103h	ABO	STM	_	_	_	_	MBNR1	MBNR0	MCR
074046	_	_	_	_	_	_	_	_	DCD2
07104h	BRP7	BRP6	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0	BCR2



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

	BIT 15	DIT 44	DIT 40	DIT 40	DIT 44	DIT 40	DIT 0	BIT 8	٦
ADDR	BIT 7	BIT 14 BIT 6	BIT 13 BIT 5	BIT 12 BIT 4	BIT 11 BIT 3	BIT 10 BIT 2	BIT 9 BIT 1	BIT 0	REG
						NTROL REGISTE			
		_	_		_	SBG	SJW1	SJW0	
07105h	SAM	TSEG1-3	TSEG1-2	TSEG1-1	TSEG1-0	TSEG2-2	TSEG2-1	TSEG2-0	BCR1
	—	_	—	_	—	—	—	FER	
07106h	BEF	SA1	CRCE	SER	ACKE	ВО	EP	EW	ESR
	_	_	_	_	_		_	_	
07107h	_	_	SMA	CCE	PDA	_	RM	TM	GSR
	TEC7	TEC6	TEC5	TEC4	TEC3	TEC2	TEC1	TEC0	
07108h	REC7	REC6	REC5	REC4	REC3	REC2	REC1	REC0	CEC
	_	_	MIF5	MIF4	MIF3	MIF2	MIF1	MIF0	
07109h	_	RMLIF	AAIF	WDIF	WUIF	BOIF	EPIF	WLIF	CAN_IFR
	MIL	_	MIM5	MIM4	MIM3	MIM2	MIM1	MIMO	T
0710Ah	EIL	RMLIM	AAIM	WDIM	WUIM	BOIM	EPIM	WLIM	CAN_IMR
	LAMI	_	_	LAM0-28	LAM0-27	LAM0-26	LAM0-25	LAM0-24	T
0710Bh	LAM0-23	LAM0-22	LAM0-21	LAM0-20	LAM0-19	LAM0-18	LAM0-17	LAM0-16	LAM0_H
	LAM0-15	LAM0-14	LAM0-13	LAM0-12	LAM0-11	LAM0-10	LAM0-9	LAM0-8	-
0710Ch	LAM0-7	LAM0-6	LAM0-5	LAM0-4	LAM0-3	LAM0-2	LAM0-1	LAM0-0	LAM0_L
074001	LAMI	_	_	LAM1-28	LAM1-27	LAM1-26	LAM1-25	LAM1-24	Ī.,,,,,
0710Dh	LAM1-23	LAM1-22	LAM1-21	LAM1-20	LAM1-19	LAM1-18	LAM1-17	LAM1-16	LAM1_H
074056	LAM1-15	LAM1-14	LAM1-13	LAM1-12	LAM1-11	LAM1-10	LAM1-9	LAM1-8	1 0 0 0 1
0710Eh	LAM1-7	LAM1-6	LAM1-5	LAM1-4	LAM1-3	LAM1-2	LAM1-1	LAM1-0	LAM1_L
0710Fh									
to 071FFh				Res	served				
U/ IFFII				Manager	01-1				-
	IDI 45	IDI 44	IDI 40		Object #0	IDI 40	IDI. O	IDL 0	-
07200h	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	MSGID0L
	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	
07201h	IDE IDH–23	AME IDH-22	IDH-21	IDH-28 IDH-20	IDH-27 IDH-19	IDH-26 IDH-18	IDH-25 IDH-17	IDH–24 IDH–16	MSGID0H
	IDH-23	IDH-22	IDH-ZI	1011-20	100-19	1011-10	100-17	100-16	
07202h		<u> </u>	 	RTR	DLC3	DLC2	DLC1	DLC0	MSGCTRL0
07203h		_	_		served	DLOZ	DLCT	DLCO	-
0720311	D15	D14	D13	D12	D11	D10	D9	D8	
07204h	D13	D6	D15	D12	D3	D10	D1	D0	MBX0A
	D15	D14	D13	D12	D11	D10	D9	D8	
07205h	D13	D6	D13	D12	D3	D10	D3	D0	MBX0B
	D15	D14	D13	D12	D11	D10	D9	D8	1
07206h	D13	D6	D15	D12	D3	D10	D3	D0	MBX0C
	D15	D14	D13	D12	D11	D10	D9	D8	1
07207h	D7	D6	D5	D4	D3	D2	D1	D0	MBX0D
		1 20	<u> </u>	<u> </u>		L 22	<u> </u>	1 50	J



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	7
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
	C	ONTROLLER A	REA NETWORI	K (CAN) CONFI	GURATION CON	NTROL REGISTE	RS (CONTINUE	ED)	7
				Message	Object #1				7
	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	7
07208h	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	MSGID1L
	IDE	AME	AAM	IDH-28	IDH-27	IDH-26	IDH-25	IDH-24	1
07209h	IDH-23	IDH-22	IDH-21	IDH-20	IDH-19	IDH–18	IDH-17	IDH–16	MSGID1H
	_	_	_	_	_	_	_	_	1
0720Ah	_	i –	_	RTR	DLC3	DLC2	DLC1	DLC0	MSGCTRL1
0720Bh		•		Res	erved			•	7
	D15	D14	D13	D12	D11	D10	D9	D8	1
0720Ch	D7	D6	D5	D4	D3	D2	D1	D0	MBX1A
	D15	D14	D13	D12	D11	D10	D9	D8	٦
0720Dh	D7	D6	D5	D4	D3	D2	D1	D0	MBX1B
.=	D15	D14	D13	D12	D11	D10	D9	D8	T
0720Eh	D7	D6	D5	D4	D3	D2	D1	D0	MBX1C
07005	D15	D14	D13	D12	D11	D10	D9	D8	
0720Fh	D7	D6	D5	D4	D3	D2	D1	D0	MBX1D
		•		Message	Object #2		•	•	7
	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	1
07210h	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	MSGID2L
	IDE	AME	AAM	IDH-28	IDH-27	IDH-26	IDH-25	IDH-24	1
07211h	IDH-23	IDH-22	IDH-21	IDH-20	IDH-19	IDH-18	IDH–17	IDH–16	MSGID2H
	_	_	_	_	_	_	_	_	1
07212h	_	i –	_	RTR	DLC3	DLC2	DLC1	DLC0	MSGCTRL2
07213h		•		Res	erved			•	7
	D15	D14	D13	D12	D11	D10	D9	D8	-
07214h	D7	D6	D5	D4	D3	D2	D1	D0	MBX2A
	D15	D14	D13	D12	D11	D10	D9	D8	1
07215h	D7	D6	D5	D4	D3	D2	D1	D0	MBX2B
	D15	D14	D13	D12	D11	D10	D9	D8	7
07216h	D7	D6	D5	D4	D3	D2	D1	D0	MBX2C
	D15	D14	D13	D12	D11	D10	D9	D8	٦
07217h	D7	D6	D5	D4	D3	D2	D1	D0	MBX2D
		•		Message	Object #3			•	7
	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	7
07218h	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	MSGID3L
	IDE	AME	AAM	IDH-28	IDH-27	IDH-26	IDH-25	IDH-24	7
07219h	IDH-23	IDH-22	IDH-21	IDH-20	IDH-19	IDH-18	IDH-17	IDH-16	MSGID3H
	_	_	_	_	_	_	_	_	┨
0721Ah	_	<u> </u>	_	RTR	DLC3	DLC2	DLC1	DLC0	MSGCTRL3
0721Bh		•	·	l	erved				1
	D15	D14	D13	D12	D11	D10	D9	D8	7
0721Ch	D7	D6	D5	D4	D3	D2	D1	D0	MBX3A
ı									_



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

4000	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	1
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		CONTROLLER	AREA NETWOR	K (CAN) CONFI	GURATION CON	TROL REGISTE	RS (CONTINUE	D)	1
0=0.4B1	D15	D14	D13	D12	D11	D10	D9	D8	1
0721Dh	D7	D6	D5	D4	D3	D2	D1	D0	MBX3B
070456	D15	D14	D13	D12	D11	D10	D9	D8	MDV2C
0721Eh	D7	D6	D5	D4	D3	D2	D1	D0	MBX3C
0721Fh	D15	D14	D13	D12	D11	D10	D9	D8	MBX3D
0/21711	D7	D6	D5	D4	D3	D2	D1	D0	INIDX3D
				Messag	e Object #4				
070001	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	MOOID
07220h	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	MSGID4L
070046	IDE	AME	AAM	IDH-28	IDH-27	IDH-26	IDH-25	IDH-24	Mecipali
07221h	IDH-23	IDH-22	IDH-21	IDH-20	IDH-19	IDH-18	IDH-17	IDH-16	MSGID4H
070006	_	_	_	_	_	_	_	_	MSGCTRL4
07222h	_	_	_	RTR	DLC3	DLC2	DLC1	DLC0	WSGC1RL4
07223h				Res	served				
070046	D15	D14	D13	D12	D11	D10	D9	D8	MBX4A
07224h	D7	D6	D5	D4	D3	D2	D1	D0	IVIDA4A
072256	D15	D14	D13	D12	D11	D10	D9	D8	MBX4B
07225h	D7	D6	D5	D4	D3	D2	D1	D0	IVIDA46
07226h	D15	D14	D13	D12	D11	D10	D9	D8	MBX4C
0722011	D7	D6	D5	D4	D3	D2	D1	D0	WIDX4C
07227h	D15	D14	D13	D12	D11	D10	D9	D8	MBX4D
0722711	D7	D6	D5	D4	D3	D2	D1	D0	WIDA4D
				Messag	e Object #5				
070006	IDL-15	IDL-14	IDL-13	IDL-12	IDL-11	IDL-10	IDL-9	IDL-8	MOCIDEL
07228h	IDL-7	IDL-6	IDL-5	IDL-4	IDL-3	IDL-2	IDL-1	IDL-0	MSGID5L
072206	IDE	AME	AAM	IDH-28	IDH-27	IDH-26	IDH-25	IDH-24	MECIDER
07229h	IDH-23	IDH-22	IDH-21	IDH-20	IDH-19	IDH-18	IDH-17	IDH-16	MSGID5H
0722Ah	_	_	_	_	_	_	_	_	MSGCTRL5
UZZAII	_	_	_	RTR	DLC3	DLC2	DLC1	DLC0	WISGUTKES
0722Bh				Res	served				
0722Ch	D15	D14	D13	D12	D11	D10	D9	D8	MBX5A
0722011	D7	D6	D5	D4	D3	D2	D1	D0	IVIDAJA
0722Dh	D15	D14	D13	D12	D11	D10	D9	D8	MBX5B
0722011	D7	D6	D5	D4	D3	D2	D1	D0	IVIDAGE
0722Eh	D15	D14	D13	D12	D11	D10	D9	D8	MBX5C
07 ZZLII	D7	D6	D5	D4	D3	D2	D1	D0	WIDXOC
0722Fh	D15	D14	D13	D12	D11	D10	D9	D8	MBX5D
0122111	D7	D6	D5	D4	D3	D2	D1	D0	MIDYOD
07230h to 073FFh				Re	served				



ADVANCE INFORMATION

peripheral register description (continued)

Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

ADDR	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	1
ADDK	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		GENERA	L-PURPOSE (G	P) TIMER CONF	IGURATION CO	ONTROL REGIST	TERS – EVA		
07400h	_	T2STAT	T1STAT	-	-	T2TC	ADC	T1TOADC(1)	GPTCONA
0740011	T1TOADC(0)	TCOMPOE	-	_	T2	PIN	T	1PIN	GFTCONA
07401h	D15	D14	D13	D12	D11	D10	D9	D8	T1CNT
0740111	D7	D6	D5	D4	D3	D2	D1	D0	
07402h	D15	D14	D13	D12	D11	D10	D9	D8	T1CMPR
0740211	D7	D6	D5	D4	D3	D2	D1	D0	I TOWN IX
07403h	D15	D14	D13	D12	D11	D10	D9	D8	T1PR
	D7	D6	D5	D4	D3	D2	D1	D0	I I I I K
07404h	FREE	SOFT	_	TMODE1	TMODE0	TPS2	TPS1	TPS0	T1CON
0740411	TSWT1	TENABLE	TCLKS1	TCLKS0	TCLD1	TCLD0	TECMPR	SELT1PR	TICON
07405h	D15	D14	D13	D12	D11	D10	D9	D8	T2CNT
0740311	D7	D6	D5	D4	D3	D2	D1	D0	
07406h	D15	D14	D13	D12	D11	D10	D9	D8	T2CMPR
0740011	D7	D6	D5	D4	D3	D2	D1	D0	
07407h	D15	D14	D13	D12	D11	D10	D9	D8	T2PR
07407h	D7	D6	D5	D4	D3	D2	D1	D0	
07408h	FREE	SOFT	_	TMODE1	TMODE0	TPS2	TPS1	TPS0	TOCON
0740811	TSWT1	TENABLE	TCLKS1	TCLKS0	TCLD1	TCLD0	TECMPR	SELT1PR	T2CON
07409h					1				
to 07410h				Ke	served				
	FULL AND SIMPLE COMPARE UNIT REGISTERS – EVA								
	CENABLE	CLD1	CLD0	SVENABLE	ACTRLD1	ACTRLD0	FCOMPOE	_	1
07411h	_	_	<u> </u>	_	_	_	<u> </u>	_	COMCONA
07412h		1	1	Re	served		1		1
	SVRDIR	D2	D1	D0	CMP6ACT1	CMP6ACT0	CMP5ACT1	CMP5ACT0	1
07413h	CMP4ACT1	CMP4ACT0	CMP3ACT1	CMP3ACT0	CMP2ACT1	CMP2ACT0	CMP1ACT1	CMP1ACT0	ACTRA
07414h				l .	served			l	1
	_	_	_	_	DBT3	DBT2	DBT1	DBT0	1
07415h	EDBT3	EDBT2	EDBT1	DBTPS2	DBTPS1	DBTPS0	_	_	DBTCONA
07416h				Re	served			ı	1
	D15	D14	D13	D12	D11	D10	D9	D8	1
07417h	D7	D6	D5	D4	D3	D2	D1	D0	CMPR1
	D15	D14	D13	D12	D11	D10	D9	D8	1
07418h	D7	D6	D5	D4	D3	D2	D1	D0	CMPR2
	D15	D14	D13	D12	D11	D10	D9	D8	1
07419h	D7	D6	D5	D4	D3	D2	D1	D0	CMPR3
0741Ah		<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	<u> </u>	1
to				Res	served				
0741Fh									J



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

ADDR	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8]
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
			(CAPTURE UNIT	REGISTERS -	EVA			
074006	CAPRES	CAPO	QEPN	CAP3EN	_	CAP3TSEL	CAP12TSEL	CAP3TOADC	CARCONA
07420h	CAP1	EDGE	CAP2	EDGE	CAP3	BEDGE		_	CAPCONA
07421h				Re	served				
07422h	— CAP3FIFO CAP2FIFO CAP1FIFO		P1FIFO	CAPFIFOA					
0742211	_	_	_	_	_	_	_	_	CAPPIFOA
07423h	D15	D14	D13	D12	D11	D10	D9	D8	CAP1FIFO
0742311	D7	D6	D5	D4	D3	D2	D1	D0	CAFILIO
07424h	D15	D14	D13	D12	D11	D10	D9	D8	CAP2FIFO CAP3FIFO
0742411	D7	D6	D5	D4	D3	D2	D1	D0	
07425h	D15	D14	D13	D12	D11	D10	D9	D8	
0742011	D7	D6	D5	D4	D3	D2	D1	D0	0711 01 11 0
07426h				Re	served				_
07427h	D15	D14	D13	D12	D11	D10	D9	D8	CAP1FBOT
0742711	D7	D6	D5	D4	D3	D2	D1	D0	CAFIFBUI
07428h	D15	D14	D13	D12	D11	D10	D9	D8	CAP2FBOT
0742011	D7	D6	D5	D4	D3	D2	D1	D0	3/11/21/201
07429h	D15	D14	D13	D12	D11	D10	D9	D8	CAP3FBOT
07 12011	D7	D6	D5	D4	D3	D2	D1	D0	0,11 01 20 1
0742Ah				Do	served				
to 0742Bh				Ke	served				
			EVENT MANA	GER (EVA) INT	ERRUPT CONT	ROL REGISTERS	 S		1
						T10FINT	T1UFINT	T1CINT	1
0742Ch	_	_	_	_	_	ENA	ENA	ENA	EVAIMRA
0742011	T1PINT	_	_	_	CMP3INT	CMP2INT	CMP1INT	PDPINT	EVAIIVIKA
	ENA				ENA	ENA	ENA	ENA	4
07.4001			_	<u> </u>	_	_	_		
0742Dh	_	_	_	_	T2OFINT ENA	T2UFINT ENA	T2CINT ENA	T2PINT ENA	EVAIMRB
			_	_					1
0742Eh				<u> </u>	! 	CAP3INT	CAP2INT	CAP1INT	EVAIMRC
	_	_	_	_	_	ENA	ENA	ENA	
	_		_	_	_	T10FINT	T1UFINT	T1CINT	1
0742Fh					ļ	FLAG	FLAG	FLAG	EVAIFRA
01 121 11	T1PINT	_	_	_	CMP3INT	CMP2INT	CMP1INT	PDPINT	
	FLAG				FLAG	FLAG	FLAG	FLAG	4
07430h	_	<u> </u>		_	TOOFINIT	TOLICINIT	TOCINIT	—	EVAIFRB
0743011	_	_	_	_	T2OFINT FLAG	T2UFINT FLAG	T2CINT FLAG	T2PINT FLAG	LVAII KD
	_	_	_	_	_	_	_	_	1
07431h				! 		CAP3INT	CAP2INT	CAP1INT	EVAIFRC
	_	_	_	_	_	FLAG	FLAG	FLAG	
07432h									1
to 074FFh				Re	served				
07-71111									J



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

DDR	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	REG
	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
		GENERA	L-PURPOSE (G	P) TIMER CONF	IGURATION CO	NTROL REGIST	ERS – EVB		
500h	_	T4STAT	T3STAT	-	-	T4TC	ADC	T3TOADC(1)	GPTCONB
OUII	T3TOADC(0)	TCOMPOEB	-	_	T4	PIN	T3	BPIN	GFICOND
501h	D15	D14	D13	D12	D11	D10	D9	D8	T3CNT
0111	D7	D6	D5	D4	D3	D2	D1	D0	TSCIVI
02h	D15	D14	D13	D12	D11	D10	D9	D8	T3CMPR
0211	D7	D6	D5	D4	D3	D2	D1	D0	- TSCIVIFIC
03h	D15	D14	D13	D12	D11	D10	D9	D8	T3PR
JOH	D7	D6	D5	D4	D3	D2	D1	D0	
046	FREE	SOFT	_	TMODE1	TMODE0	TPS2	TPS1	TPS0	T3CON
04h	TSWT3	TENABLE	TCLKS3	TCLKS0	TCLD1	TCLD0	TECMPR	SELT1PR	
	D15	D14	D13	D12	D11	D10	D9	D8	1
05h	D7	D6	D5	D4	D3	D2	D1	D0	T4CNT
	D15	D14	D13	D12	D11	D10	D9	D8	T4CMPR
06h	D7	D6	D5	D4	D3	D2	D1	D0	
	D15	D14	D13	D12	D11	D10	D9	D8	T4PR
07h	D7	D6	D5	D4	D3	D2	D1	D0	
	FREE	SOFT	_	TMODE1	TMODE0	TPS2	TPS1	TPS0	T4CON
08h	TSWT1	TENABLE	TCLKS1	TCLKS0	TCLD1	TCLD0	TECMPR	SELT3PR	
09h 10h			EUL AND		served	ICTEDO EVO			
	OFNIABLE	01.04		SIMPLE COMP	1	ı	FOOMBOED		-
11h	CENABLE	CLD1	CLD0	SVENABLE	ACTRLD1	ACTRLD0	FCOMPOEB	_	COMCONB
	_	_	_			_	_	_	4
12h				ī	served				4
13h	SVRDIR	D2	D1	D0	CMP12ACT1	CMP12ACT0	CMP11ACT1	CMP11ACT0	ACTRB
	CMP10ACT1	CMP10ACT0	CMP9ACT1	CMP9ACT0	CMP8ACT1	CMP8ACT0	CMP7ACT1	CMP7ACT0	_
14h				Re	served	1			
15h				<u> </u>	DBT3	DBT2	DBT1	DBT0	DBTCONB
	EDBT3	EDBT2	EDBT1	DBTPS2	DBTPS1	DBTPS0	_	_	
16h				Re	served				
17h	D15	D14	D13	D12	D11	D10	D9	D8	CMPR4
/ . /	D7	D6	D5	D4	D3	D2	D1	D0	
18h	D15	D14	D13	D12	D11	D10	D9	D8	CMPR5
. 011	D7	D6	D5	D4	D3	D2	D1	D0]
19h	D15	D14	D13	D12	D11	D10	D9	D8	CMPR6
וופו	D7	D6	D5	D4	D3	D2	D1	D0	CIVIFICO
1Ah o				Pe	served				



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

BIT 7	ADDD	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8	1
CAPRES	ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
CAPEDGE CAPSEDGE CAPSEDGE CAPSEING					CAPTURE UNIT	REGISTERS-E	EVB]
CAPEDGE	075006	CAPRES	CAPO	QEPN	CAP6EN	_	CAP6TSEL	CAP45SEL	CAP6TOADC	CARCONR
CAP6FIFO CAP6FIFO CAP6FIFO CAP6FIFO CAP6FIFO	07520N	CAP4	EDGE	CAP5	EDGE	CAP6	SEDGE		_	CAPCONB
CAPFIFOB	07521h				Re	served				
15	07522h	-	_	CAP	SFIFO	CAP	5FIFO	CAF	P4FIFO	CAREIEOR
D7	0732211	_	_	_	_	_	_	_	_	CAFTILOB
D7	07523h	D15	D14	D13	D12	D11	D10	D9	D8	CAPAFIEO
D7	0732311	D7	D6	D5	D4	D3	D2	D1	D0	CAF4III O
D7	07524h	D15	D14	D13	D12	D11	D10	D9	D8	CAPSEIEO
D7 D6 D5 D4 D3 D2 D1 D0 CAPEFIFO	0732411	D7	D6	D5	D4	D3	D2	D1	D0	J CAI SI II O
D7 D6 D5 D4 D3 D2 D1 D0	07525h	D15	D14	D13	D12	D11	D10	D9	D8	CARREIEO
D15	0732311	D7	D6	D5	D4	D3	D2	D1	D0	CAFOIIIO
D7 D6 D5 D4 D3 D2 D1 D0 CAP4FBOT	07526h				Re	served				_
D7	07527h	D15	D14	D13	D12	D11	D10	D9	D8	CAPAEROT
D7 D6 D5 D4 D3 D2 D1 D0 CAPSFBOT	0732711	D7	D6	D5	D4	D3	D2	D1	D0	CAI 4I BOT
D7 D6 D5 D4 D3 D2 D1 D0	07528h	D15	D14	D13	D12	D11	D10	D9	D8	CAPSEROT
D7 D6 D5 D4 D3 D2 D1 D0 CAP6FBOT	0732011	D7	D6	D5	D4	D3	D2	D1	D0	CAI SI BOT
D7 D6 D5 D4 D3 D2 D1 D0	07529h	D15	D14	D13	D12	D11	D10	D9	D8	CAPSEBOT
Table Tabl	0732311	D7	D6	D5	D4	D3	D2	D1	D0	CAI OI BOT
					5					
T3PINT					Re	servea				
T3OFINT				EVENT MANA	GER (EVB) INT	ERRUPT CONT	ROL REGISTER:	S		1
Tapint								ı	T3CINT	1
T3PINT	075001	_	_	_	_	_	ENA			EV (DINADA
ENA	0/52Cn		_	_	_					EARIMKA
0752Dh		ENA				ENA	ENA	ENA	ENA	
Composition		_		<u> </u>	<u> </u>	<u> </u>				
O752Eh	0752Dh	_	_	_	_					EVBIMRB
0752Eh — — — — CAP6INT ENA CAP4INT ENA EVBIMRC 0752Fh — — — — — T30FINT FLAG T3CINT FLAG FLAG FLAG EVBIFRA 0752Fh T3PINT FLAG — — — CMP6INT FLAG CMP4INT PDPINTB FLAG EVBIFRA 07530h — — — — — — — 07530h — — — — — — — 07531h — — — — — — — — 07532h to Reserved Reserved EVBIFRC EVBIFRC										-
Composition	0752Fh	_		-	-	<u> </u>				EVBIMBC:
T3PINT	0702211	_	_	_	_	_				LVBIIIII
T3PINT FLAG — — — CMP6INT FLAG CMP5INT FLAG PDPINTB FLAG EVBIFRA — <td></td> <td></td> <td></td> <td></td> <td></td> <td></td> <td>T30FINT</td> <td>T3UFINT</td> <td>T3CINT</td> <td>1</td>							T30FINT	T3UFINT	T3CINT	1
13PINT	0752Eb	_	_	_	_	_	FLAG	FLAG	FLAG	EV/DIED A
FLAG	0/52FII		_							EVBIFKA
07530h									FLAG	1
FLAG FLAG FLAG			<u> </u>	<u> </u>	<u> </u>		1	ļ 1		
- - - - - - - - -	07530h	_	_	_	_					EVBIFRB
07531h										-
07532h to Reserved FLAG FLAG	07531h	_	_	_	_	_				EVBIERC
to Reserved	0.00111	_	_	_	_	_				2.75.11.0
to Reserved	07532h									1
U/53Fn	to				Re	served				
	0753Fh									J



Table 18. 'LF240x/'LC240x DSP Peripheral Register Description (Continued)

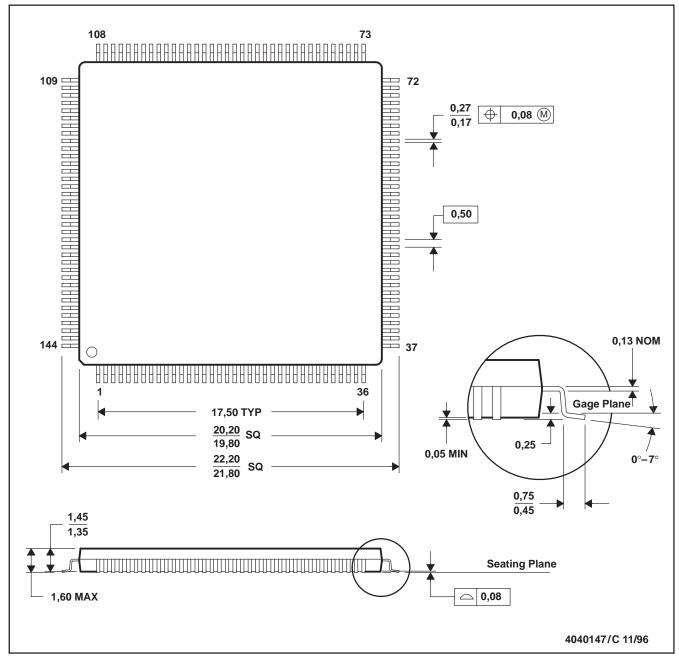
ADDR	BIT 15	BIT 14	BIT 13	BIT 12	BIT 11	BIT 10	BIT 9	BIT 8]
ADDR	BIT 7	BIT 6	BIT 5	BIT 4	BIT 3	BIT 2	BIT 1	BIT 0	REG
			PROGR <i>A</i>	M MEMORY SP	ACE – FLASH F	REGISTERS]
0xx00h	_	_	_	_	_	_	_	_	PMPC
UXXUUII	_	_	_	_	PWR DWN	KEY1	KEY0	EXEC	FIVIEC
0xx01h	_	_	_	_	_	_	WSVER EN	PRECND Mode1	CTRL†
OXXOTI	PRECND Mode0	ENG/R Mode2	ENG/R Mode1	ENG/R Mode0	FCM3	FCM2	FCM1	FCM0	CIRLI
0xx02h									WADDR
0xx03h									WDATA
00.415	_	_	_	_	_	_	_	_	1
0xx04h	_	_	_	_	_	_	_		TCR
0xx05h	_	_	_	_	_	_	_	_	ENAB
UXXUSII	_	_	_	_	_	_	_	_	LINAD
	_	_	_	_	_	_	_	_	
0xx06h	_	_	_	_	SECT 4 ENABLE	SECT 3 ENABLE	SECT 2 ENABLE	SECT 1 ENABLE	SECT
				I/O MEMO	ORY SPACE				
0FF0Fh	_	_	_	_	_	_	_	_	FCMR
OFFOFII	-	_	_	_	_	_	_		PCIVIK
			WAIT-S	TATE GENERAT	OR CONTROL	REGISTER			_
0FFFFh	_	_	_	_	_	BVIS.1	BVIS.0	ISWS.2	WSGR
OI I I I II	ISWS.1	ISWS.0	DSWS.2	DSWS.1	DSWS.0	PSWS.2	PSWS.1	PSWS.0	Wook

[†] Register shown with bits set in **register mode**.

MECHANICAL DATA

PGE (S-PQFP-G144)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026

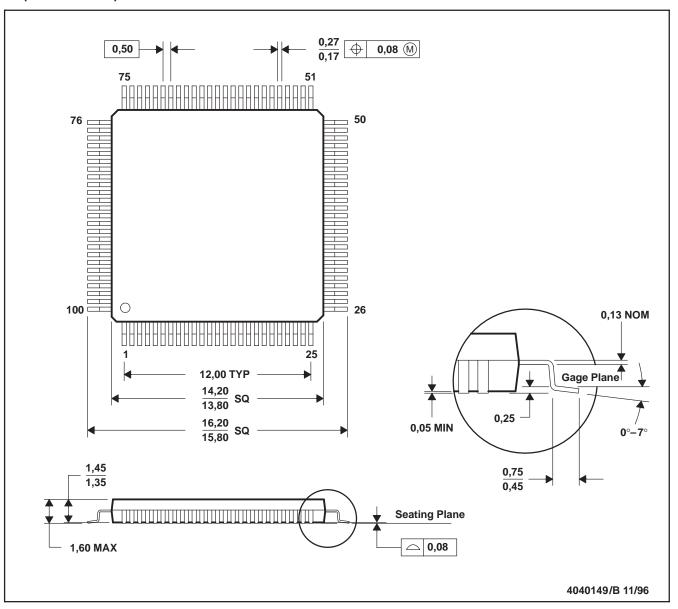
Typical Thermal Resistance Characteristics

.,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,							
PARAMETER	DESCRIPTION	°C/W					
$\Theta_{\sf JA}$	Junction-to-ambient	32					
ΘJC	Junction-to-case	8					



MECHANICAL DATA

PZ (S-PQFP-G100)



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-026

Typical Thermal Resistance Characteristics

PARAMETER	DESCRIPTION	°C/W
ΘЈА	Junction-to-ambient	42
ΘJC	Junction-to-case	8



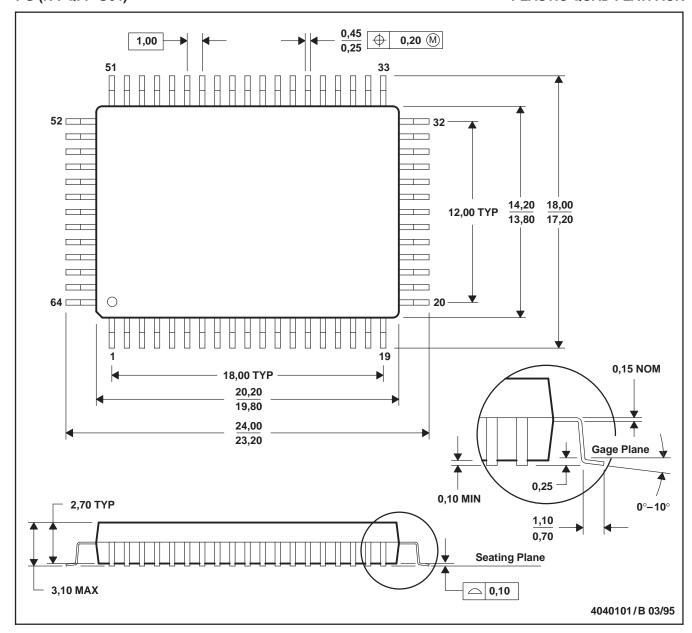
ADVANCE INFORMATION

PLASTIC QUAD FLATPACK

MECHANICAL DATA

PG (R-PQFP-G64)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Contact field sales office to determine if a tighter coplanarity requirement is available for this package.

Typical Thermal Resistance Characteristics

PARAMETER	DESCRIPTION	°C/W
$\Theta_{\sf JA}$	Junction-to-ambient	35
ΘJC	Junction-to-case	11



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